

Fully depleted Charge-Coupled Devices (CCDs) for scientific applications including single-electron detection

Steve Holland

Lawrence Berkeley National Laboratory

September 28th, 2022

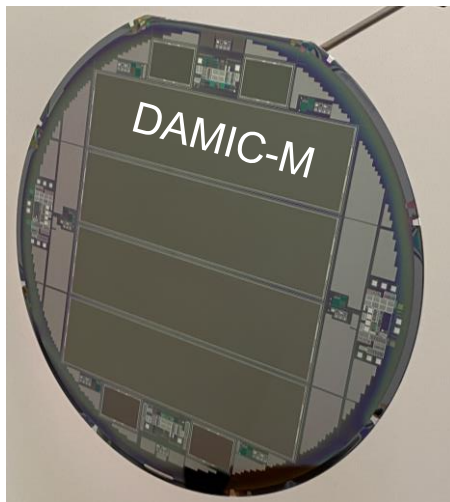
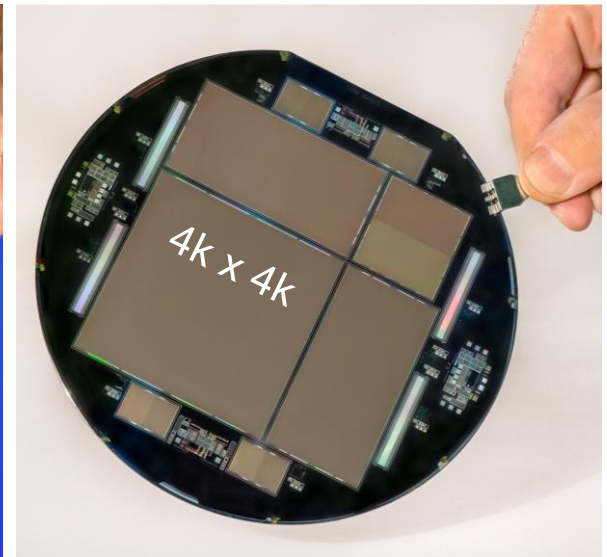
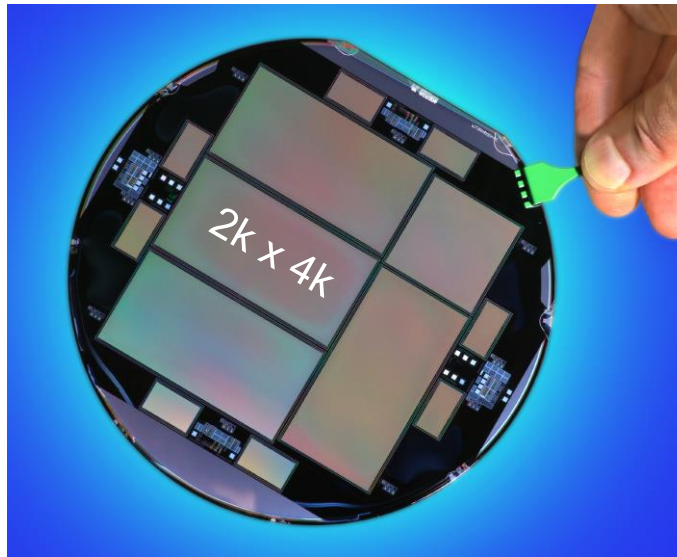


- Lawrence Berkeley National Laboratory
 - U.S. Department of Energy National Laboratory
 - Office of Science
- LBNL CCD development
 - Support DOE High-Energy Physics projects, e.g. detectors for Dark Energy and Dark Matter, Quantum Information Science (QIS)
 - Collaborators include Teledyne DALSA Semiconductor (150-mm CCD fabrication), DOE Labs FermiLab / PNNL, Lincoln Laboratory
 - New: 200 mm CCD fabrication
 - Microchip Technology and Lincoln Laboratory

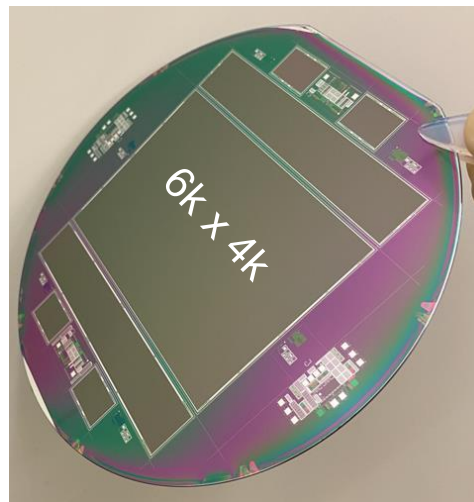
Fully depleted CCDs: 150-mm wafers

U.S. DOE Dark Energy →

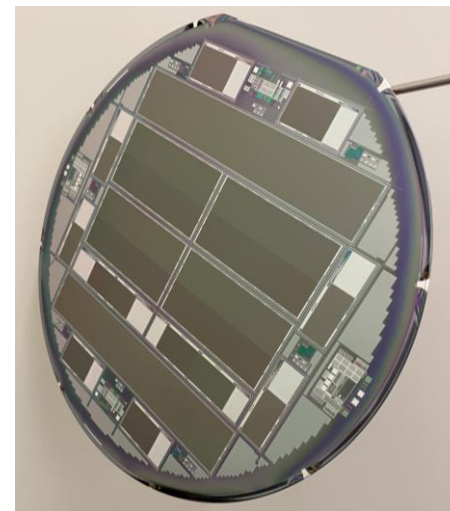
- Astronomy and QIS: Back illuminated / 250 μm thick
- Dark Matter: 650 μm thick
- Radiation detection: 580 μm thick and back illuminated



Dark Matter



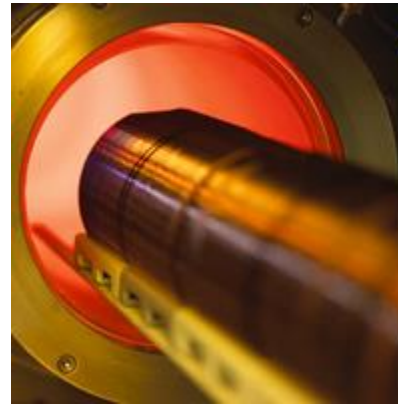
Radiation detection
Dark Matter



Quantum Information Science

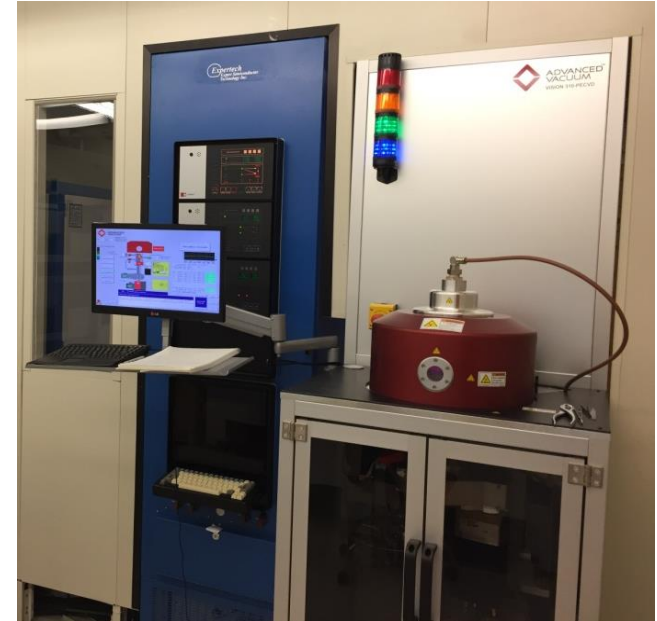
Pixel sizes:
(15 μm)² typical
Also (10.5 μm)²

- Industrial fabrication at Teledyne DALSA
 - Commercial CCD foundry located in Bromont, Quebec, Canada / 150 mm silicon wafers



- Dark Matter detection: Full fabrication at DALSA
- For back illuminated CCDs, the wafers are partially processed at DALSA with the steps needed for back illumination done at the LBNL MicroSystems Lab

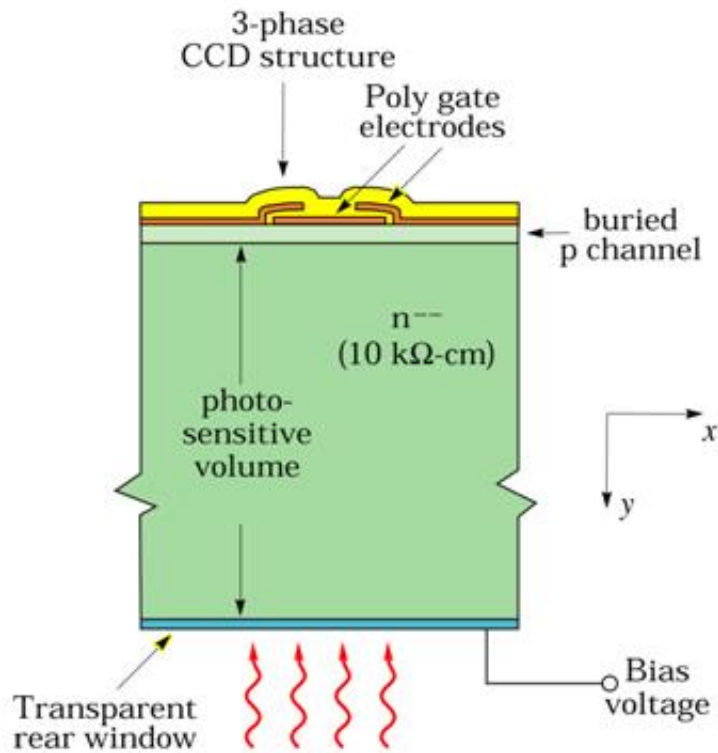
LBL MicroSystems Laboratory



- Class 10 clean room
 - 150 mm wafer processing
 - DECam / DESI CCDs with DALSA
 - QIS / radiation detecting CCDs

“Fully depleted CCDs” 101

CCD fabricated on a high-resistivity silicon substrate that is fully depleted by the application of a substrate bias

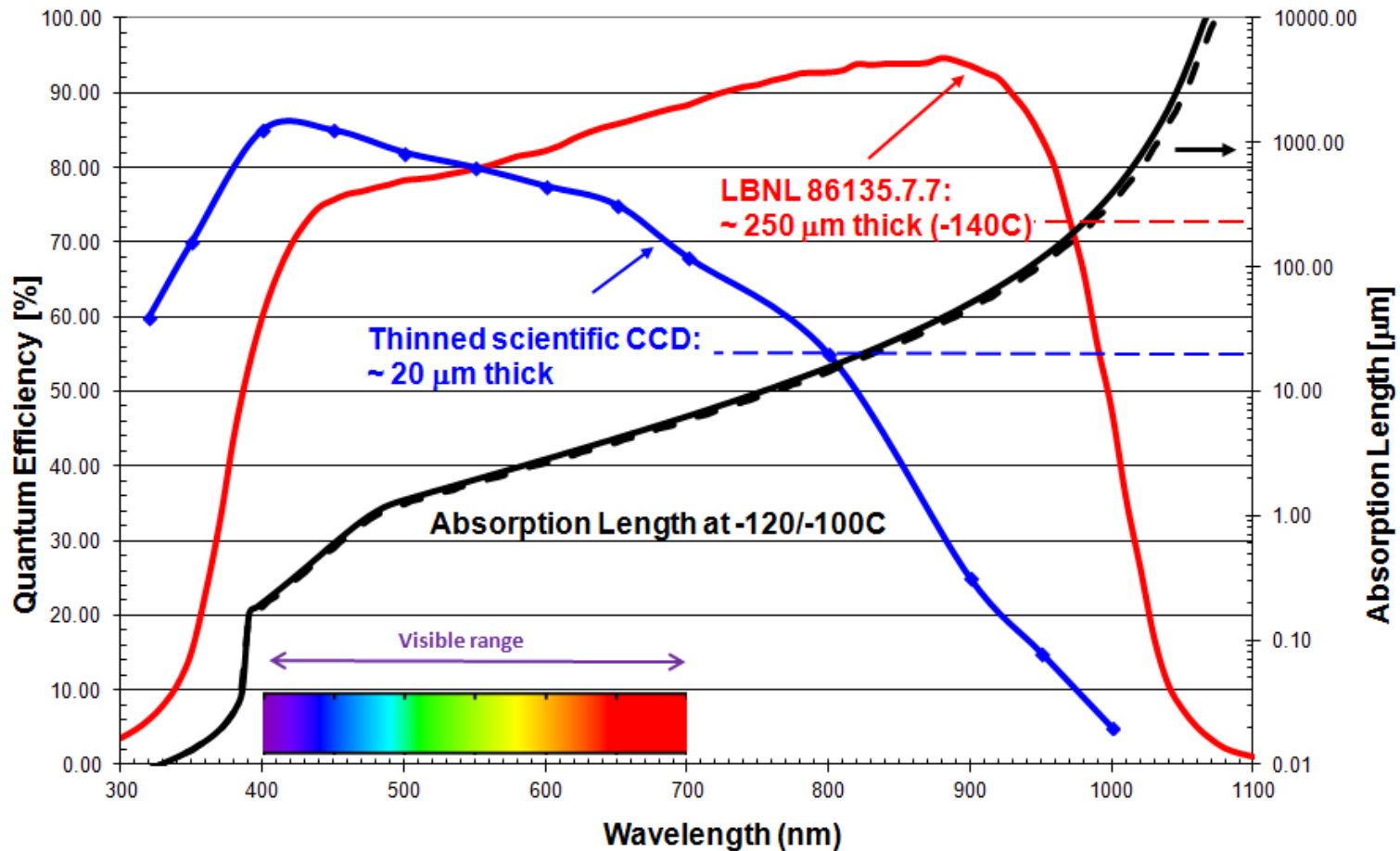


Not to scale

- Merging of CCD / p-i-n detector
- Typical thickness for astronomy is 200 – 250 μm
- Thick device results in high near-infrared response
- Main advantage for astronomy
 - Detect high redshift objects

Quantum efficiency

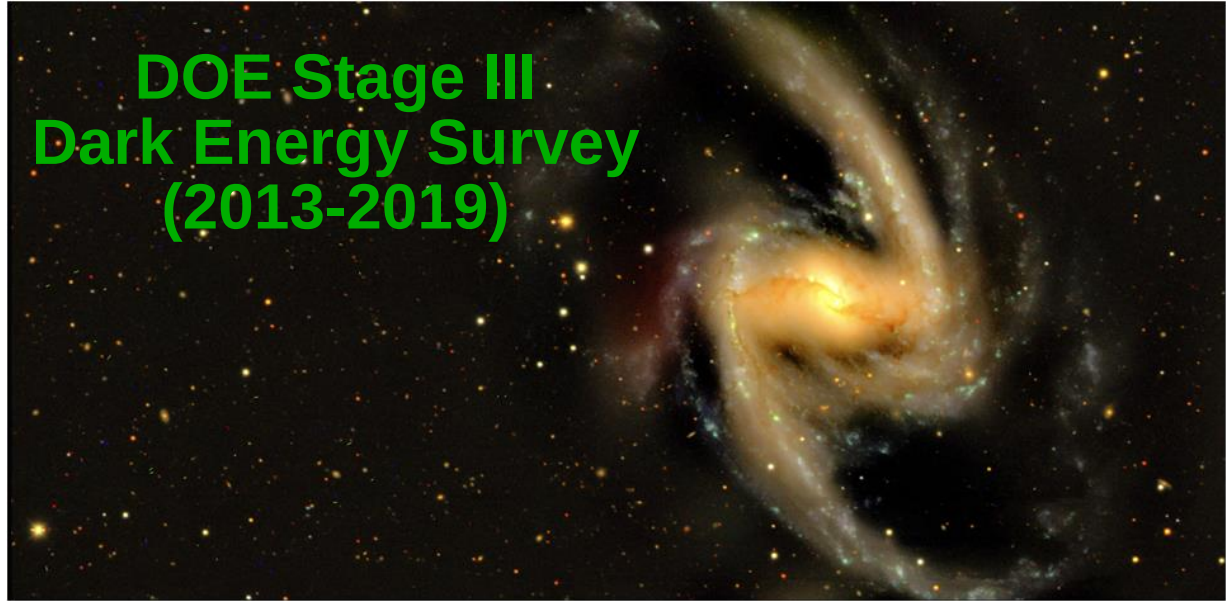
Quantum Efficiency Measurements



Near IR – Silicon becoming transparent, $E_{\text{ph}} < \text{Si bandgap}$ ($\sim 1.1 \text{ eV}$)
 Blue end – Strong absorption in dead layers (n^+ of p-i-n structure)

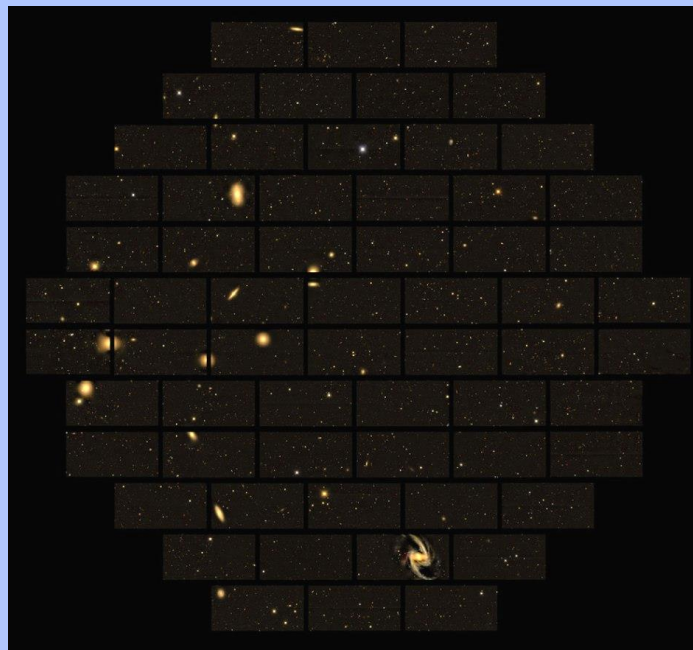
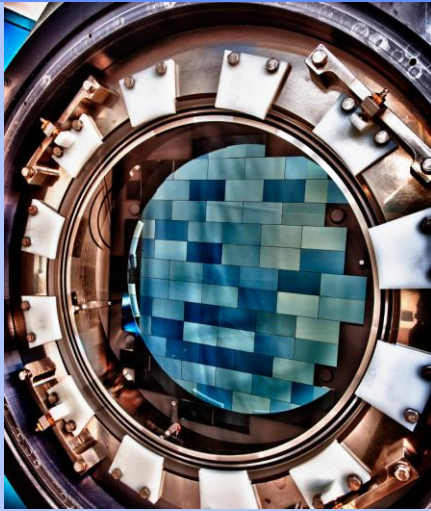


DOE Stage III Dark Energy Survey (2013-2019)

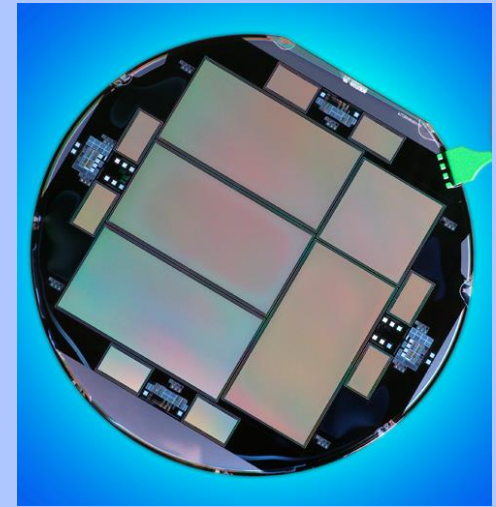


- Dark Energy Camera: CTIO Blanco 4-m telescope
 - FermiLab was the lead institution
 - DALSA/LBNL fully depleted CCDs
 - 1st light in September 2012
 - Over 1.1 million images to date

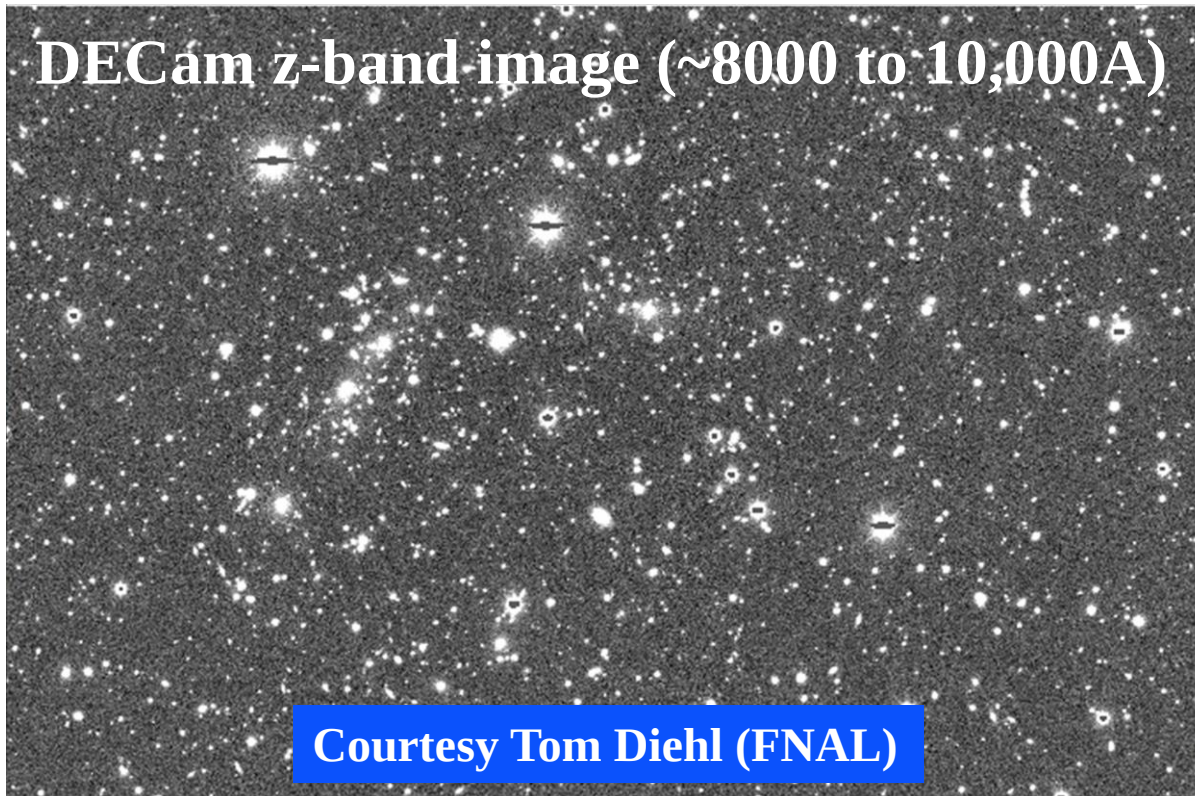
520 Mpixels
250 μm thick, fully depleted CCDs



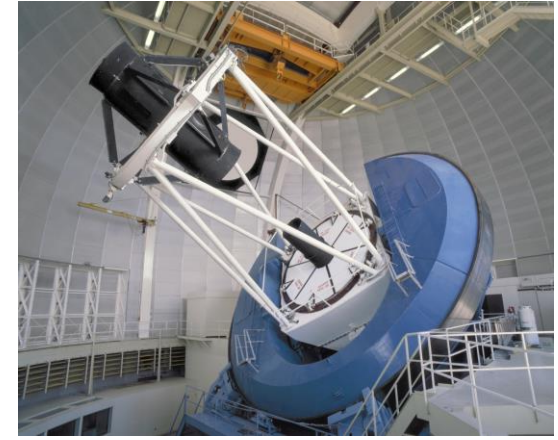
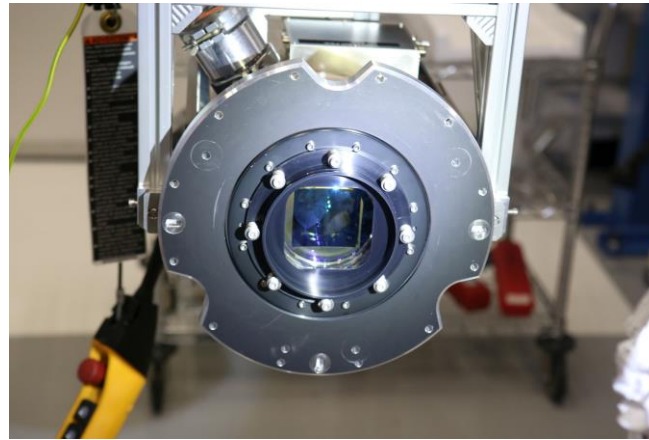
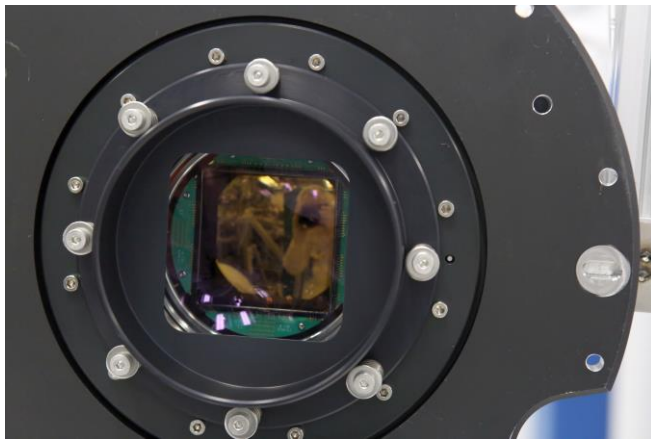
150 mm diameter Si wafer
8 Mpixels (15 μm pixels)



DECam z-band image (~ 8000 to $10,000\text{\AA}$)



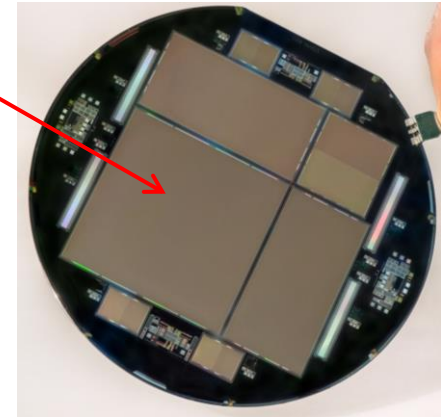
Courtesy Tom Diehl (FNAL)



Blue-sensitive CCDs (10):
 $360 < \lambda \leq 555 \text{ nm}$
 20 μm thick, 4k x 4k
 DALSA / Semiconductor
 Technology Associates, Inc /
 University of Arizona Imaging
 Technology Laboratory

Red-sensitive CCDs (10):
 $555 < \lambda \leq 656 \text{ nm}$
 Near-infrared CCDs (10):
 $656 < \lambda \leq 980 \text{ nm}$
 250 μm thick, 4k x 4k
 DALSA / LBNL

Focal plane:
 5000 robotic fiber positioners
 Mayal 4-m telescope



Dark Energy Spectroscopic Instrument

DOE Stage IV Dark Energy experiment

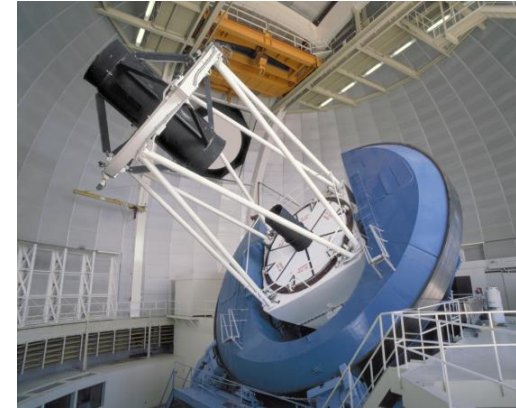
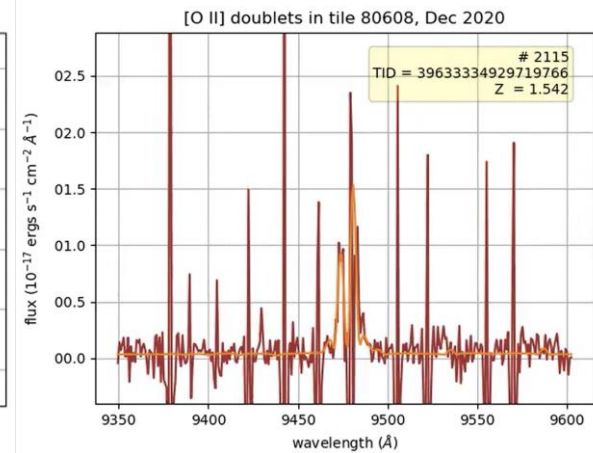
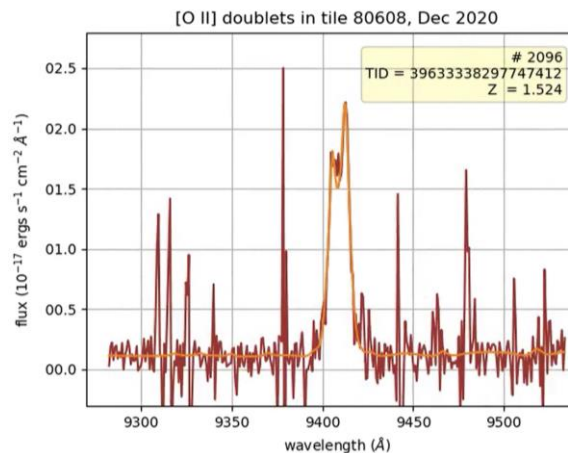
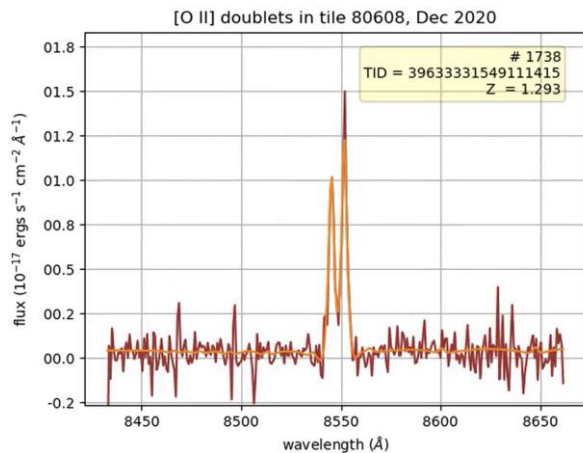
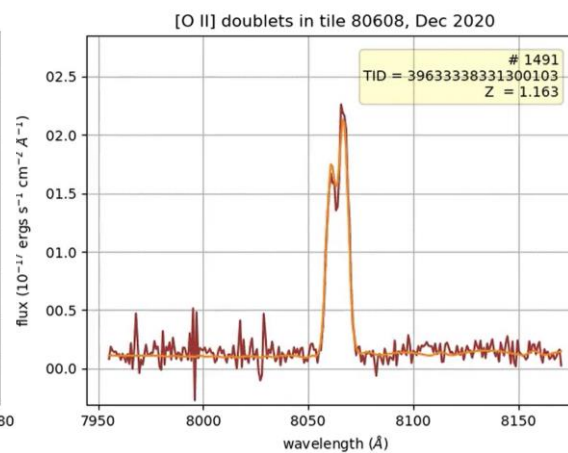
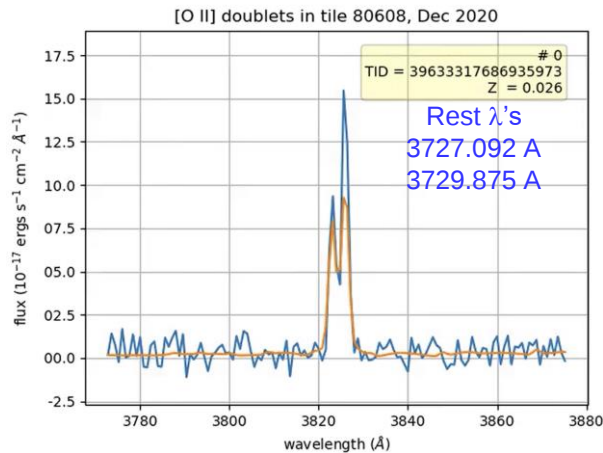
- Measure ~ 30 million redshifts using 4 classes of objects (LRGs, ELGs, QSOs, Lyman- α forest)
- 10 spectrographs each with 3 4k x 4k, 15 μm pixel CCDs
- First light October 22nd, 2019

Dark Energy Spectroscopic Instrument

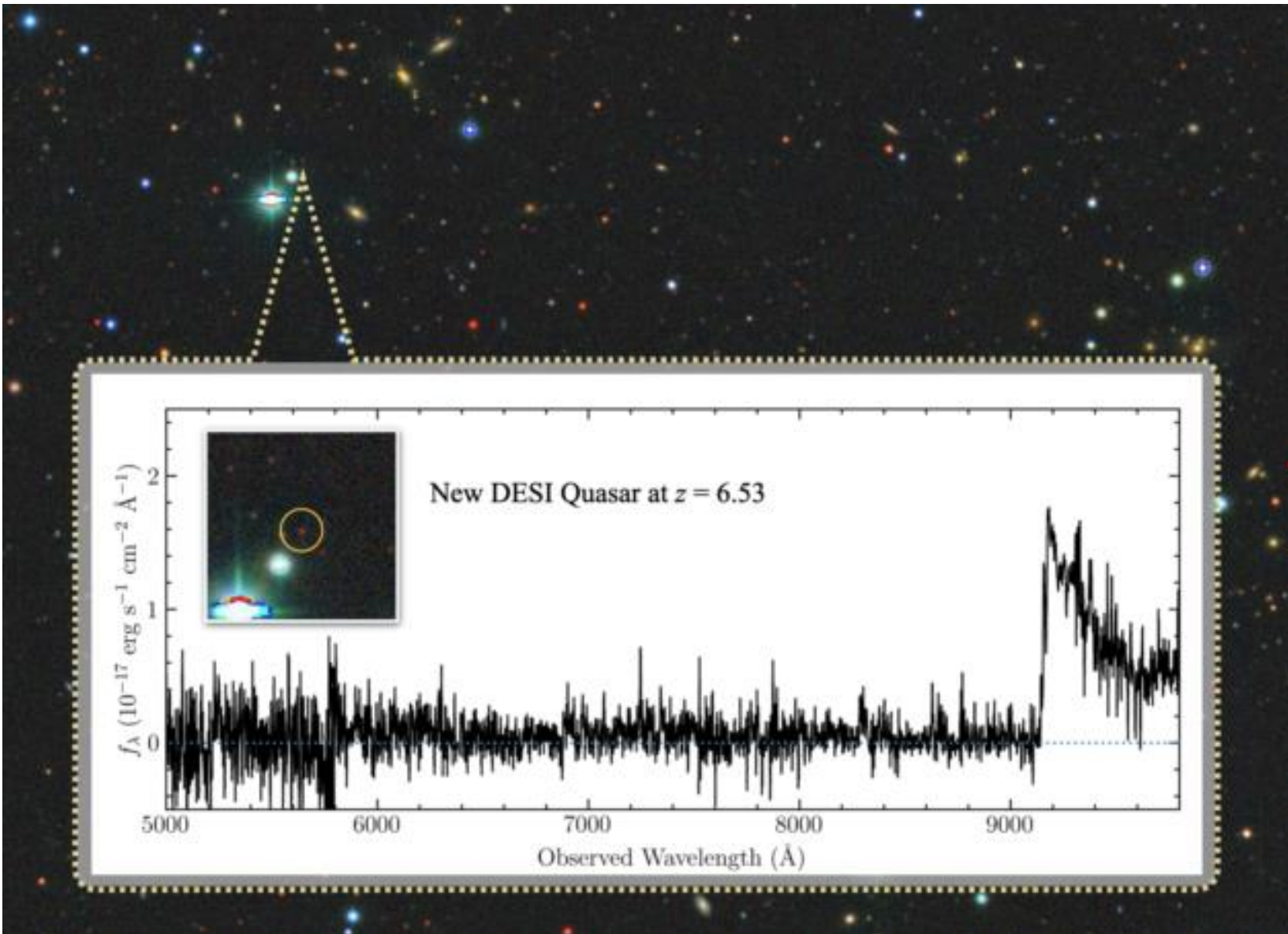
- [O II] doublet: Marker for Emission Line Galaxies
— Results from December 2020

DESI Blue CCD: ~ Rest wavelength

DESI near-IR CCDs (red shift z)

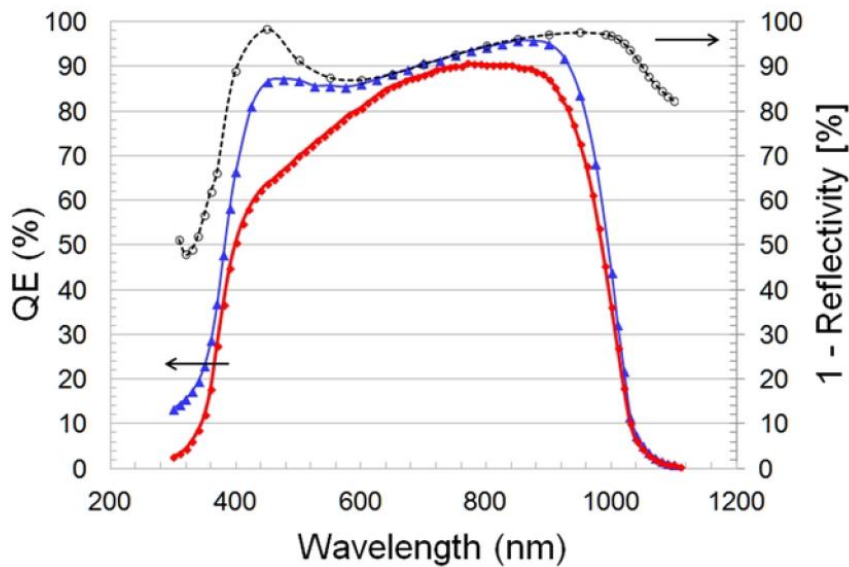


Dark Energy Spectroscopic Instrument



R&D for improved DESI CCDs

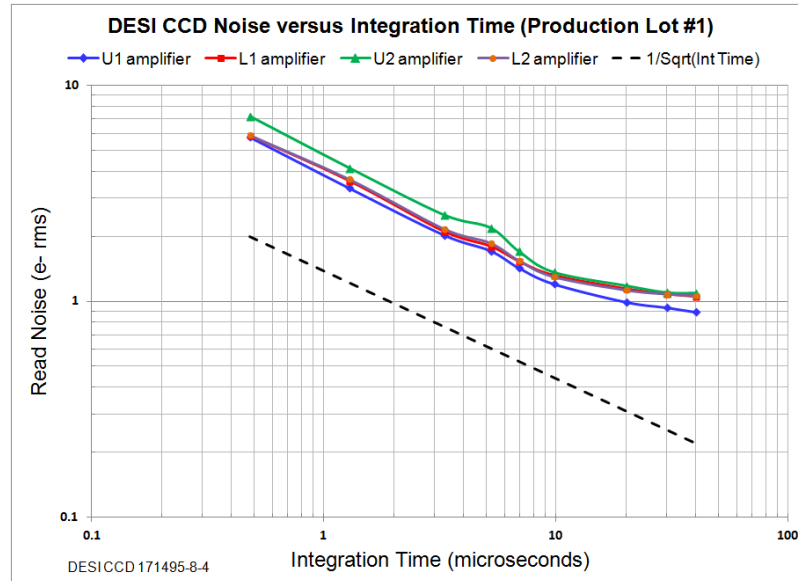
- New anti-reflection coating design (D. Groom)
- Lower readout noise



Improved DESI QE (blue) versus Dark Energy Camera CCDs (red)

[doi:10.1088/1748-0221/12/04/C04018](https://doi.org/10.1088/1748-0221/12/04/C04018)

<http://dx.doi.org/10.1088/1748-0221/10/05/C05026>

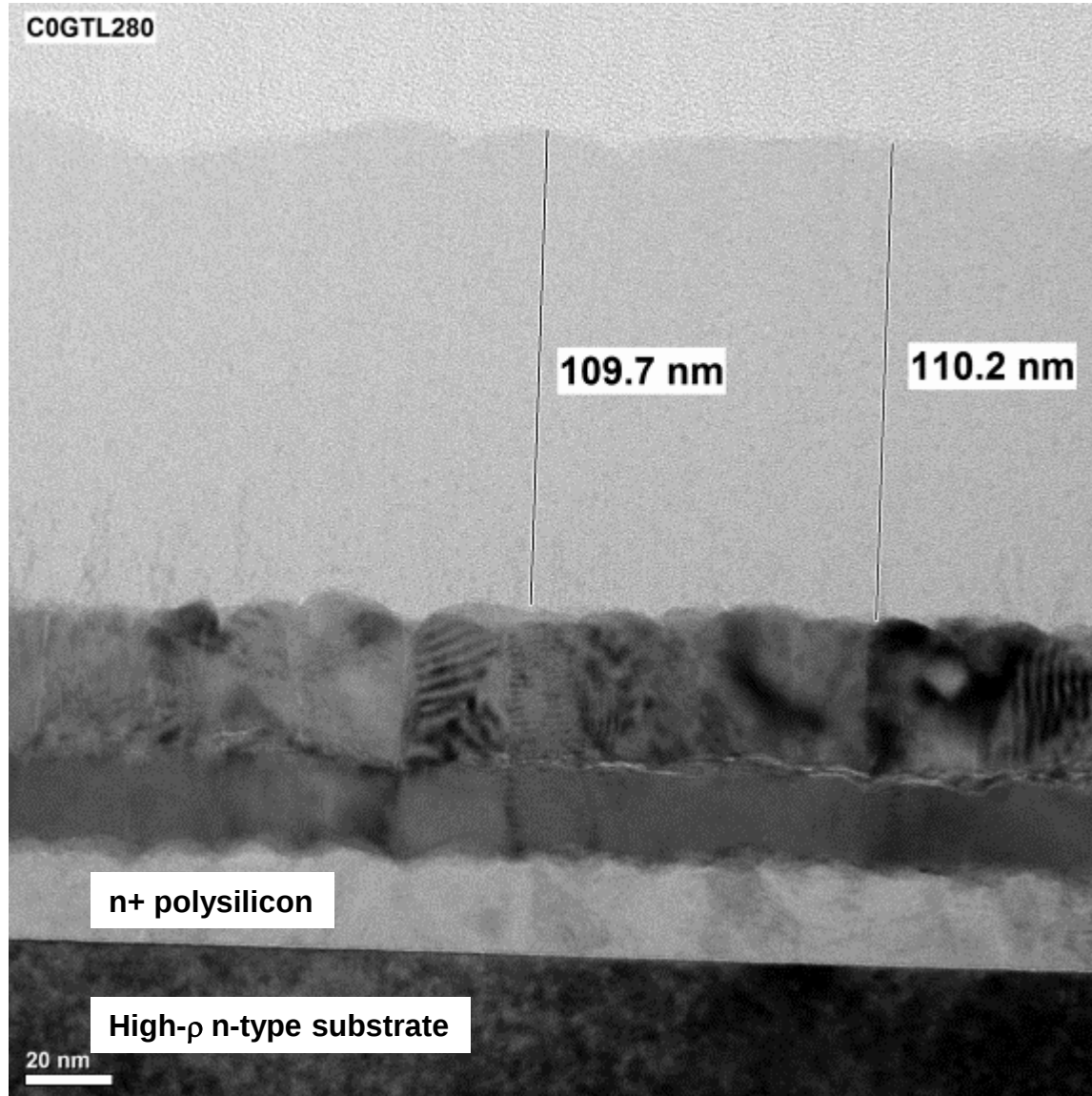


		STA	LBNL	LBNL
	SPEC	BLUE	RED	NIR
0		3.62	2.61	2.49
1		3.82	2.77	2.82
2		3.21	3.02	2.38
3		3.24	2.6	2.91
4		3.37	2.73	2.5
5		3.64	2.95	2.45
6		3.37	2.63	2.32
7		3.03	2.4	2.49
8		3.2	2.52	2.48
9		3.14	2.47	2.44

June 2022
Ave of 4 amps

Backside layers: LBNL CCDs

- TEM cross-sectional image



SiO ₂ / 106 nm
ZrO ₂ / 38 nm
Indium tin oxide / 20 nm
In-situ doped polysilicon / 20 nm / $\sim 1 \times 10^{20} \text{ cm}^{-3} \text{ P}$
Silicon substrate > 10,000 ohm-cm n-type

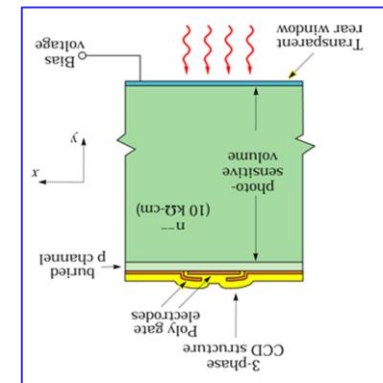
SiO₂

ZrO₂

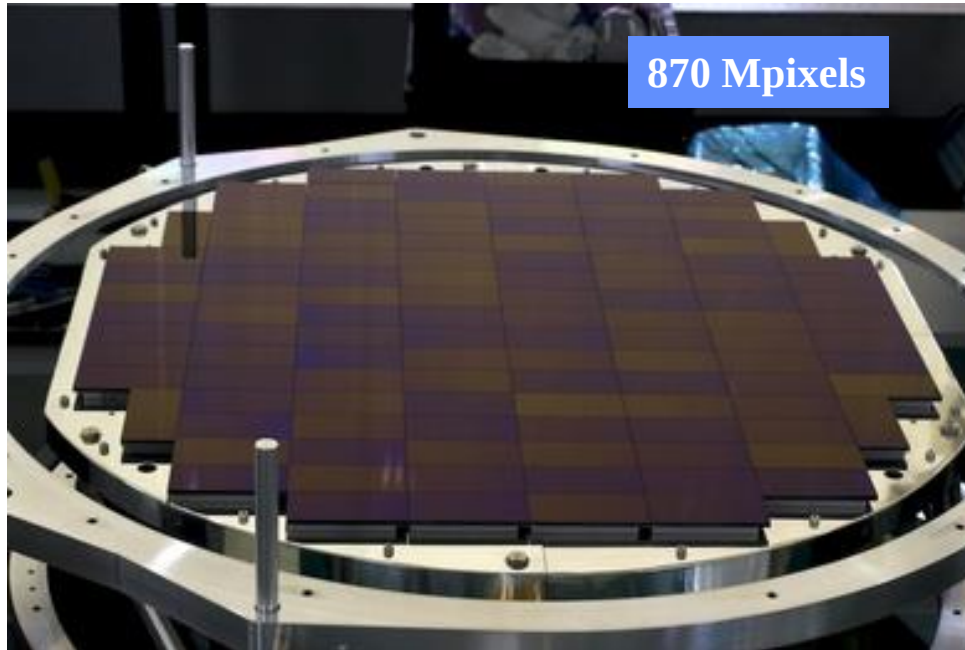
ITO

In-situ doped polysilicon

Silicon substrate



Astronomical cameras with fully depleted CCDs

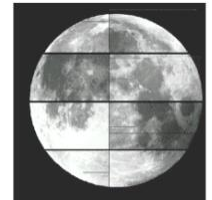
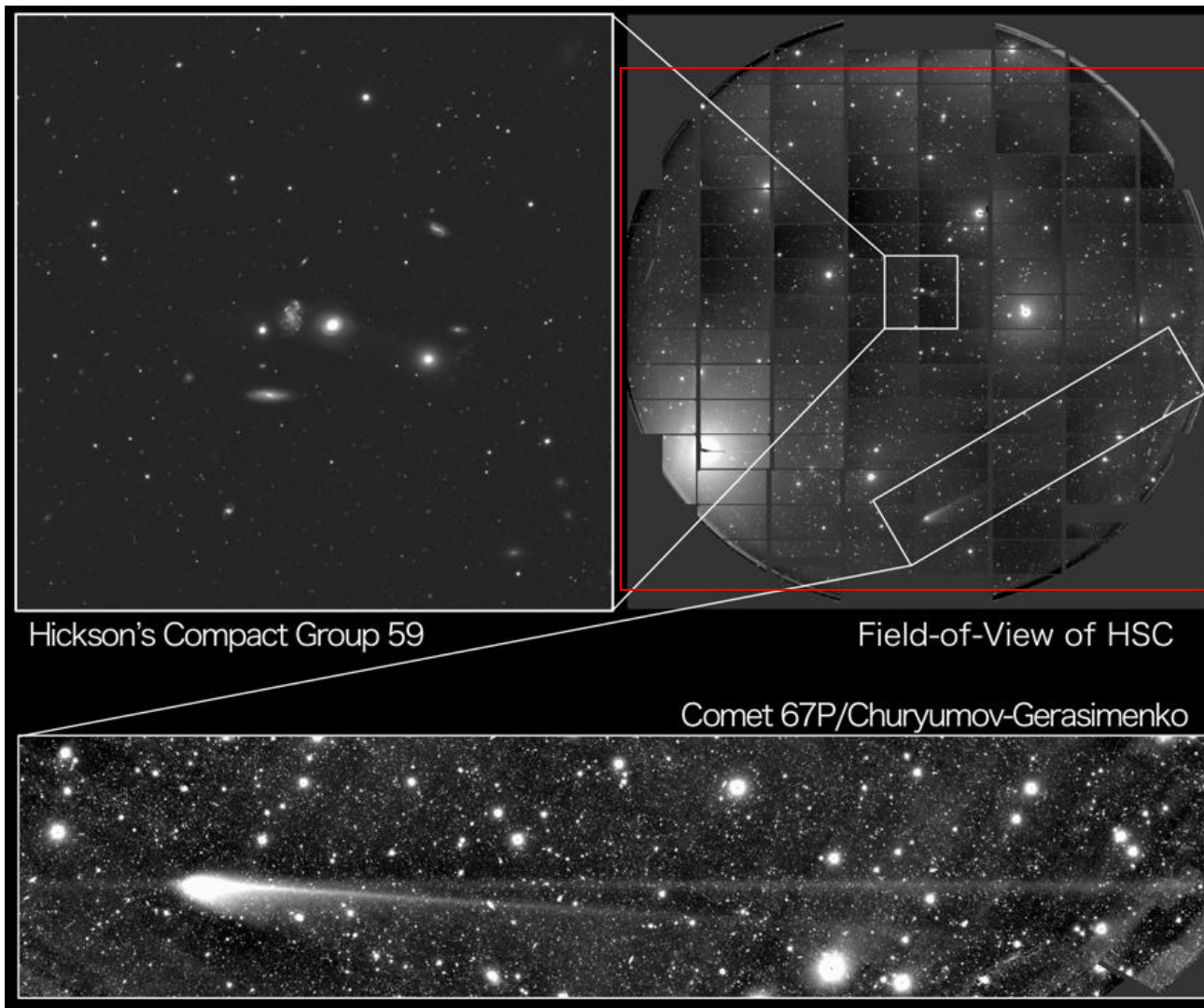


HyperSuprimeCam – 116 2k x 4k, $(15\ \mu\text{m})^2$ -pixel CCDs
200 μm thick fully depleted CCDs from Hamamatsu Corporation
Subaru 8-m Telescope

Satoshi Miyazaki (PI) and Yukiko Kamata (CCD testing)

Also PAN-STARRS (Lincoln Labs) and Vera Rubin Observatory
(e2V and DALSA/STA/University of Arizona CCDs)

Astronomical cameras with fully depleted CCDs



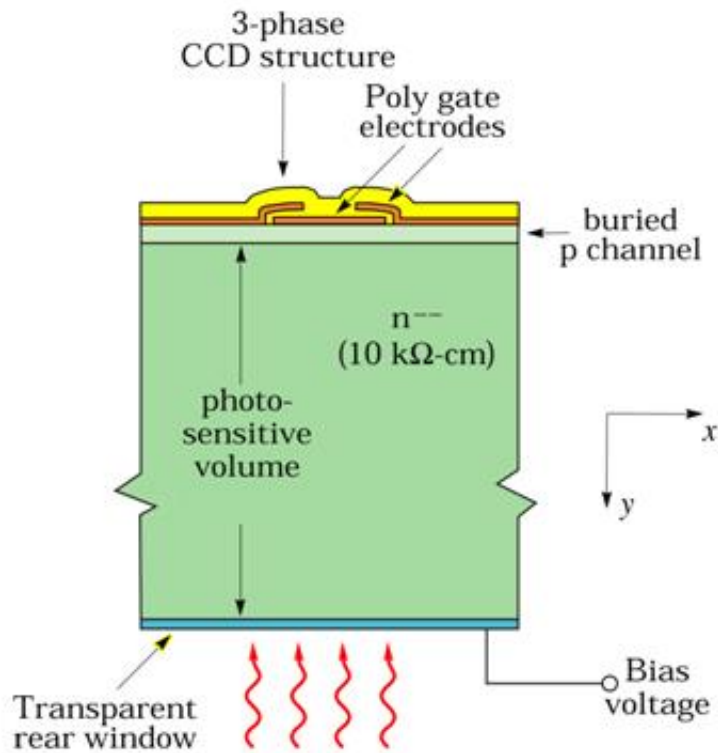
Full moon
for scale

HyperSuprimeCam – 116 2k x 4k, $(15 \mu\text{m})^2$ -pixel CCDs (870 Mpixels)
CCDs from Hamamatsu Corporation / Subaru 8-m Telescope

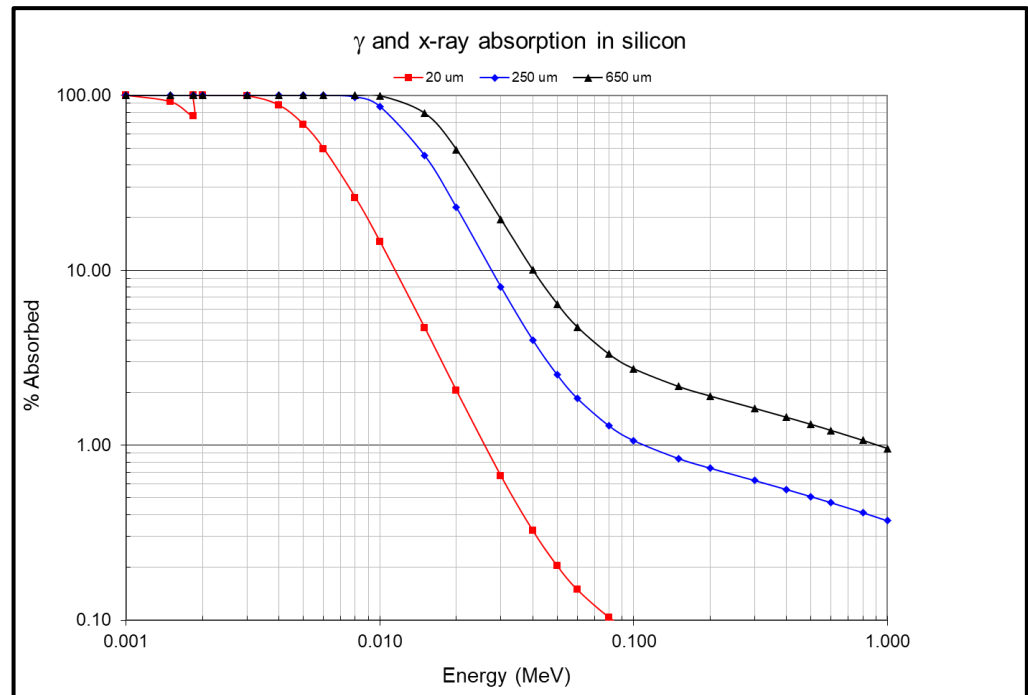
“Fully depleted CCDs” 101

CCD fabricated on a high-resistivity silicon substrate that is fully depleted by the application of a substrate bias

- Thick CCDs for radiation detection
- Charged particles, x and γ rays



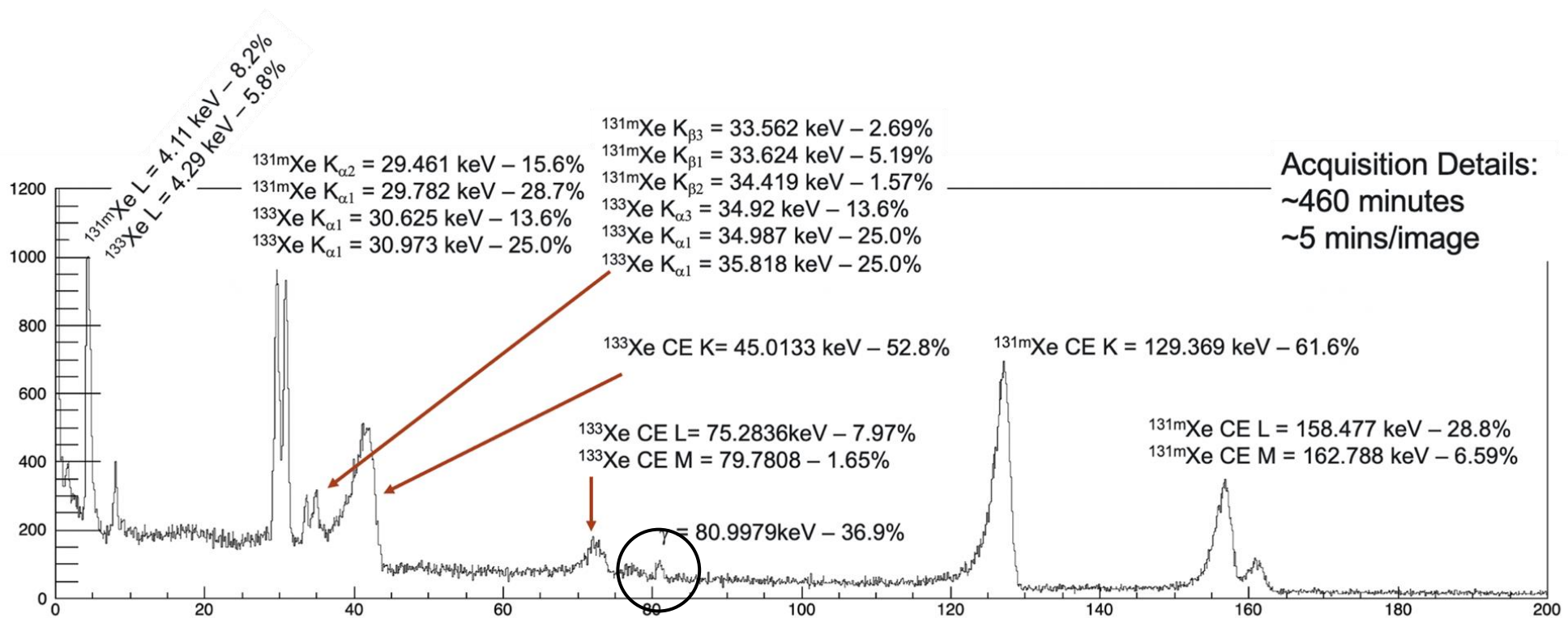
Not to scale



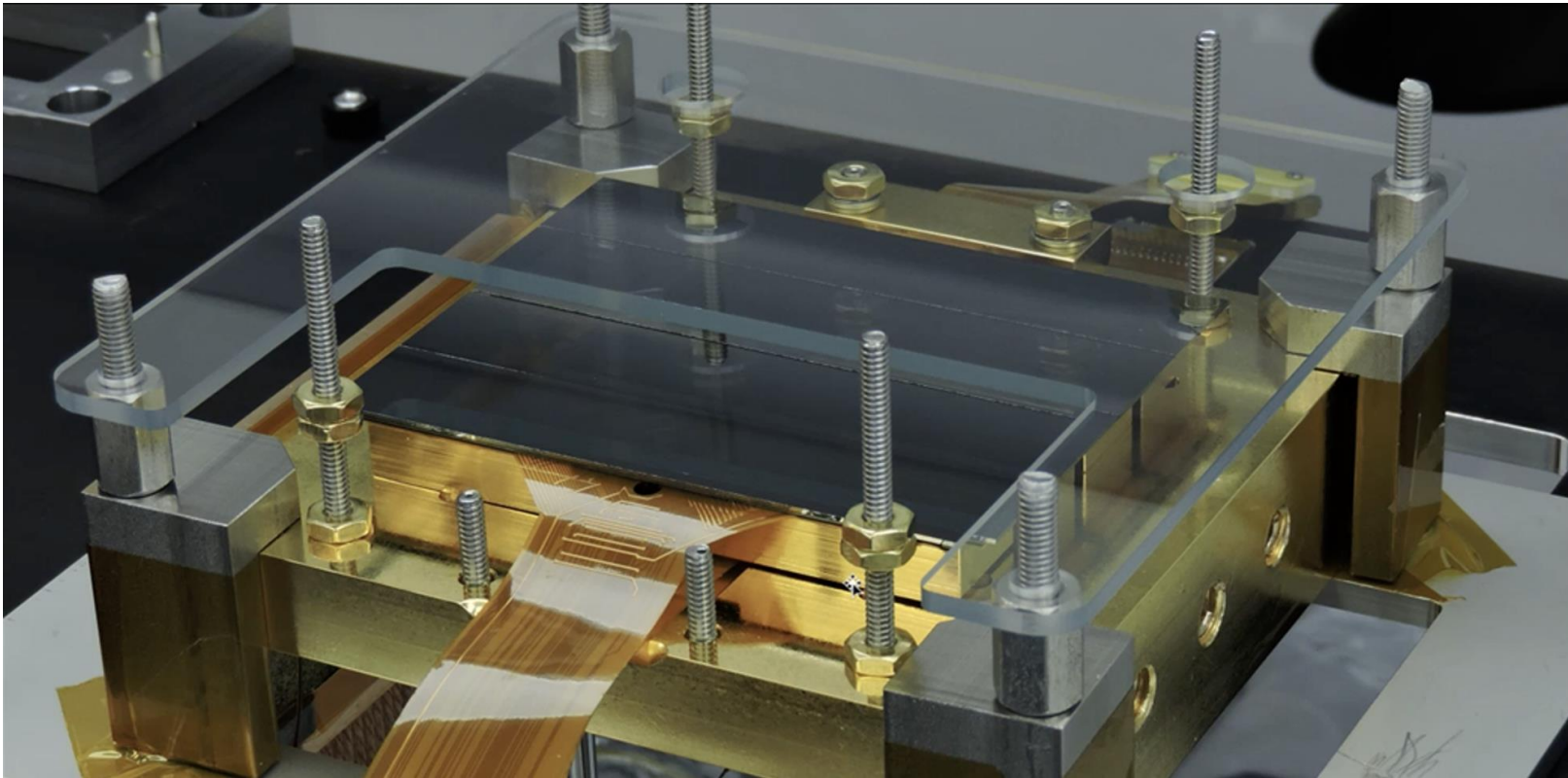
Radiation detection with thick, FD CCDs

CCD-based ionizing radiation detectors with low-energy (<100 keV) gamma-ray sensitivity / 650 um thick and fully depleted

Todd Hossbach: Pacific Northwest National Lab



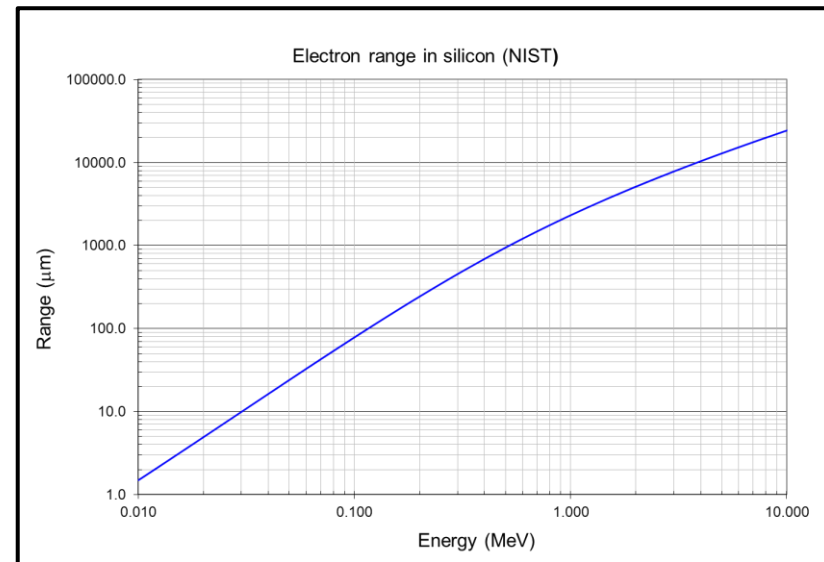
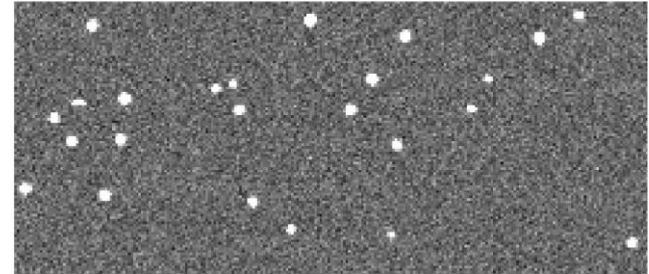
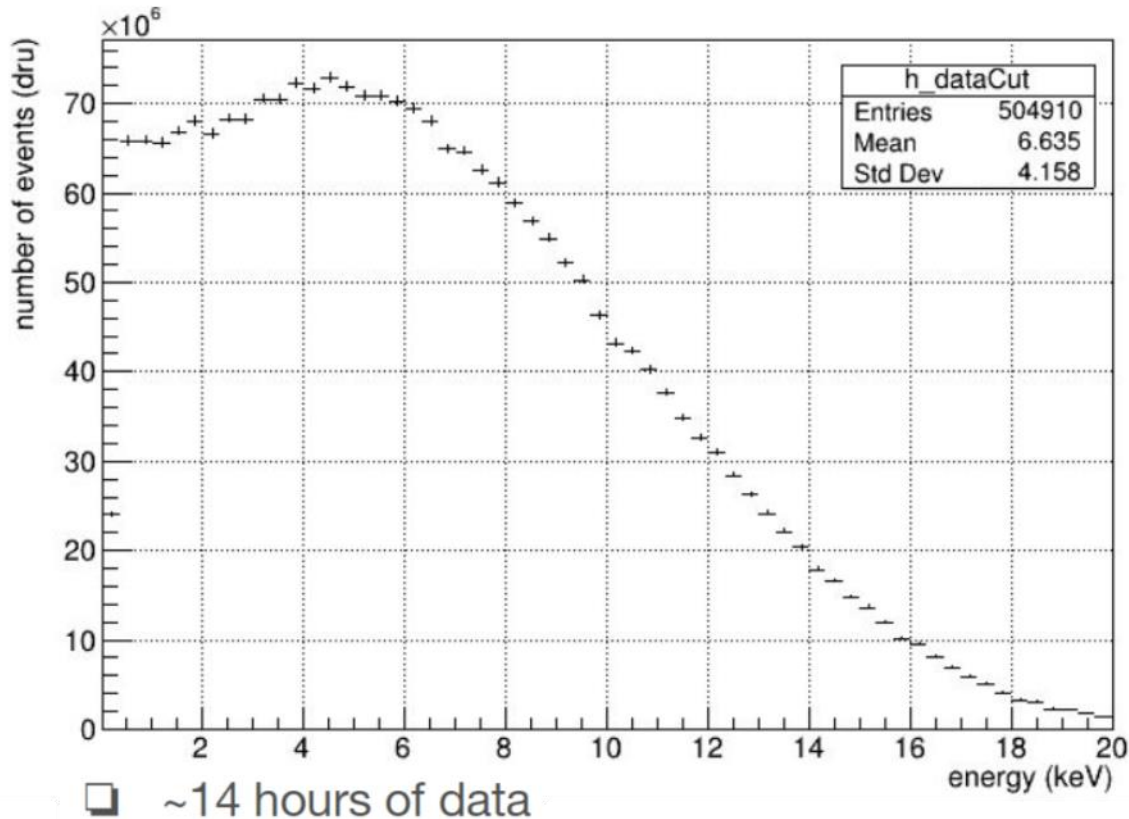
^3H detection with thick, BI, FD CCDs



- GRAIL focal plane for radiation detection
 - 4 1k x 6k, 580-um thick back-illuminated CCDs
 - Mix of finishing at LBNL and Lincoln Laboratory
 - Lincoln Labs molecular-beam epitaxy backside

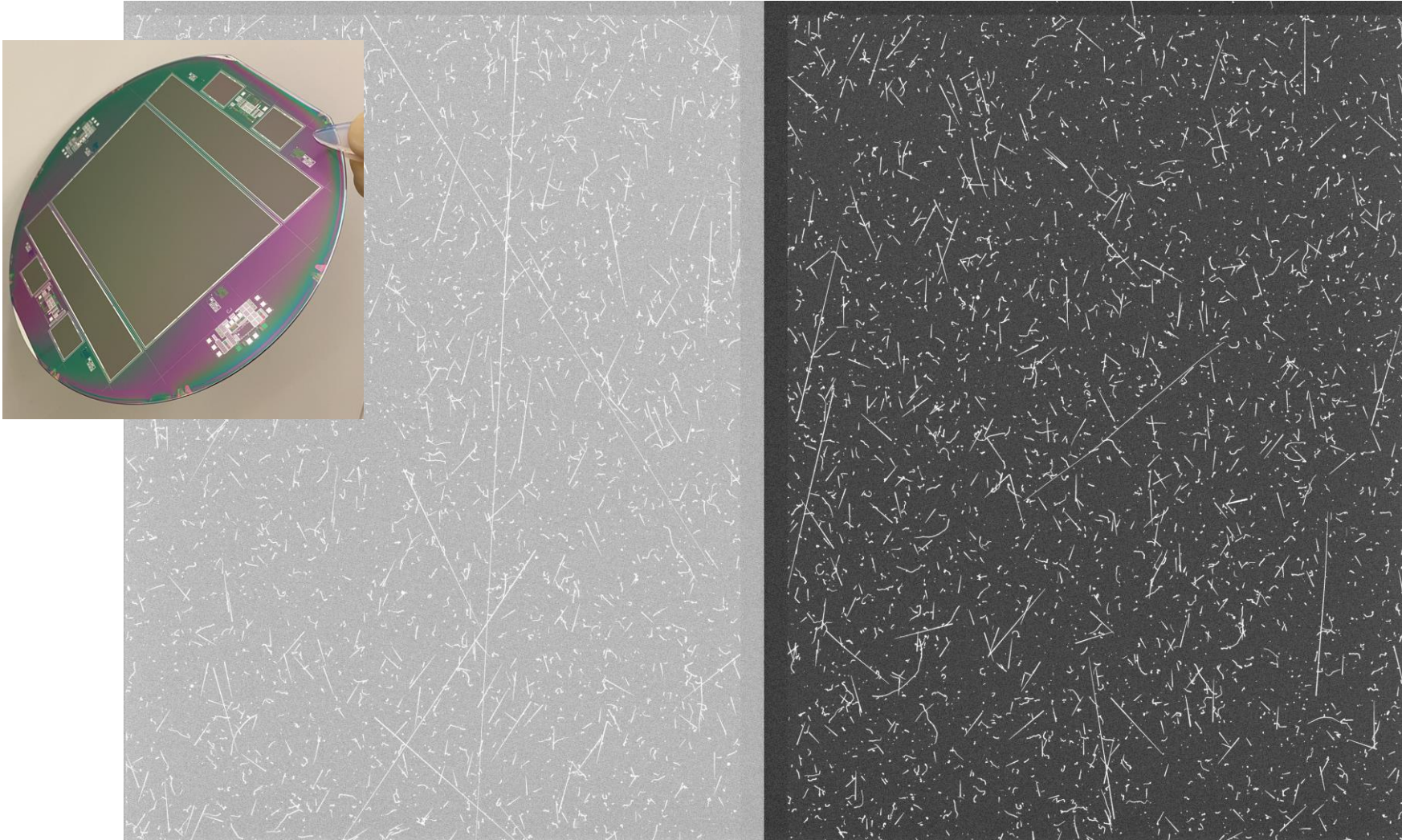
^3H detection with thick, BI, FD CCDs

Measured tritium spectrum using G2-CCD



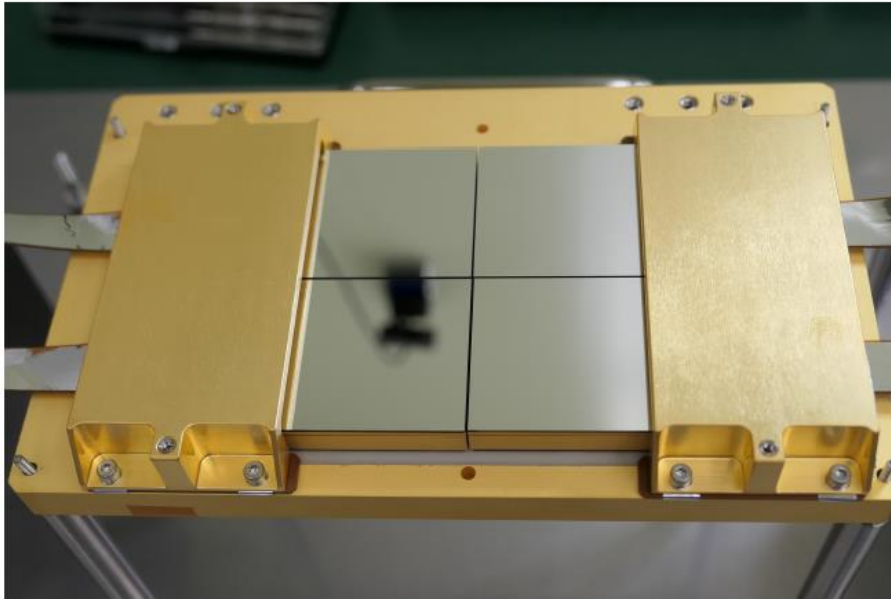
- GRAIL project with PNNL, LBNL, FermiLab, Lincoln Laboratory
 - ~ 2 keV β -electron detection

580 um thick, back-illuminated CCD



LBNL-processed 6k x 4k CCD: Thin n+ backside contact / no AR
1 hour dark / 60V / 120K
University of Chicago

Xtend CCDs on XRISM space mission



<https://doi.org/10.1117/12.2626894>
<https://doi.org/10.1117/12.2560348>
<https://doi.org/10.1016/j.nima.2020.164676>

Table 1. Specifications and nominal operation parameters of the SXI CCD

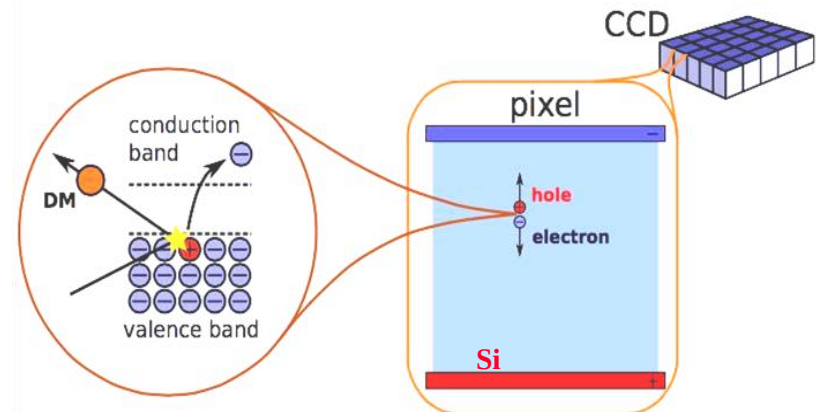
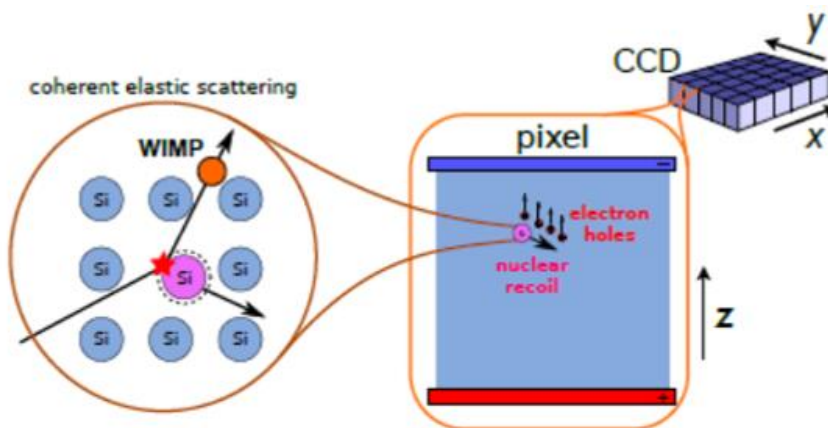
CCD Specification	Architecture	Frame transfer
	Imaging area size	30.720 mm × 30.720 mm
	Pixel format (physical/logical)	1280 × 1280 / 640 × 640
	Pixel size (physical/logical)	24μm × 24μm / 48μm × 48μm
	Depletion layer thickness	200 μm
	Incident surface layer (back side)	100 nm + 100 nm thick Aluminum coat
	Readout nodes (equipped/used)	4 / 2
Operation parameters	Frame cycle	4 seconds
	On-chip binning	2×2
	Charge injection	every 160 physical rows

Xtend soft x-ray imaging telescope (Launch 9/6/2023)
CCDs from Hamamatsu Corporation / Testing at Osaka University

Dark Matter detection with CCDs

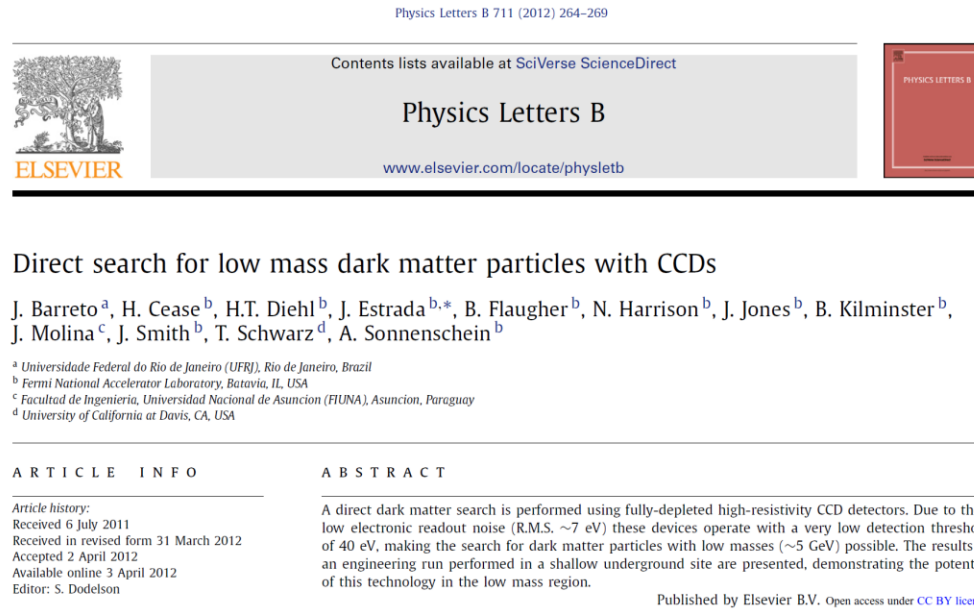
Proposed by Juan Estrada et al of FermiLab (2008)

- <https://doi.org/10.48550/arXiv.1105.5191>
- Low noise / improves low-energy detection threshold
 - Si bandgap ~ 1.1 eV
- Thick CCDs for larger volume
- Expected dark-matter particle interactions
 - Nuclear recoil (silicon nucleus)
 - Scattering off electrons



1st underground engineering run / one 4 Mpixel DECam CCD

- <https://doi.org/10.1016/j.physletb.2012.04.006>



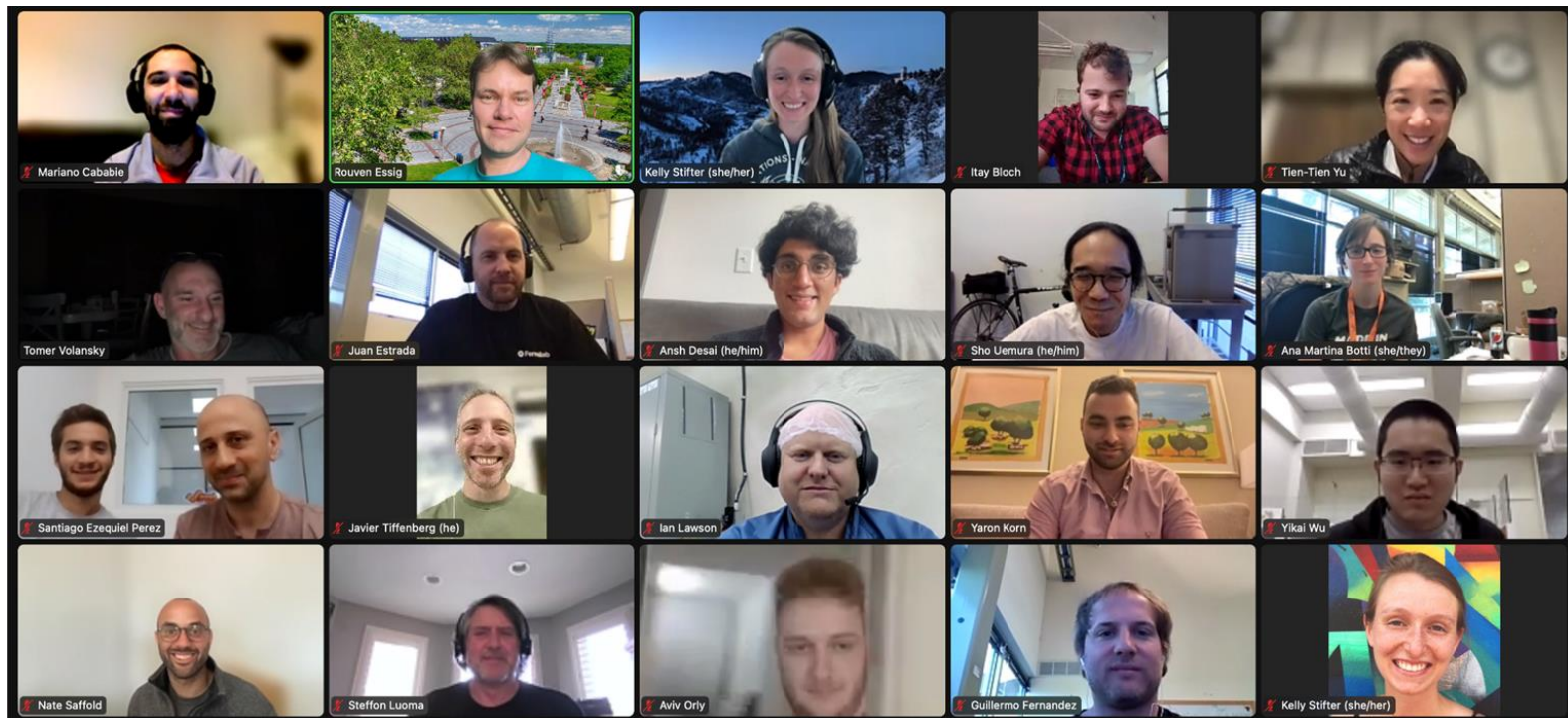
- SENSEI / DAMIC-M / OSCURA are 0.1/1/10 kg scale
 - 2 e- noise (2012) ➡ now deep sub-electron (Skipper CCDs)
 - 250 μm (2012) ➡ now 650-725 μm
 - Dark current orders of magnitude less than astronomy CCDs

Dark Matter detection with CCDs

SENSEI

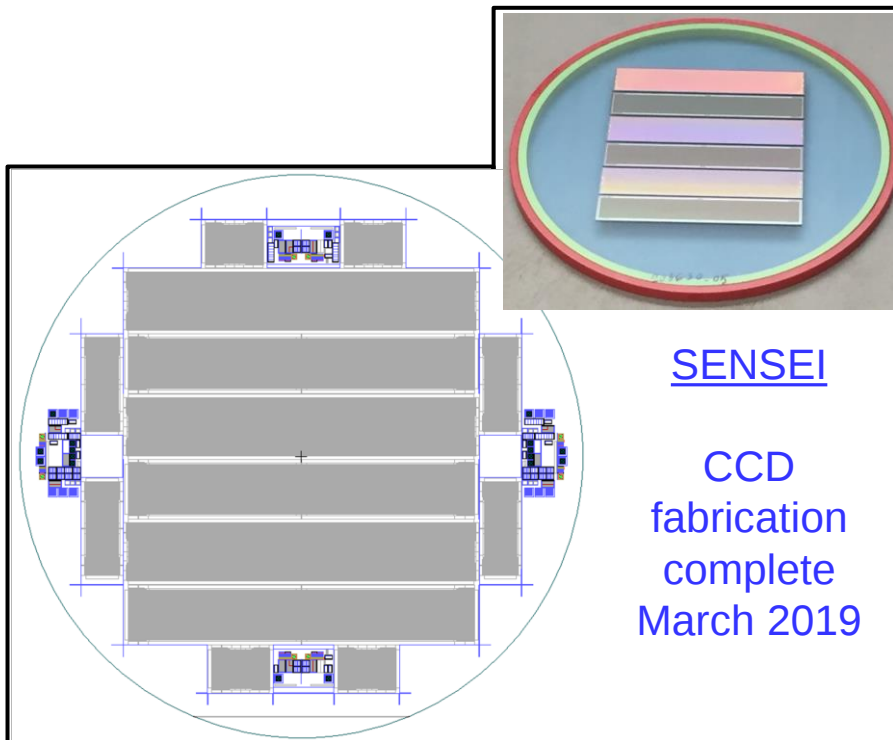
Sub-Electron-Noise Skipper-CCD Experimental Instrument

100 g scale (1 Teledyne DALSA Semiconductor lot of 25 wafers)



SENSEI collaboration at unblinding meeting

LBNL Dark Matter CCD development



650 um thick, fully depleted CCDs
150-mm wafers
Full fabrication at DALSA Semiconductor

6 6k x 1k CCDs installed now (13 g)
2 km underground at SNOLAB
1st science run was 9/2022 – 4/2023
100-g scale experiment

SENSEI@SNOLAB

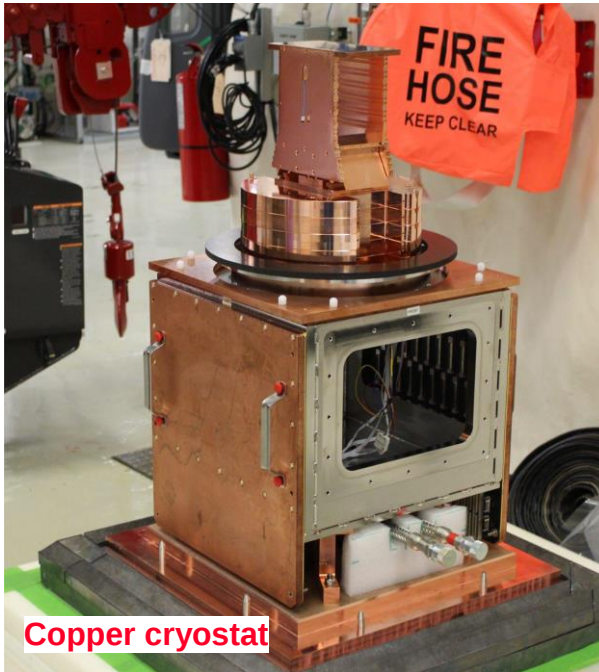


SENSEI publications

- 2017 Skipper CCD
 - [PRL 119.131802](#)
- 2018 Surface run prototype CCD
 - [PRL 121.061803](#)
- 2019 Underground prototype CCD
 - [PRL 122.161801](#)
- 2020 Underground science CCD
 - [PRL 125.171802](#)

LBNL Dark Matter CCD development

SENSEI@SNOLAB



Results presented at
APS April Meeting 2023
2023 Phenomenology Symposium

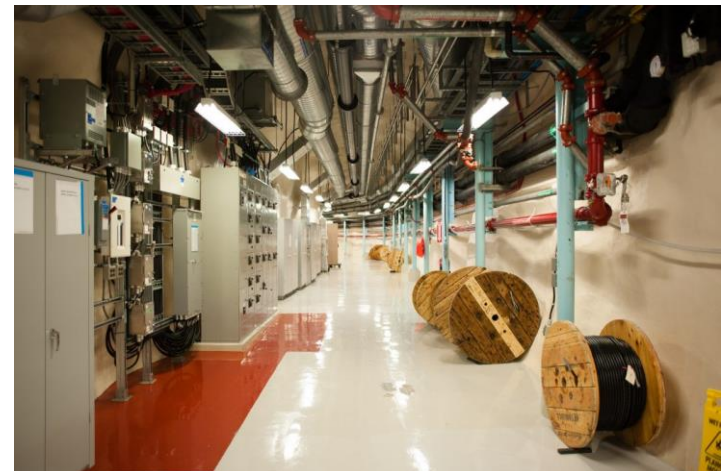
Paper in preparation

Presently installing more CCDs

SNOLAB is Canada's deep underground research laboratory, located in Vale's Creighton mine near Sudbury, Ontario Canada.

It provides an ideal low background environment for the study of extremely rare physical interactions. SNOLAB's science program focuses on astroparticle physics, specifically neutrino and dark matter studies, though its unique location is also well-suited to biology and geology experiments. SNOLAB facilitates world-class research, trains highly qualified personnel, and inspires the next generation of scientists.

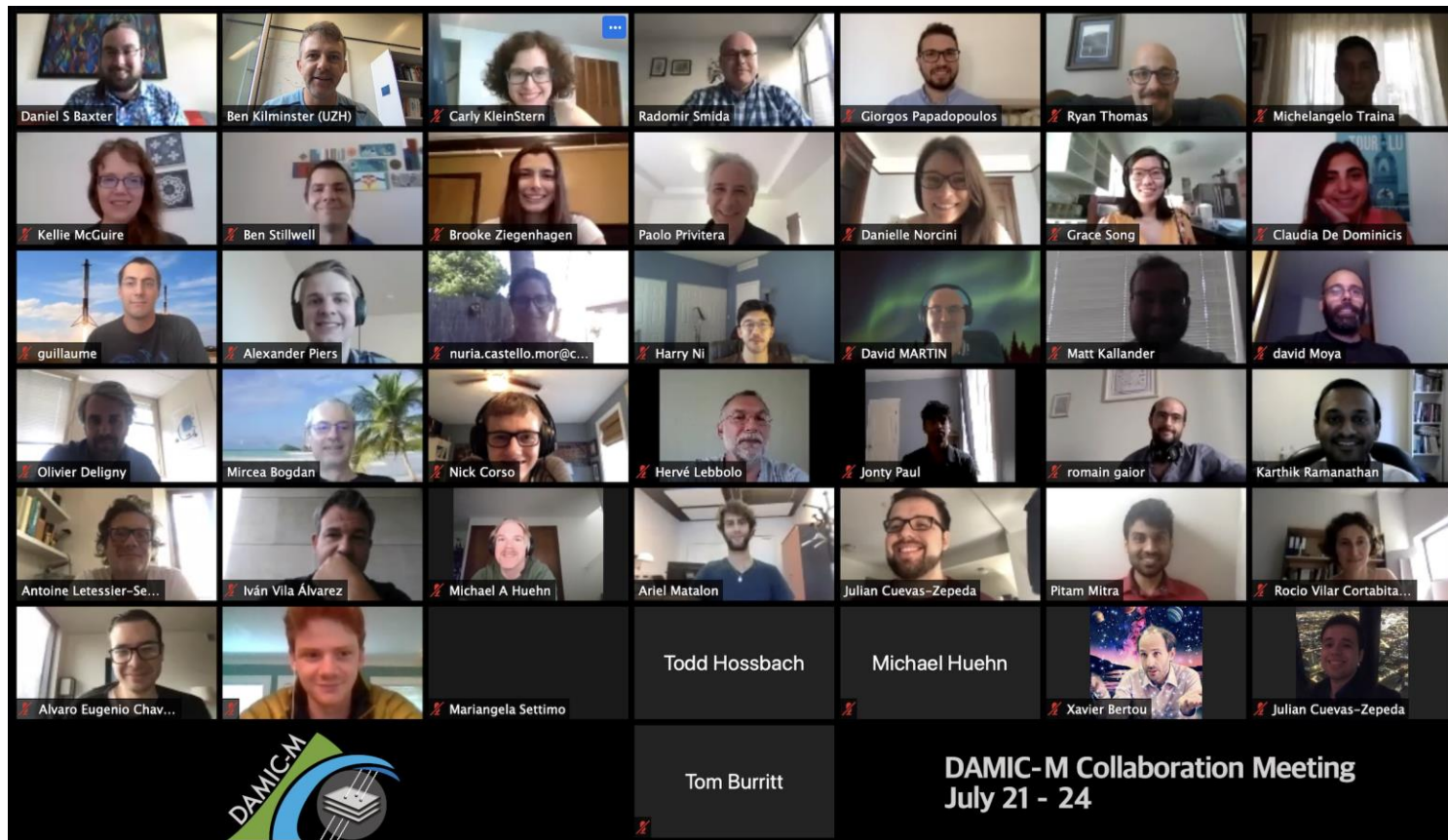
At 2km, SNOLAB is the deepest cleanest lab in the world. It is an expansion of the facilities constructed for the Sudbury Neutrino Observatory (SNO) solar neutrino experiment and has 5,000 m² of clean space underground for experiments and supporting infrastructure. A staff of over 100 support the science, providing business processes, engineering design, construction, installation, technical support, and operations. SNOLAB research scientists provide expert and local support to the experiments and undertake research in their own right as members of experimental collaborations.



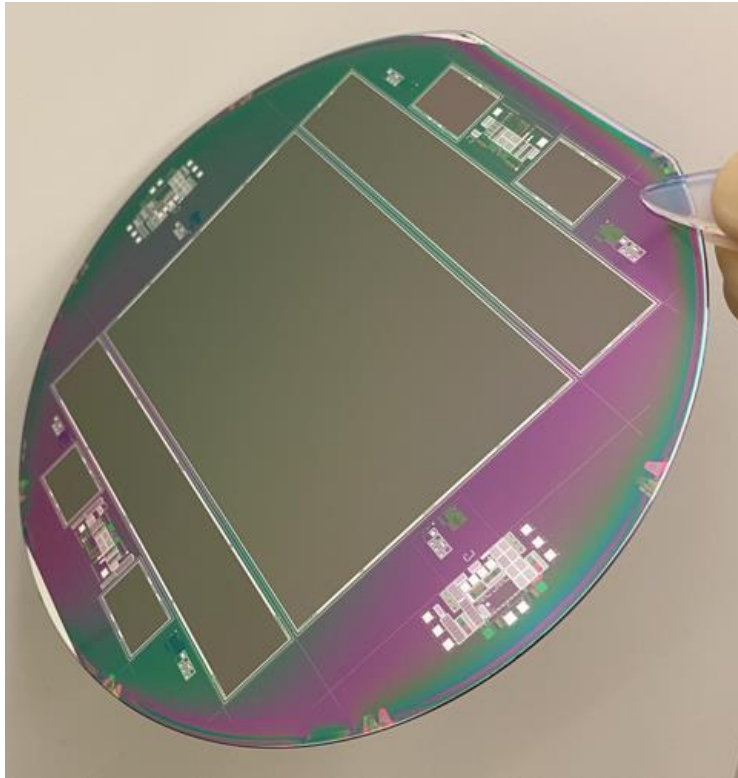
DAMIC-M

Dark Matter in CCDs at Modane

1 kg scale (~10 Teledyne DALSA Semiconductor lots of 25 wafers)

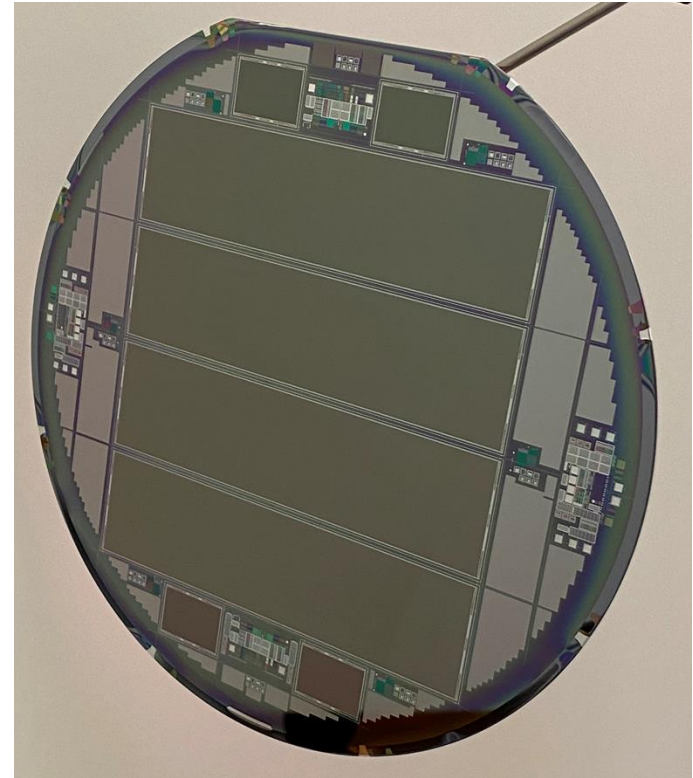


LBNL Dark Matter CCD development



DAMIC-M R&D CCDs
650 um thick, fully depleted CCDs
150-mm wafers

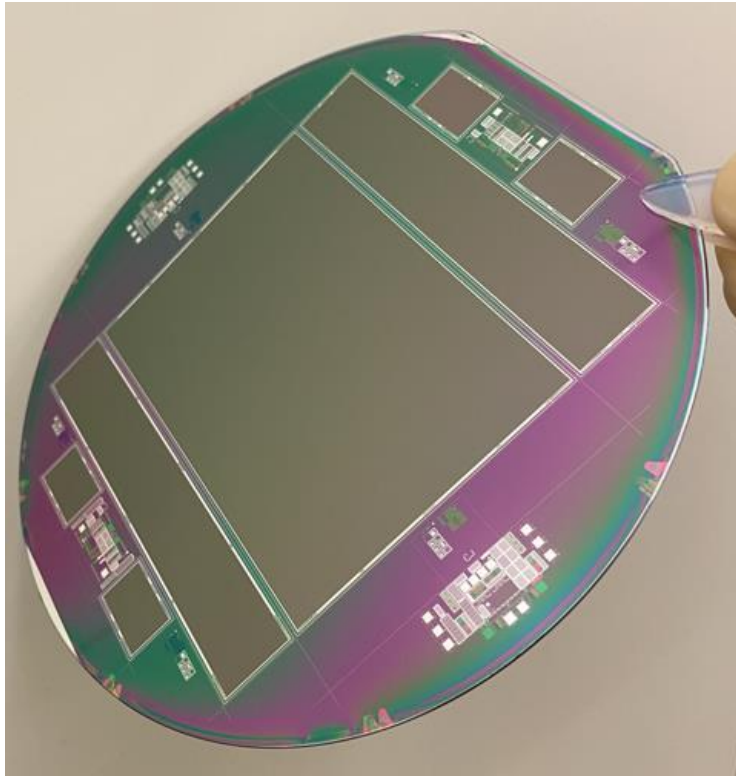
See DAMIC-M web site
<https://damic.uchicago.edu/>



DAMIC-M production CCDs
1 kg scale dark matter
Fabrication started March 2021
9-10 lots for 1 kg

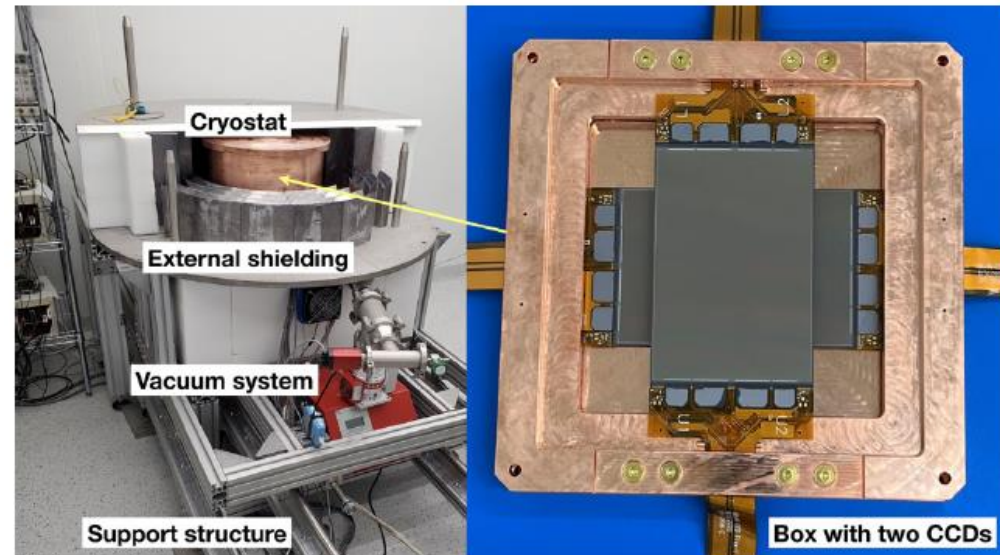
Full fabrication at DALSA
Semiconductor

LBNL Dark Matter CCD development



DAMIC-M R&D CCDs
650 um thick, fully depleted CCDs
150-mm wafers

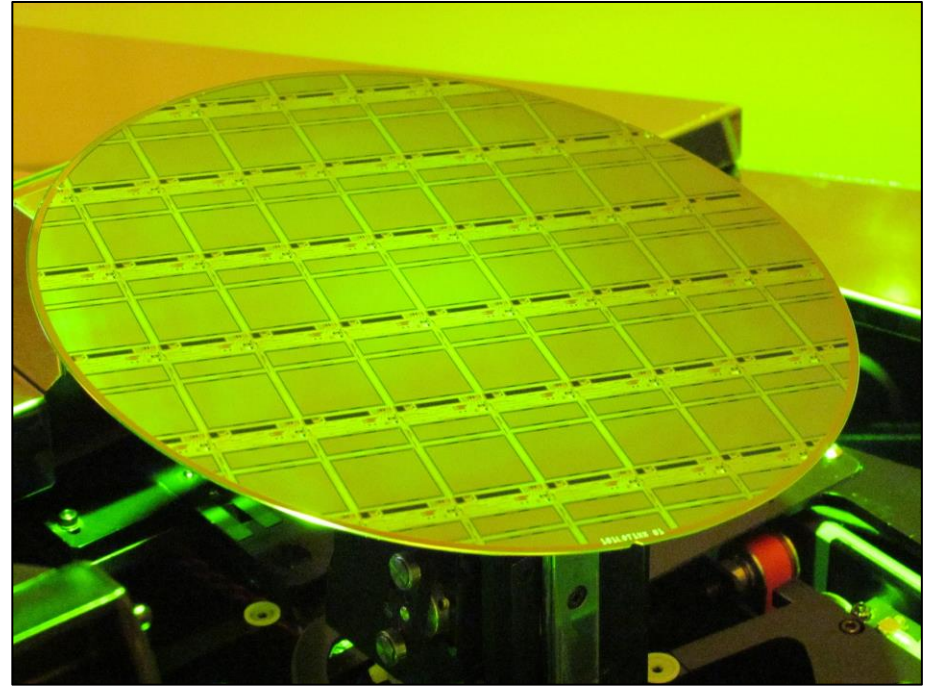
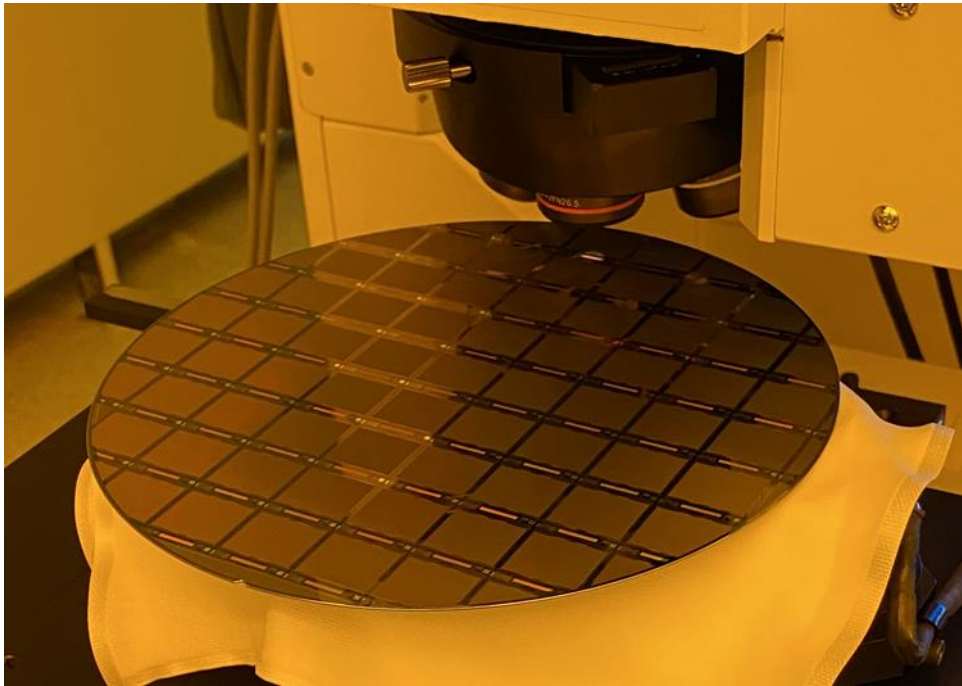
See DAMIC-M web site
<https://damic.uchicago.edu/>



- 2022 DAMIC-M run at Modane
 - [PRL 130.171003](#)
 - Low background chamber (LBC)
 - Laboratoire Souterrain de Modane
 - 2 6k x 4k CCDs, 650 um thick
- 2022-2023 DAMIC-M at SNOLAB
 - [arXiv:2306.01717](#)
 - 2 6k x 4k CCDs, 650 um thick
 - Feb 2022 – Jan 2023
 - Excess signal noted

OSCURA

Observatory of Skipper CCDs Unveiling Recoiling Atoms



- Technology transfer of the LBNL p-channel fully depleted technology to Microchip Technology (above left) and Lincoln Laboratory (above right)
 - 200 mm wafers with step-and-repeat photolithography
 - 10 kg scale (~20k 1Mpix CCDs, 10x more pixels than LSST/Rubin)

First results from a multiplexed and massive instrument with sub-electron noise Skipper-CCDs

F. Chierchie,^{a,b,1} C.R. Chavez,^{c,b,d} M. Sofo Haro,^e G. Fernandez Moroni,^c B.A. Cervantes-Vergara,^{c,f} S. Perez,^{g,c} J. Estrada,^c J. Tiffenberg,^c S. Uemura^c and A. Botti,^c

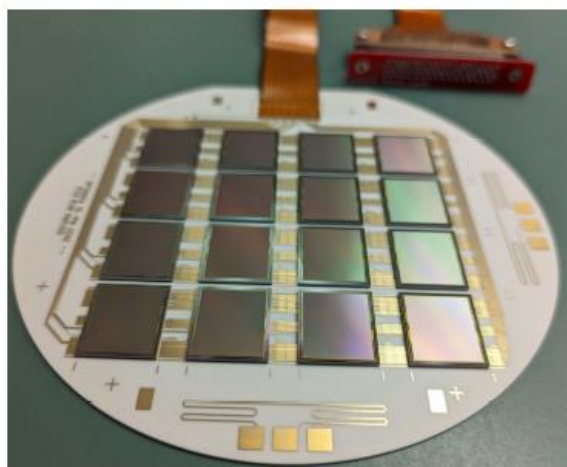


Figure 3: Photograph of a Multi-Chip Module (MCM): single layer ceramic substrate with 16 glued single-electron resolution Skipper-CCDs.

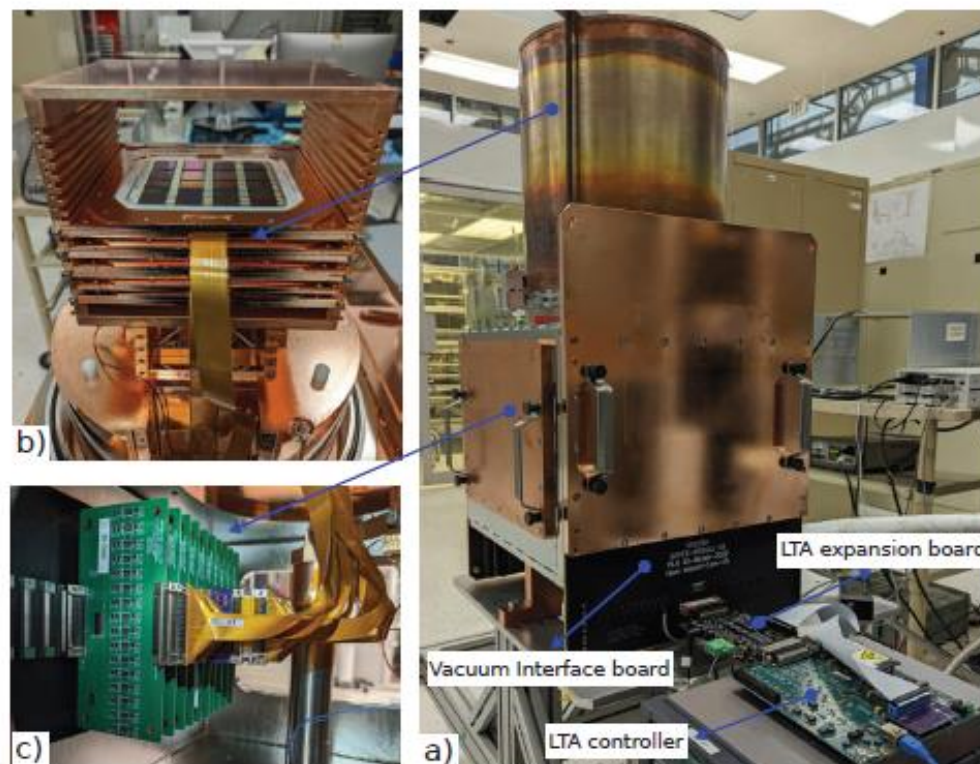


Figure 2: a) Photograph of the exterior of the instrument: cylinder in the top holds the sensors, box in the bottom houses the frontend electronics; b) Copper box and copper trays holding the sensors and flex cables; c) frontend electronics connected to the vacuum interface board.

DESI (astronomy) vs SENSEI (DM)

Parameter	DESI	SENSEI ¹
CCD format Thickness	4k x 4k (15 μ m) ² 250 μ m	6k x 1k (15 μ m) ² 650 μ m
Read noise	2.5 – 3.0 e- rms	0.1 e- rms See note 1
Dark current	~ 1 e-/pixel-hour (133K)	~ 2 x 10 ⁻⁴ e/pix-day (135-155K) See note 2
Exposure time	15 minutes	20 hours
Readout time	1 minute	7.3 hours

Note 1: Skipper CCD with 300 samples / pixel

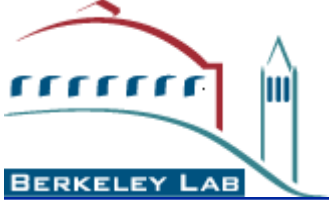
Note 2: Cold Cu, some shielding / 100 m underground
Number quoted is the single-electron event rate

¹ Sub-GeV dark matter searches with SENSEI

Nate Safford, for the SENSEI collaboration
APS April Meeting
4/15/2023

Fully depleted CCD advantages for dark matter detection

- Low noise / few e⁻ and deep sub electron (Skipper CCDs)
- Thick depleted regions / larger mass
- Background suppression / spatial and energy resolution
- Extremely low dark current for DM experiments
- Main disadvantage is the lack of timing information



Skipper CCDs / 1990

Two SPIE papers in 1990 / sub e- noise CCDs

New advancements in charge-coupled device technology - sub-electron noise and 4096x4096 pixel CCDs

James Janesick, Tom Elliott, Arsham Dingizian,
Jet Propulsion Laboratory, 4800 Oak Grove Dr, Pasadena, CA. 91109

Richard Bredthauer, Charles Chandler
Ford Aerospace Corporation, Ford Road, Newport Beach, CA. 92658

James Westphal
California Institute of Technology, Pasadena, CA. 91125

James Gunn
Princeton University, Princeton, NJ. 08544

<https://doi.org/10.1117/12.19452>

Sub-electron noise charge coupled devices

Charles E. Chandler, Richard A. Bredthauer

Ford Aerospace Corporation
Ford Road, Newport Beach, California 92658

James R. Janesick

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4800 Oak Grove Drive, Pasadena, California 91109

James A. Westphal

California Institute of Technology
Pasadena, California 91125

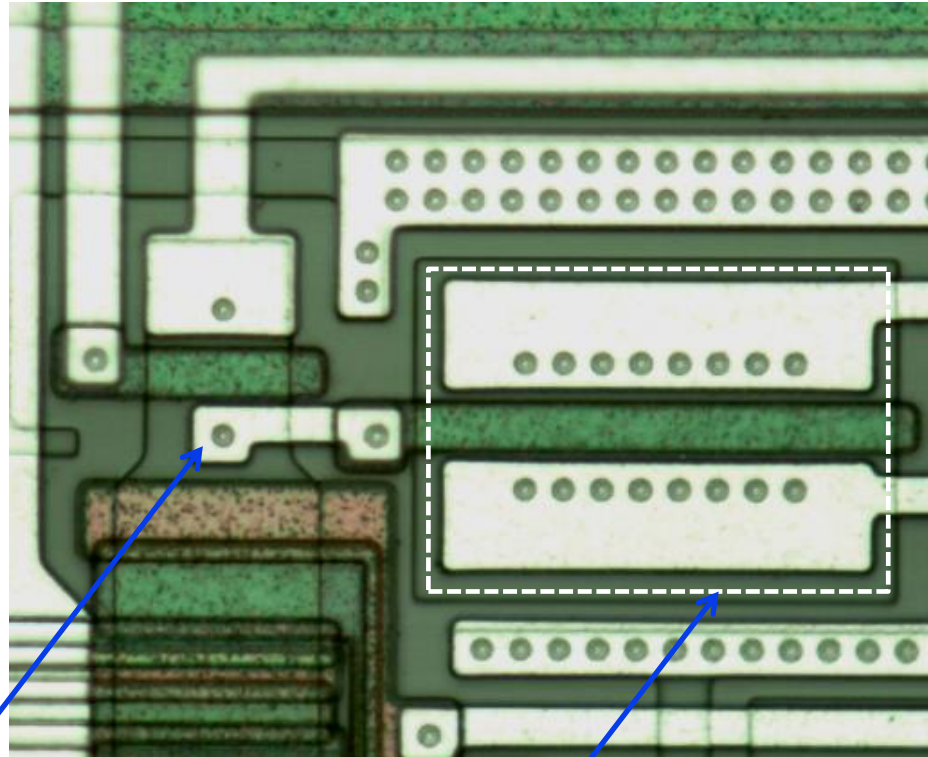
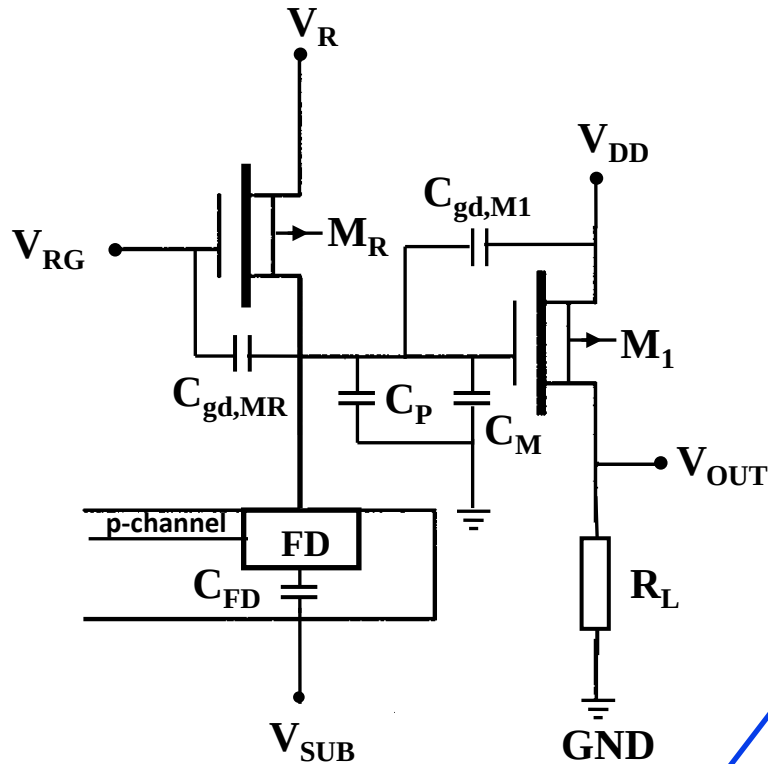
James E. Gunn

Princeton University
Princeton, New Jersey, 08544

<https://doi.org/10.1117/12.19457>

- Invented by Jim Janesick
 - U.S. patent 5250824 (1993)
- Based on the floating-gate amplifier first reported by Fairchild in the early 1970's
- Conventional CCDs use floating-diffusion amplifiers

Floating-diffusion amplifier



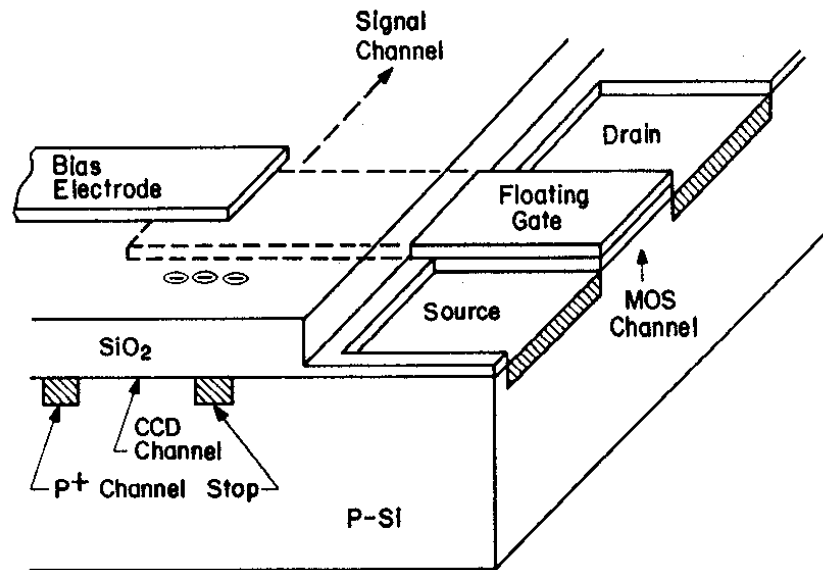
Floating diffusion

Output transistor M1

Floating-gate amplifier

- Floating-gate amplifier paper (1974 Fairchild)

WEN : FLOATING GATE AMPLIFIER



Design and Operation of a Floating Gate Amplifier

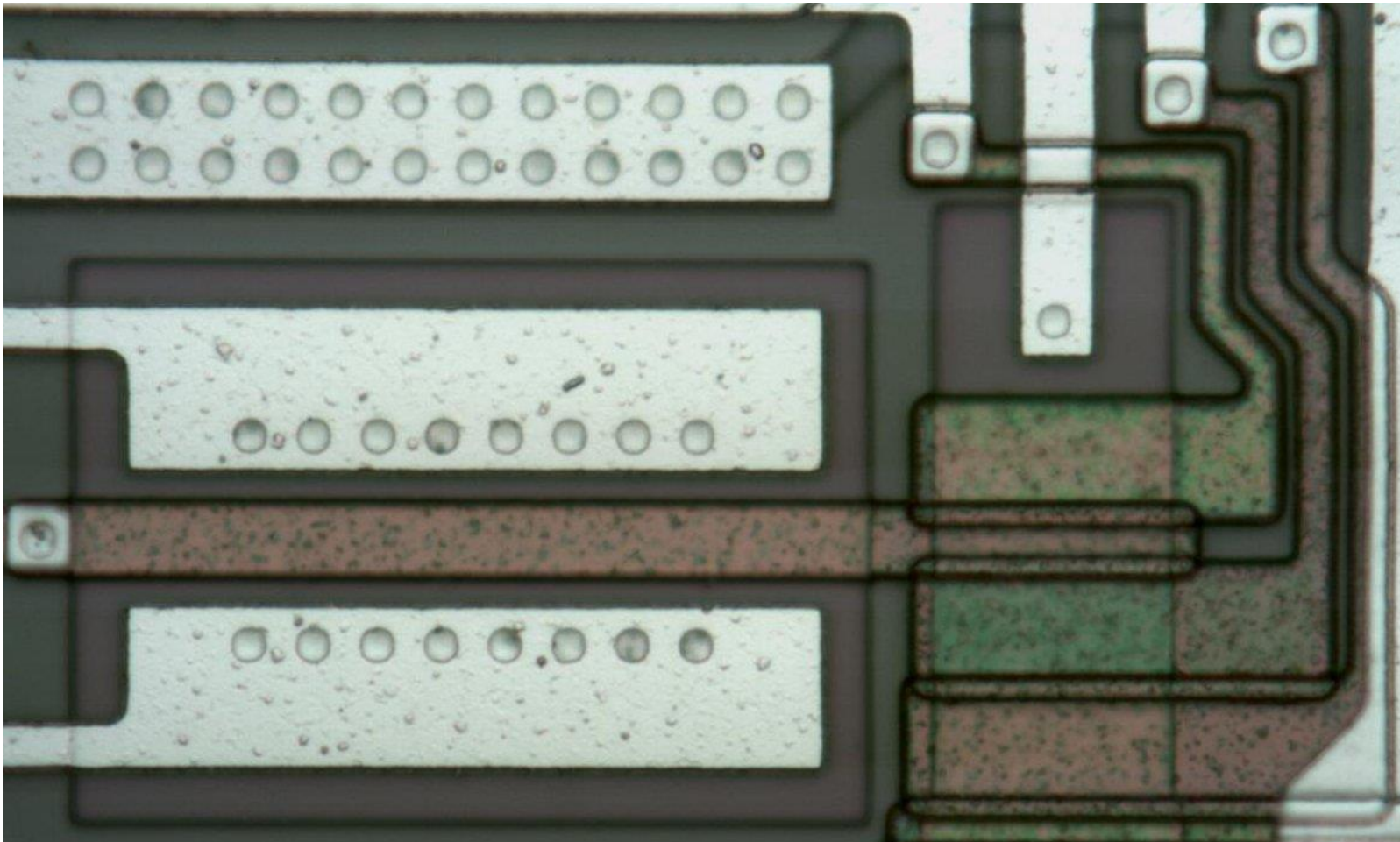
DAVID D. WEN, MEMBER, IEEE

IEEE JOURNAL OF SOLID-STATE CIRCUITS, VOL. SC-9, NO. 6, DECEMBER 1974

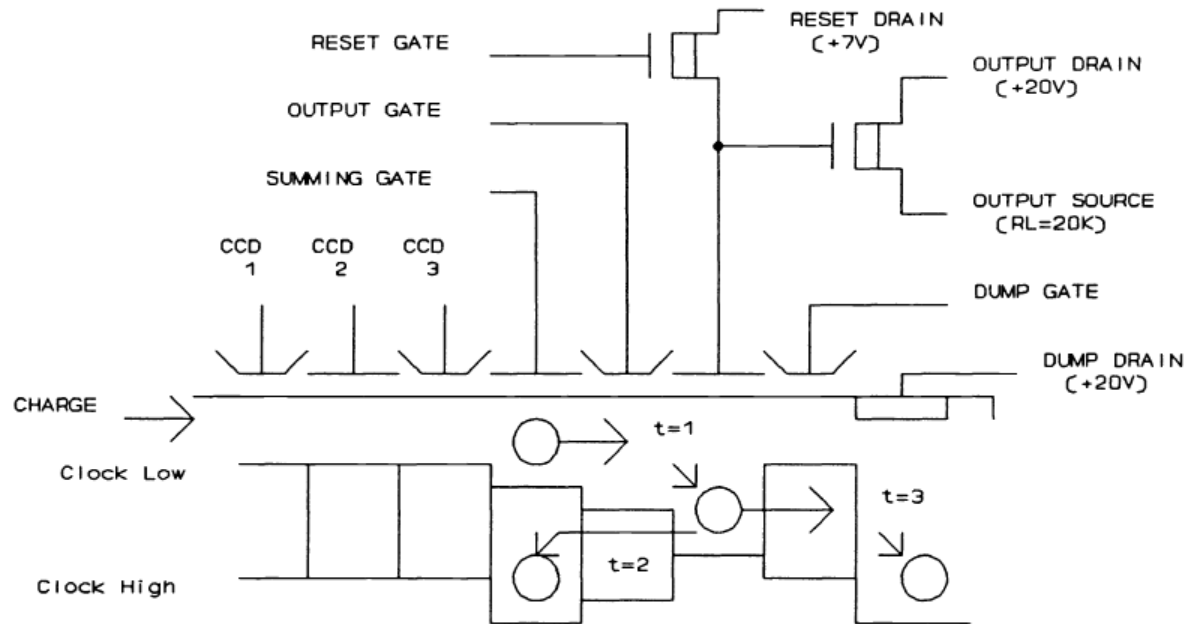
DOI: [10.1109/JSSC.1974.1050535](https://doi.org/10.1109/JSSC.1974.1050535)

Floating-gate amplifier

- LBNL implementation (floating-gate amplifier)



Skipper CCD operation



240 / SPIE Vol. 1242 Charge-Coupled Devices and Solid State Optical Sensors (1990)

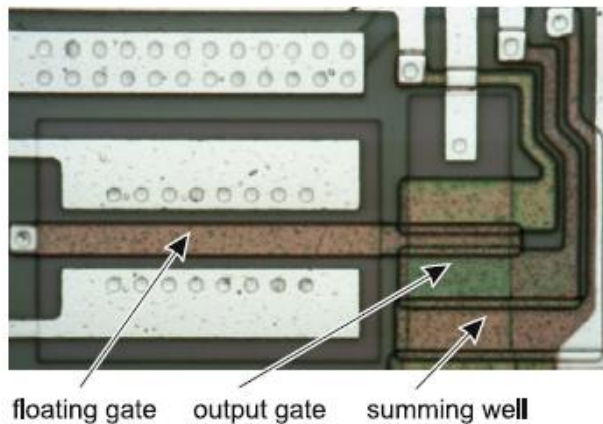
- Multiple, nondestructive reads of the charge (floating-gate)
- Noise $\propto$ Inverse square root of the number of samples
—1990 results
 - 0.5 e- noise but no improvement after 256 samples

- 1022 x 1024 (15 μm pixel)² CCD (LDRD 2009)
 - 0.2 e⁻ after 1227 samples (2012)

Exp Astron (2012) 34:43–64

47

Fig. 4 L2 amplifier layout. The floating gate, the output gate and the summing well gate are shown



Exp Astron (2012) 34:43–64

57

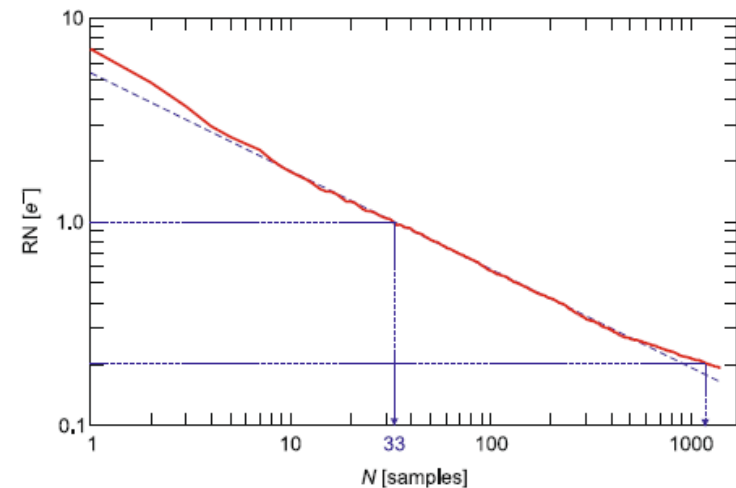


Fig. 10 Skipper CCD RN in the overscan region as a function of the number of averaged samples N . Continuous line RN measured from images. Dashed line theoretical RN reduction fit for white or $1/f^2$ noise

<https://doi.org/10.1007/s10686-012-9298-x>

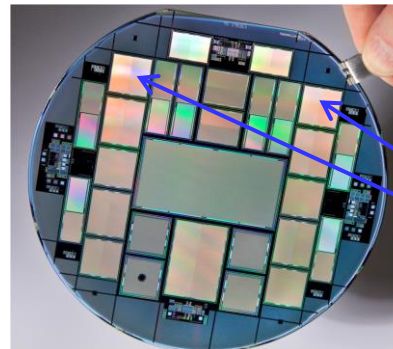
Exp Astron (2012) 34:43–64

DOI 10.1007/s10686-012-9298-x

ORIGINAL ARTICLE

Sub-electron readout noise in a Skipper CCD fabricated on high resistivity silicon

Guillermo Fernández Moroni · Juan Estrada ·
Gustavo Cancelo · Stephen E. Holland ·
Eduardo E. Paolini · H. Thomas Diehl



Factor of 2.5 better
than 1990's work

FG amplifier CCDs

- 2nd version (LDRD 2013)
 - 0.068 e^- after 4k samples (2017)

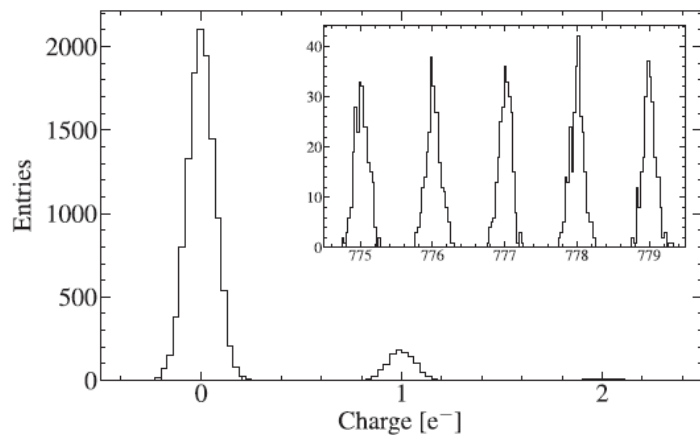


FIG. 1. Single-electron charge resolution using a Skipper CCD with 4000 samples per pixel (bin width of $0.03 e^-$). The measured charge per pixel is shown for low (main) and high (inset) illumination levels. Integer electron peaks can be distinctly resolved in both regimes contemporaneously. The $0 e^-$ peak has rms noise of $0.068 e^-$ rms/pixel while the $777 e^-$ peak has $0.086 e^-$ rms/pixel, demonstrating single-electron sensitivity over a large dynamical range. The Gaussian fits have $\chi^2 = 22.6/22$ and $\chi^2 = 19.5/21$, respectively.

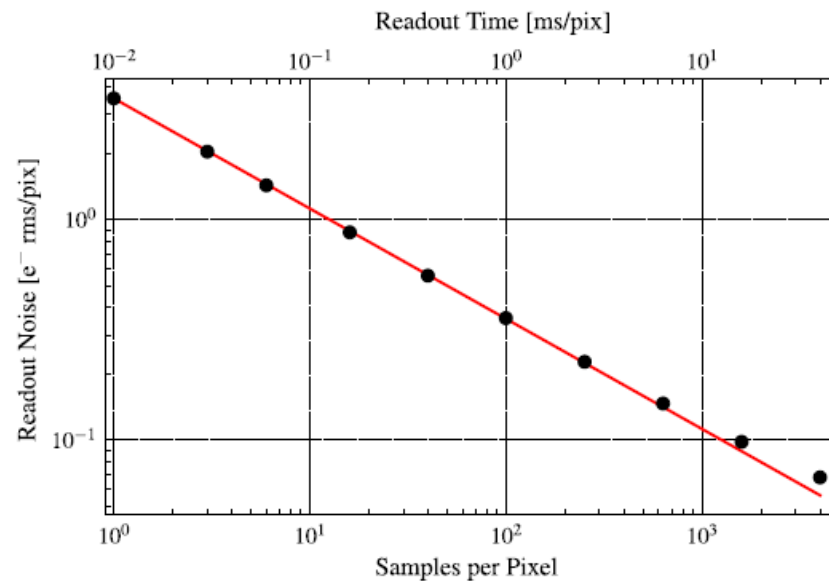
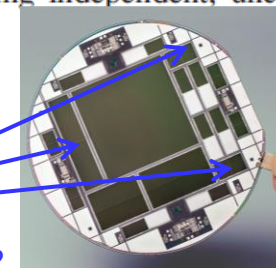


FIG. 3. Readout noise as a function of the number of nondestructive readout samples per pixel for the Skipper CCD. Black points show the rms of the empty-pixel distribution as a function of the number of averaged samples. The red line is the theoretical expectation assuming independent, uncorrelated samples [Eq. (1)].



FG amplifier CCDs

Single-Electron and Single-Photon Sensitivity with a Silicon Skipper CCD

Javier Tiffenberg,^{1,*} Miguel Sofo-Haro,^{2,1} Alex Drlica-Wagner,¹ Rouven Essig,³ Yann Guardincerri,^{1,†} Steve Holland,⁴ Tomer Volansky,⁵ and Tien-Tien Yu⁶

¹Fermi National Accelerator Laboratory, P.O. Box 500, Batavia, Illinois 60510, USA

²Centro Atómico Bariloche, CNEA/CONICET/IB, Bariloche R8402AGP, Argentina

³C.N. Yang Institute for Theoretical Physics, Stony Brook University, Stony Brook, New York 11794, USA

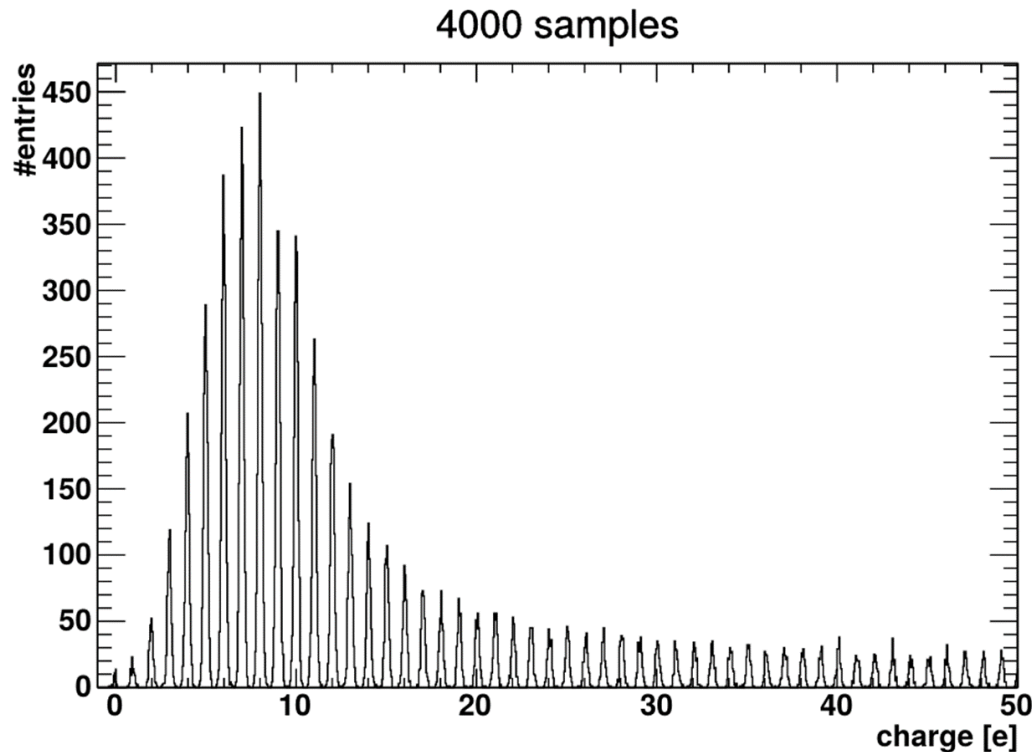
⁴Lawrence Berkeley National Laboratory, One Cyclotron Road, Berkeley, California 94720, USA

⁵Raymond and Beverly Sackler School of Physics and Astronomy, Tel-Aviv University, Tel-Aviv 69978, Israel

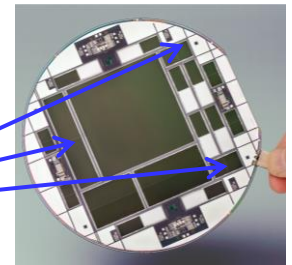
⁶Theoretical Physics Department, CERN, CH-1211 Geneva 23, Switzerland

(Received 4 June 2017; published 26 September 2017)

- 2nd version (LDRD 2013)
 - Low-level light charge histogram (FermiLab)

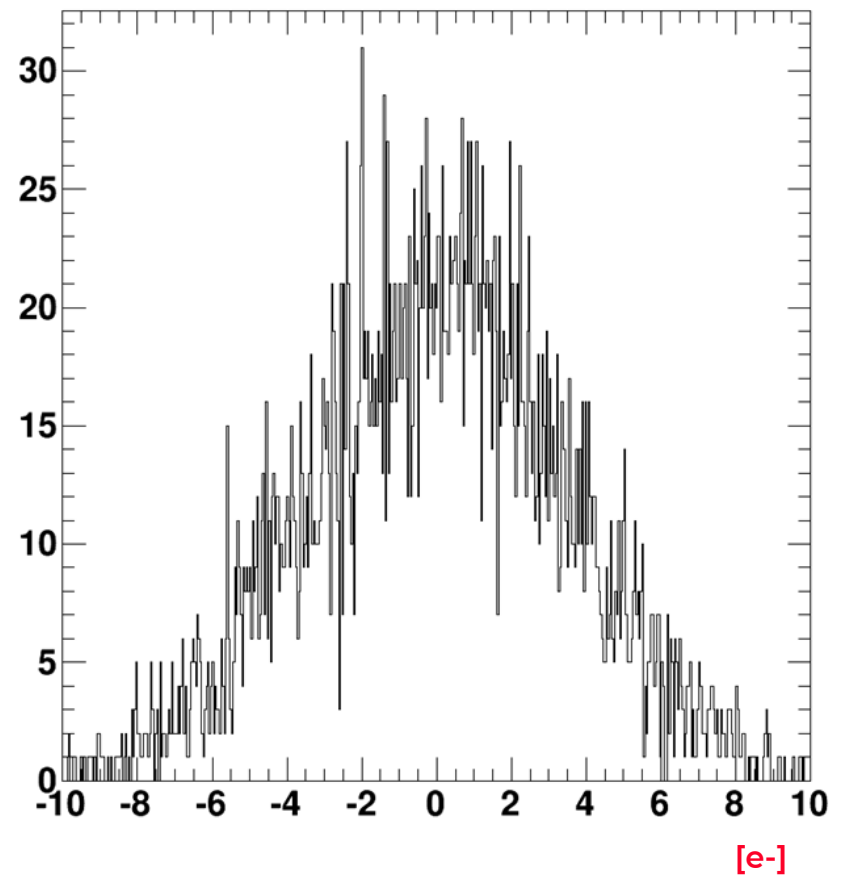
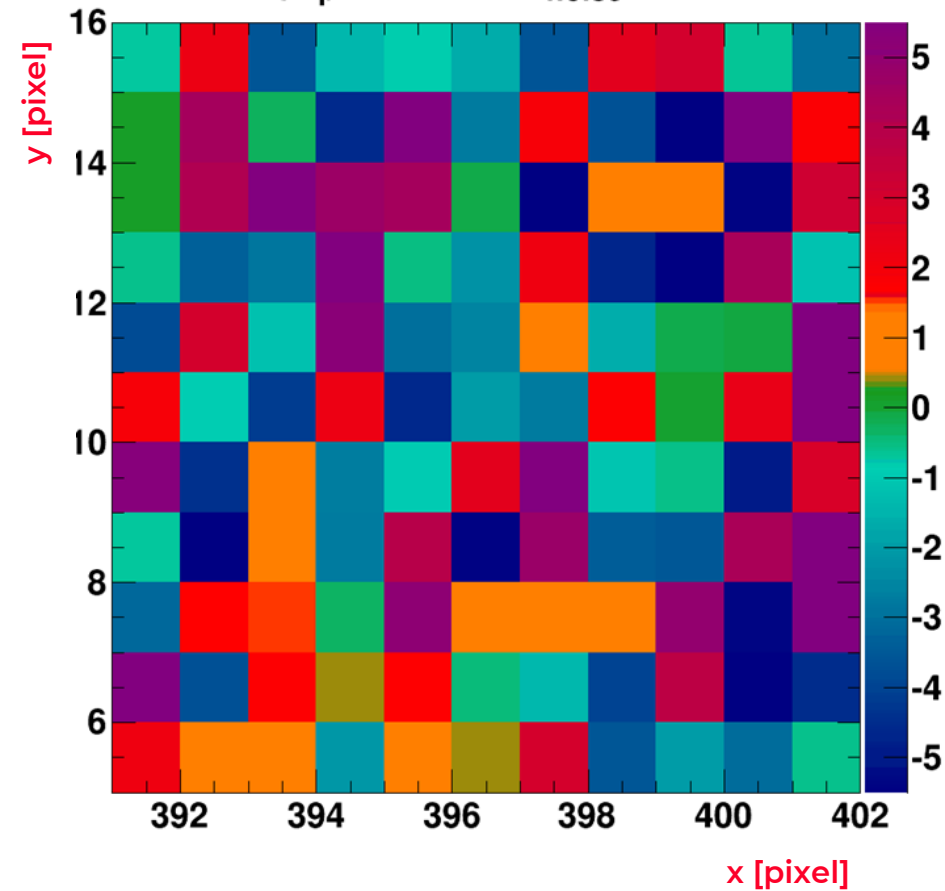


FG amplifier CCDs



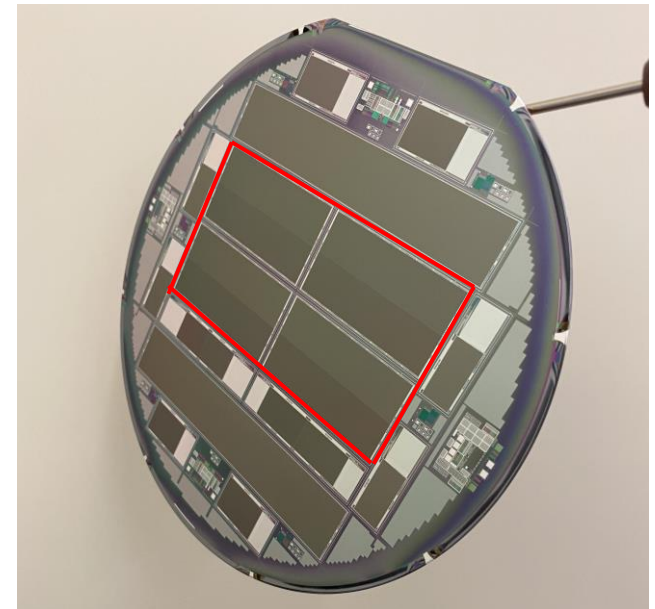
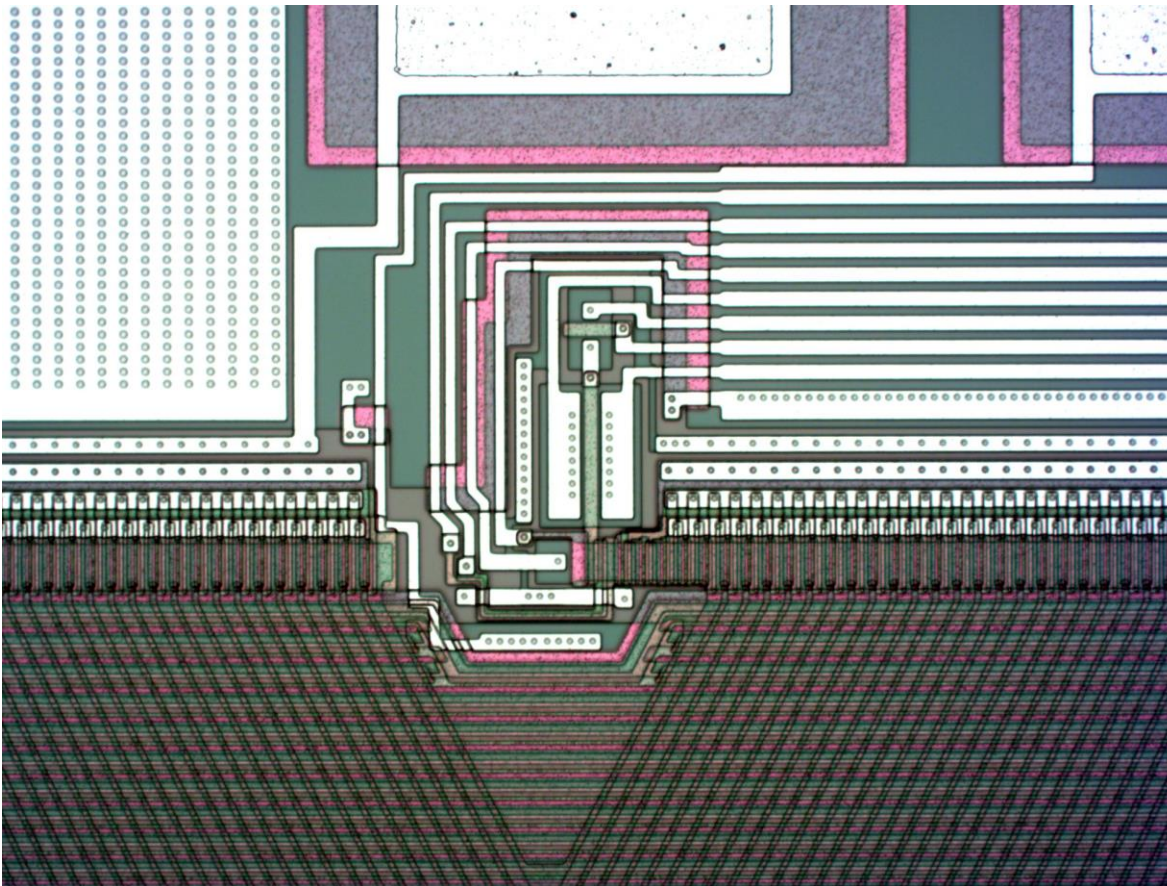
Skipper-CCD basics

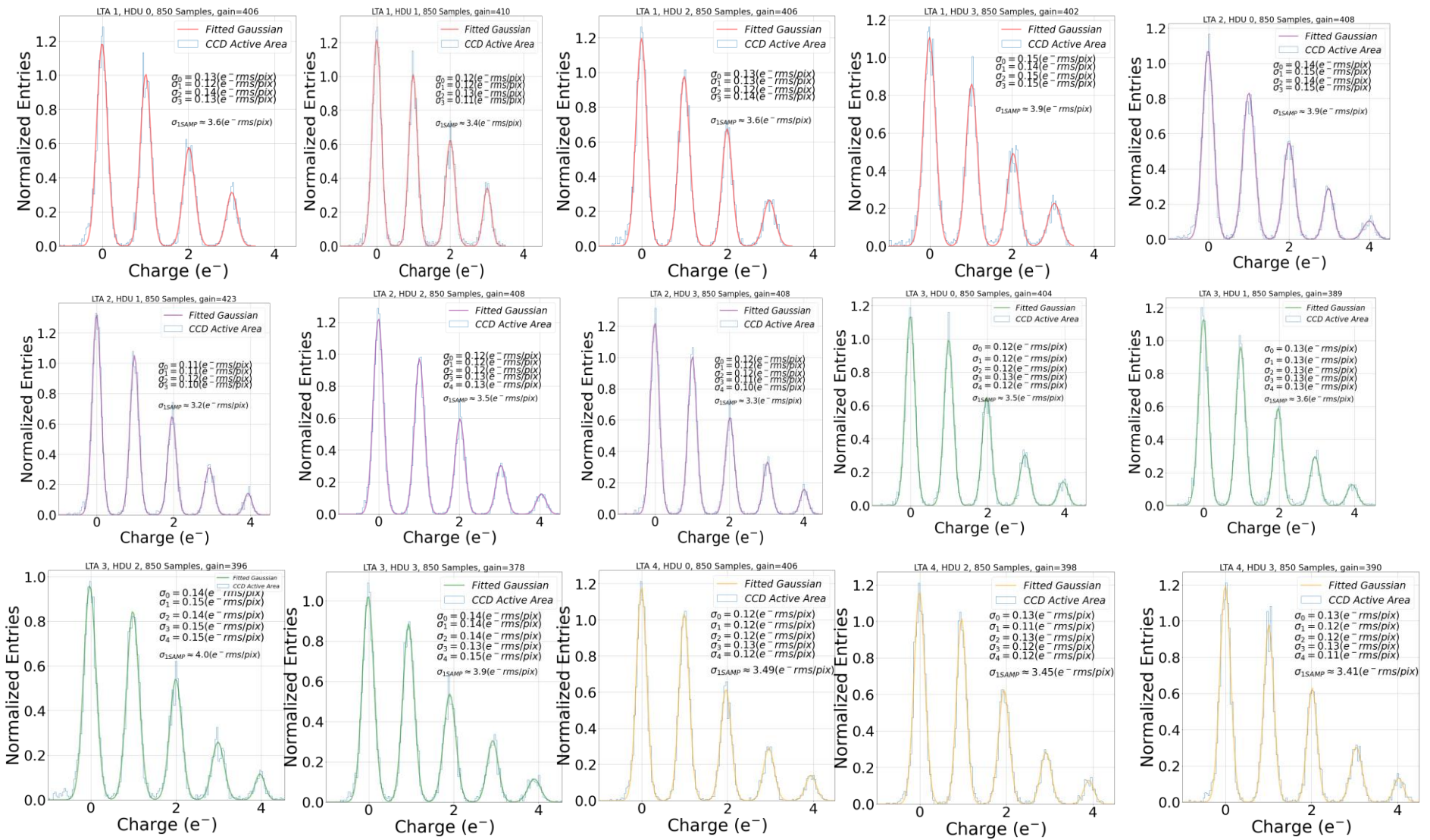
$N_{\text{smp}} = 1$ $\sigma_{\text{noise}} = 3.5$



Faster readout for Skipper CCDs

- #1: Amplifiers every 512 columns (LSST type CCD)
 - 4k x 2k, $(10.5\ \mu\text{m})^2$ pixel CCDs with 16 amplifiers
 - Tapered columns to $10.2\ \mu\text{m}$ serial registers





16-channel Skipper CCD results

Measurements at FermiLab (850 samples)

E. Marrufo Villapando (U Chicago)

Faster readout for Skipper CCDs

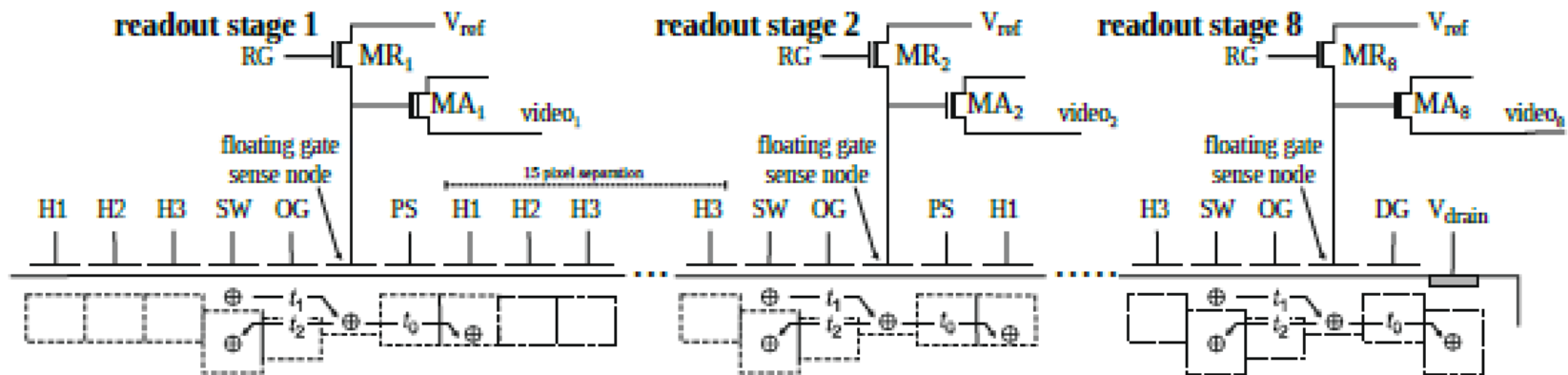
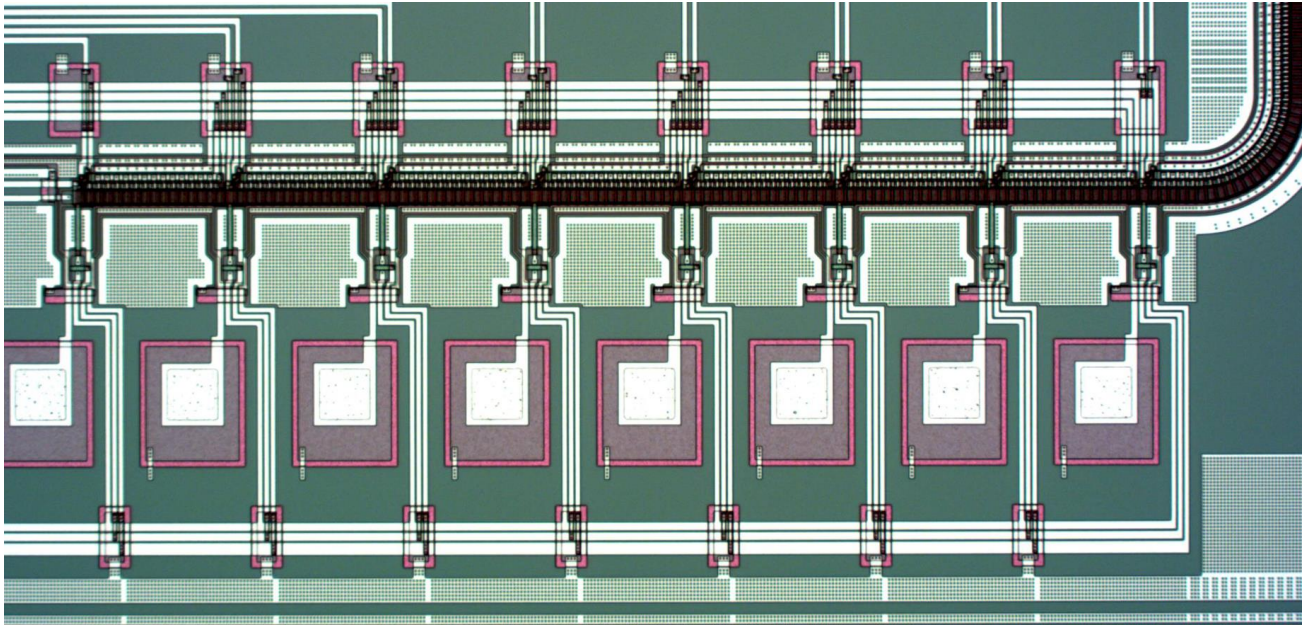


FIG. 1: Architecture of the eight inline amplifiers at the end of the serial register of the MAS-CCD.

- Multiple-amplifier sensing
 - When the first pixel is read out of the M^{th} amplifier, the next pixel has been sampled by $M-1$ amplifiers
 - ~ Conventional readout once the initial overhead to get to amp M
 - Can average over the # of amplifiers if statistically independent
 - Interest for astronomy
 - Read once per amp with $\sim 1 \text{ e}^-$ after averaging (16 amplifiers)

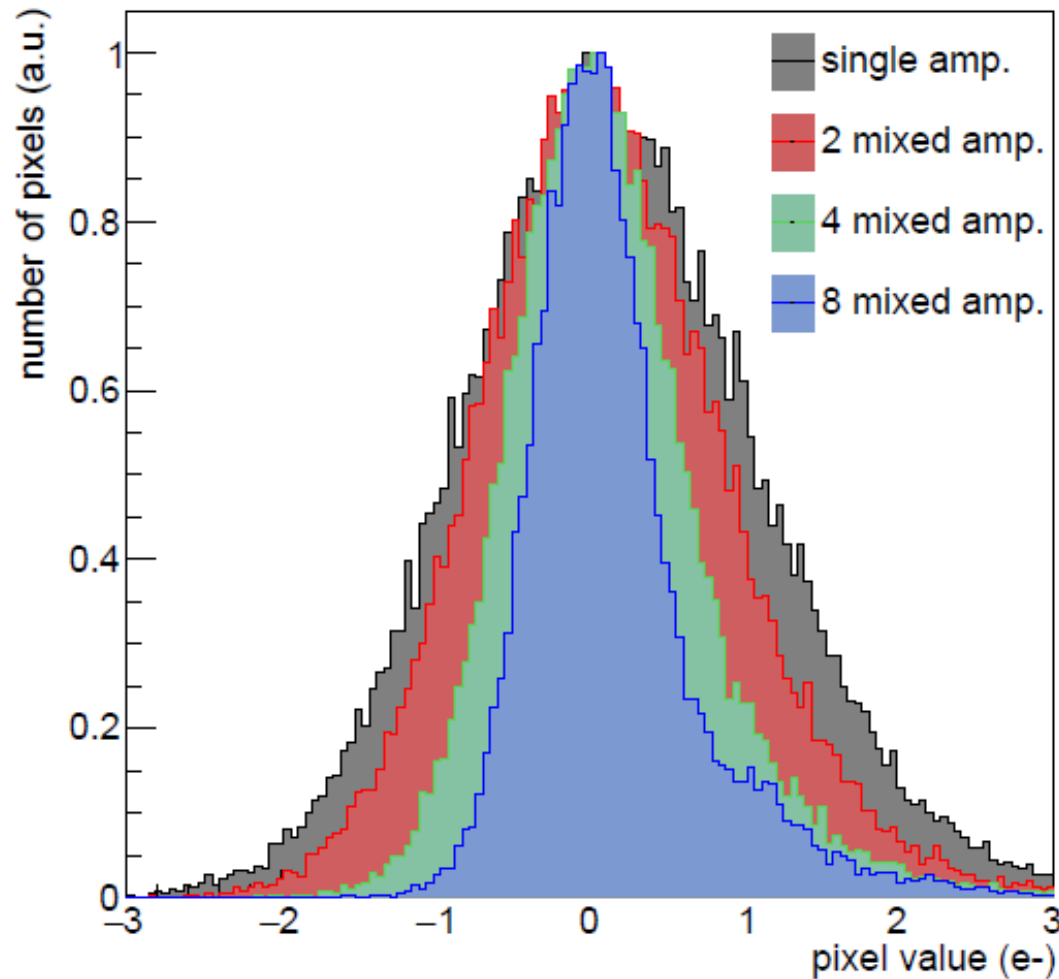
Faster readout for Skipper CCDs



- Multiple-amplifier sensing
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Faster readout for Skipper CCDs

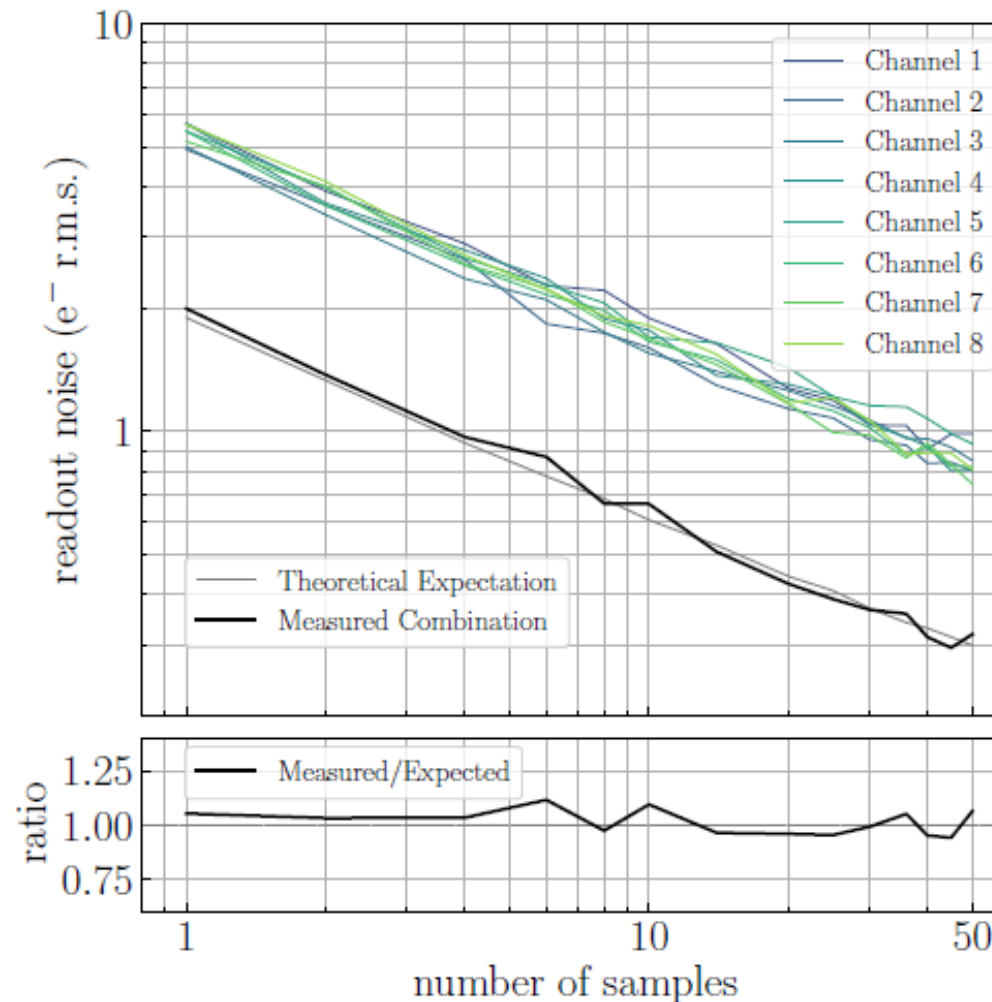
- 8-amplifier version (testing at FermiLab)



50 samples / amplifier

Faster readout for Skipper CCDs

- 8-amplifier version (testing at FermiLab)



Fully depleted CCD advantages for dark matter detection

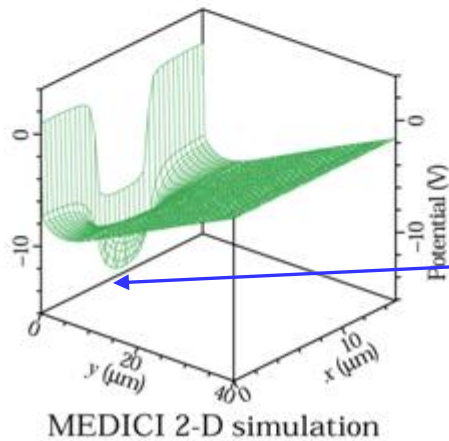
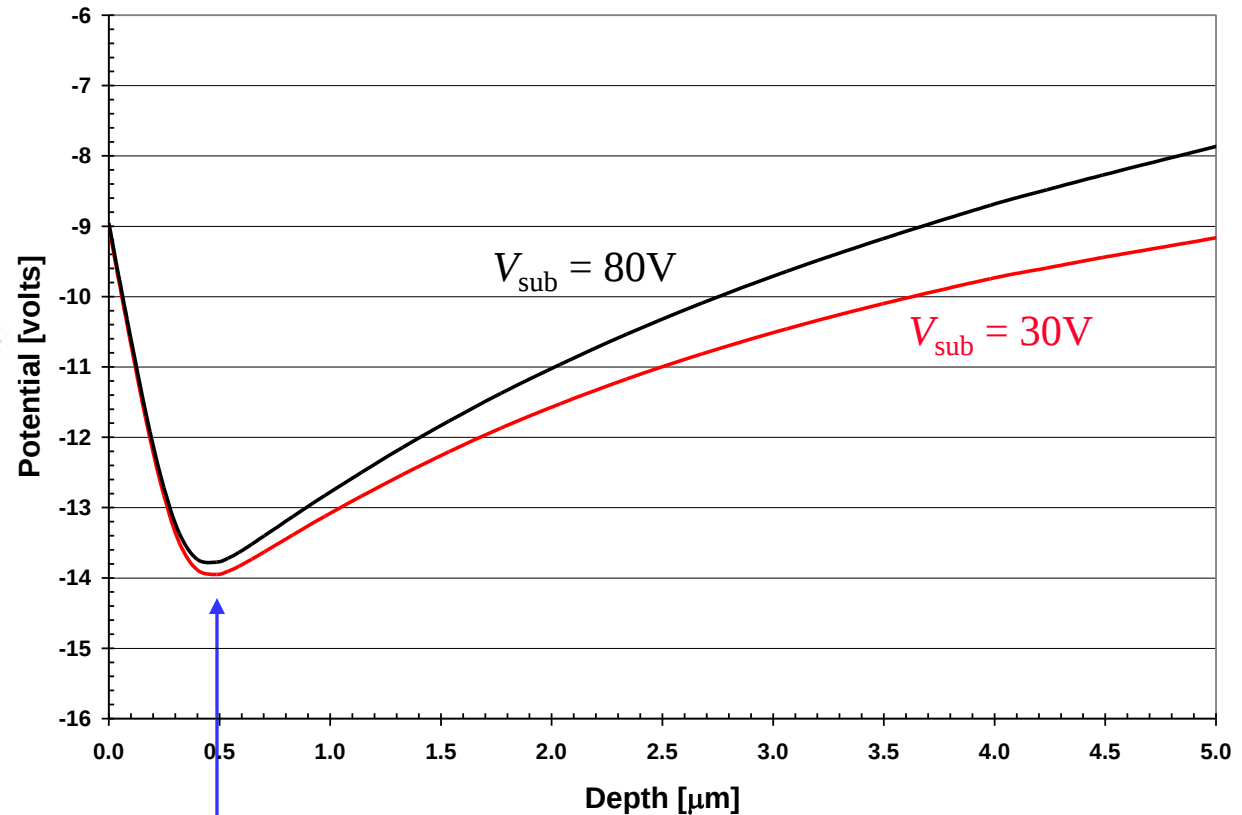
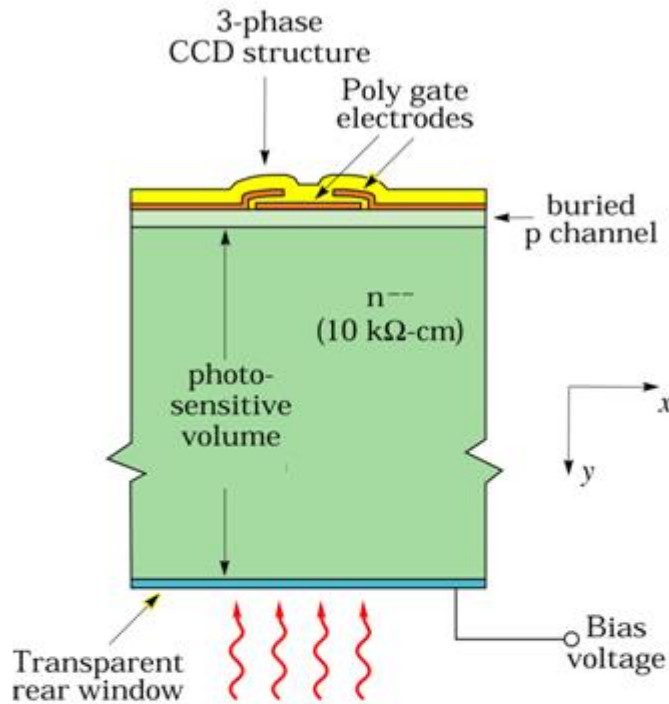
- Low noise / few e⁻ and deep sub electron (Skipper CCDs)
- Thick depleted regions / larger mass
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- Main disadvantage is the lack of timing information

Dark Matter detection with CCDs

- Dark Matter CCDs require as large as practical volume limited by the standard wafer thickness
 - Semiconductor industry standards (SEMI/JEIDA)
 - 150 mm / 200 mm Ø corresponds to 650 μm / 725 μm
- Depletion voltage goes as (thickness)² and (resistivity)⁻¹
 - LBNL high-voltage compatible CCD designs
 - DOI: [10.1109/TED.2009.2030631](https://doi.org/10.1109/TED.2009.2030631) and <https://doi.org/10.1117/12.672393>
 - Improvements in the production of float-zone silicon
 - Higher resistivity / lower depletion voltage

$$V_{\text{depl}} = \frac{qN_D}{2\varepsilon_{Si}} x_D^2 \quad \rho = \frac{1}{q\mu_n N_D}$$

Fully depleted CCDs / 2D simulations

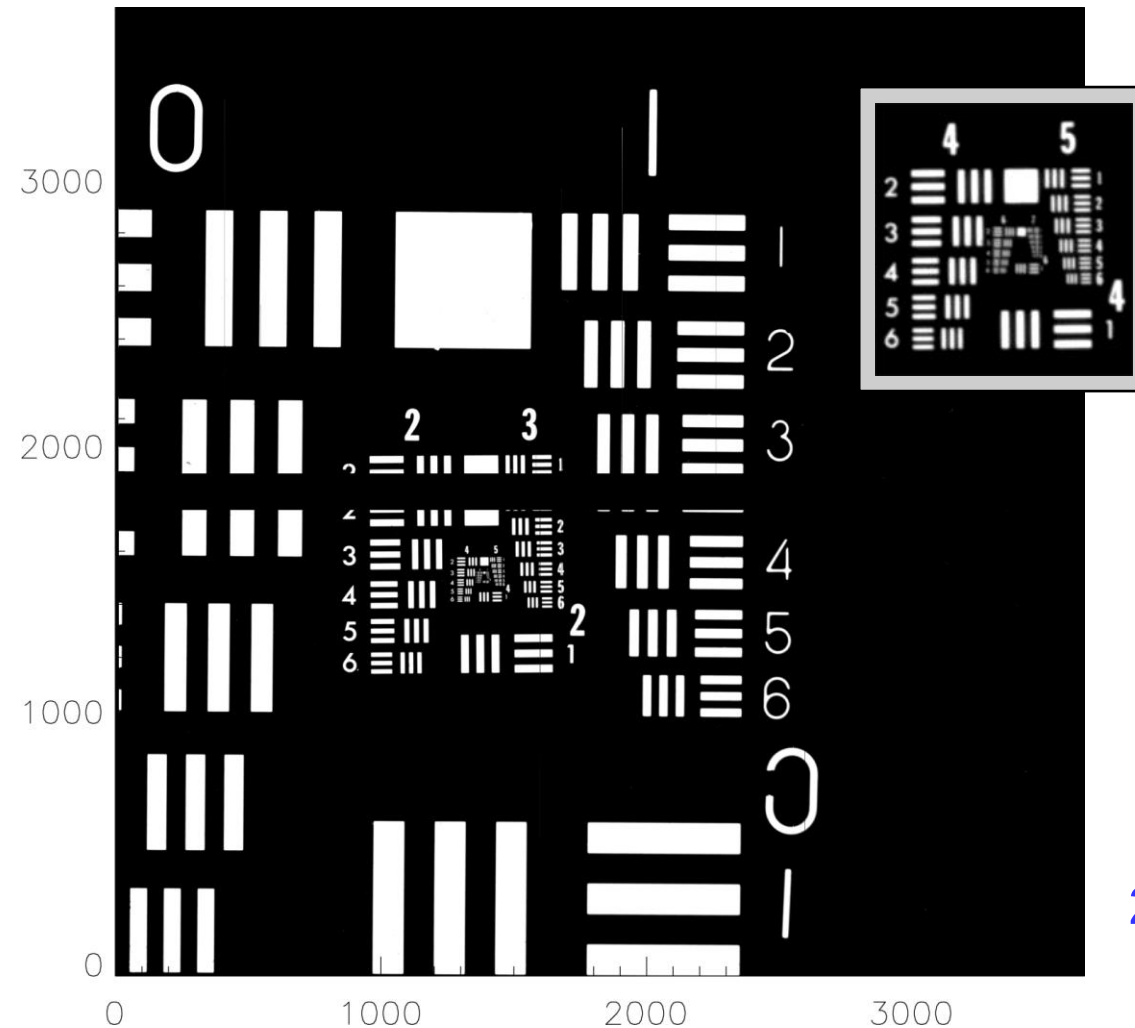


Potential minimum (collecting phase)

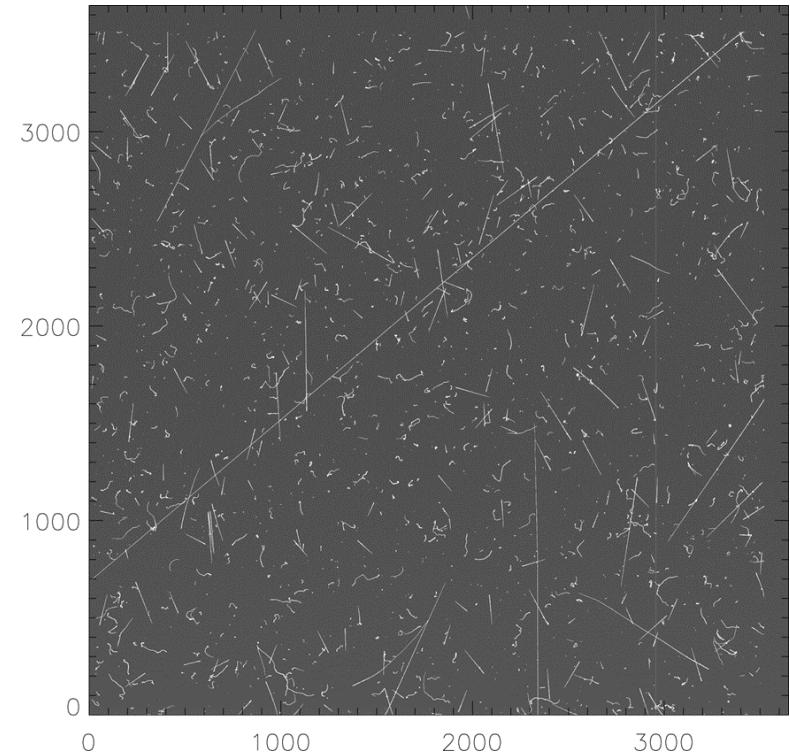
- Relatively insensitive to V_{sub}
- Wide range of V_{sub} possible
- Capacitor voltage divider effect

MEDICI simulations

HV-compatible CCD design (SNAP)



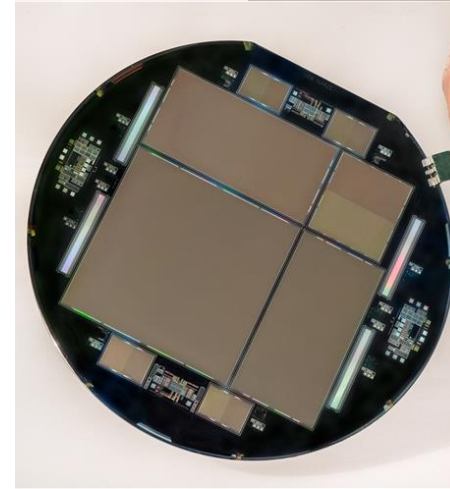
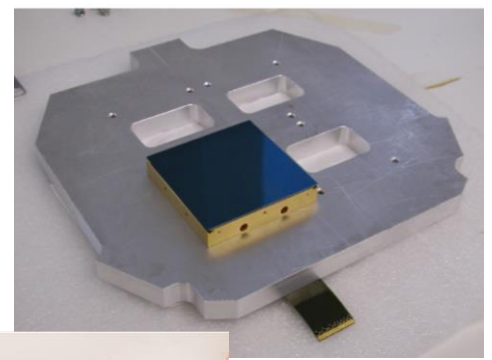
30 minute dark exposure



200V Vsub
-140C

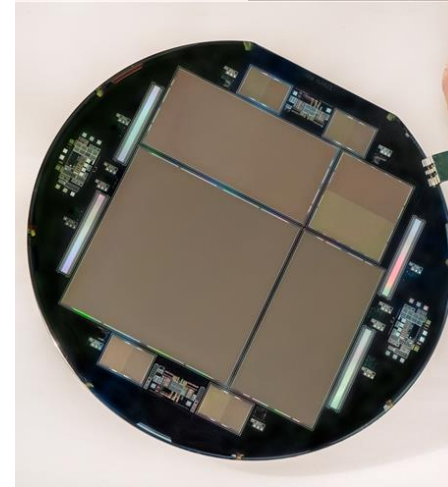
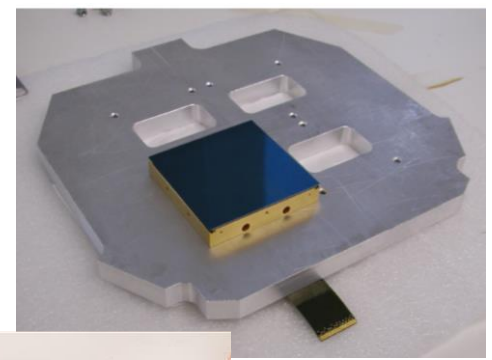
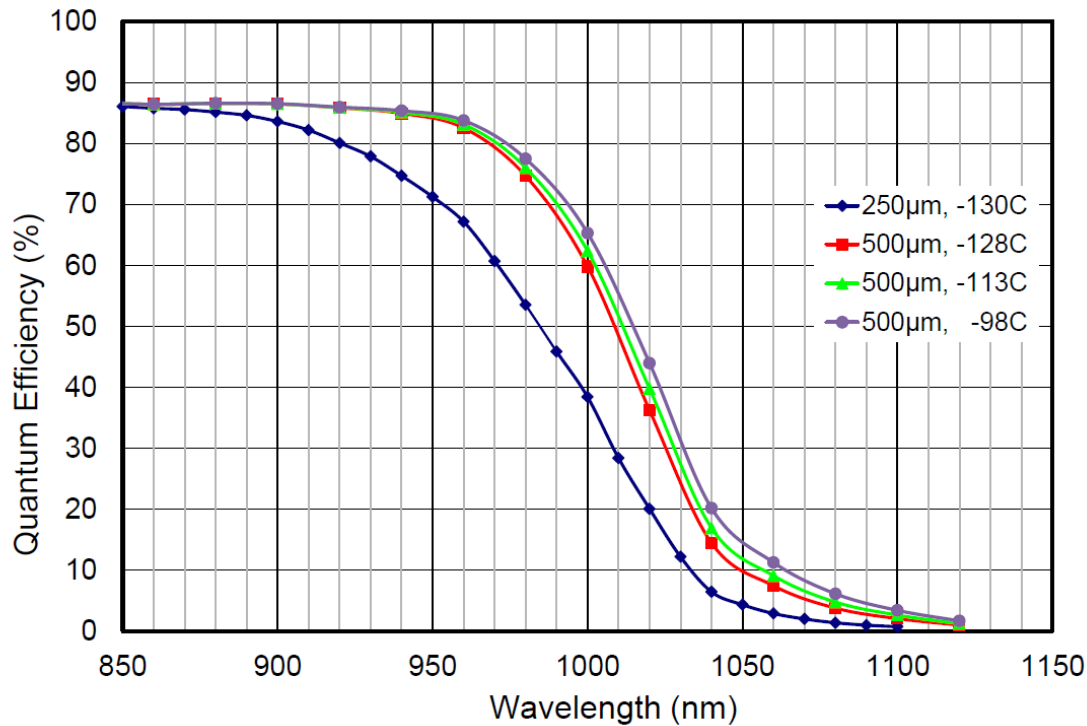
$$V_{\text{depl}} = \frac{qN_D}{2\epsilon_{Si}} x_D^2 \quad \rho = \frac{1}{q\mu_n N_D}$$

M1/Crab Nebula in z band: “First and Last”



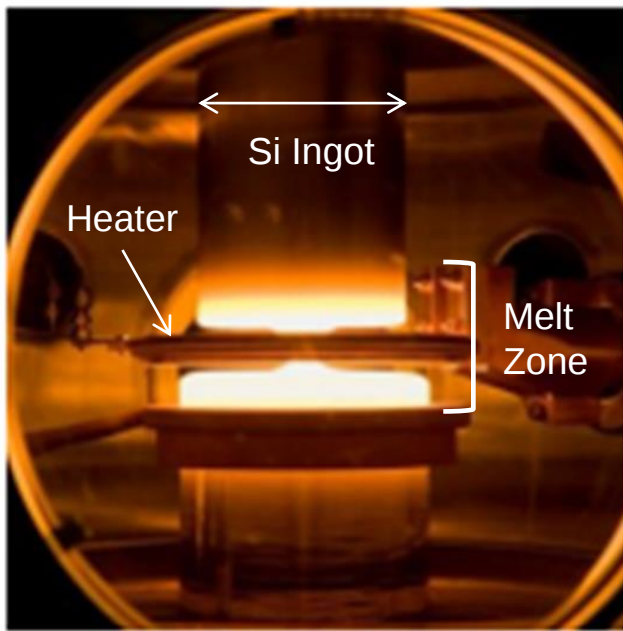
- 500 um thick, fully depleted CCD (DESI R&D)
 - MOSAIC3 was an 8k x 8k imager (2x2, 4k x 4k CCDs)
 - Lead institution was Yale University
 - One CCD now installed in the Keck LRIS instrument

A. Dey et al, “Mosaic3: A red-sensitive upgrade for the prime focus camera at the Mayall 4m telescope”, Ground-based and Airborne Instrumentation for Astronomy VI, edited by Christopher J. Evans, Luc Simard, Hideki Takami
Proc. of SPIE Vol. 9908, 99082C, 2016



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[Link to Topsil Float-Zone silicon](#)

Year Acquired	Topsil Crystal #	Resistivity ρ (k Ω -cm)	Lifetime τ (ms)
2009	2142946	5.5 – 7.0	4.4
2009	2143310	5.0 - 6.0	16.3
2009	2144322	14.0 - 20.0	3.4
2014	22-0572-10	20.0 - 28.0	7.3
2015	33-0203-20	22.0 - 26.0	21.4
2019	31-1062-10	> 10.0	22.4
2020	33-1751-30	> 10.0	18.9
2020	32-1345-20	18.0 – 20.0	23.5
2020	34-1802-10	17.7 – 22.4	18.4

Blue table entries are 150-mm diameter
Red are 200-mm diameter wafers

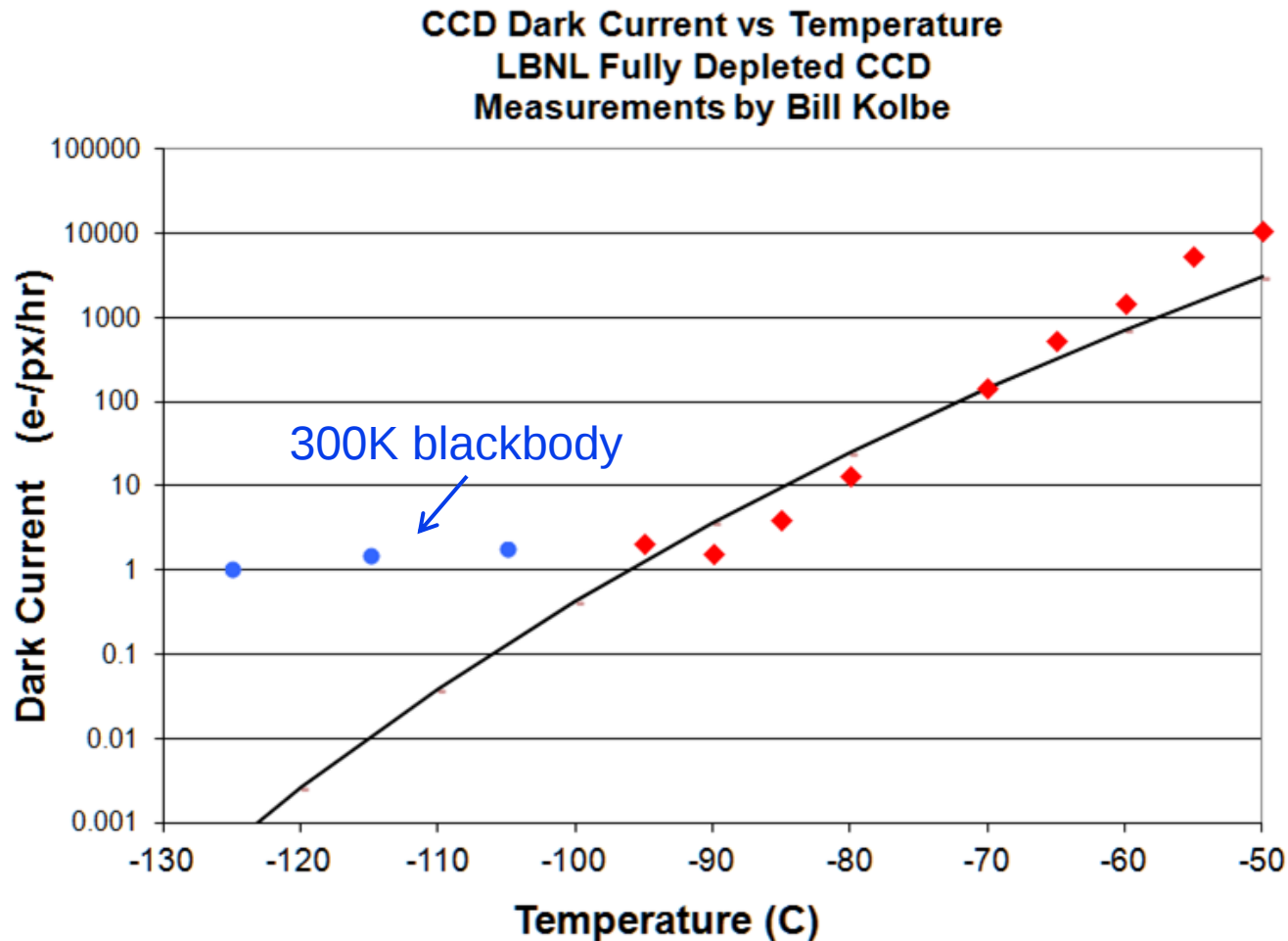
$$V_{\text{depl}} = \frac{qN_D}{2\epsilon_{Si}} x_D^2 \quad \rho = \frac{1}{q\mu_n N_D}$$

Fully depleted CCD advantages for dark matter detection

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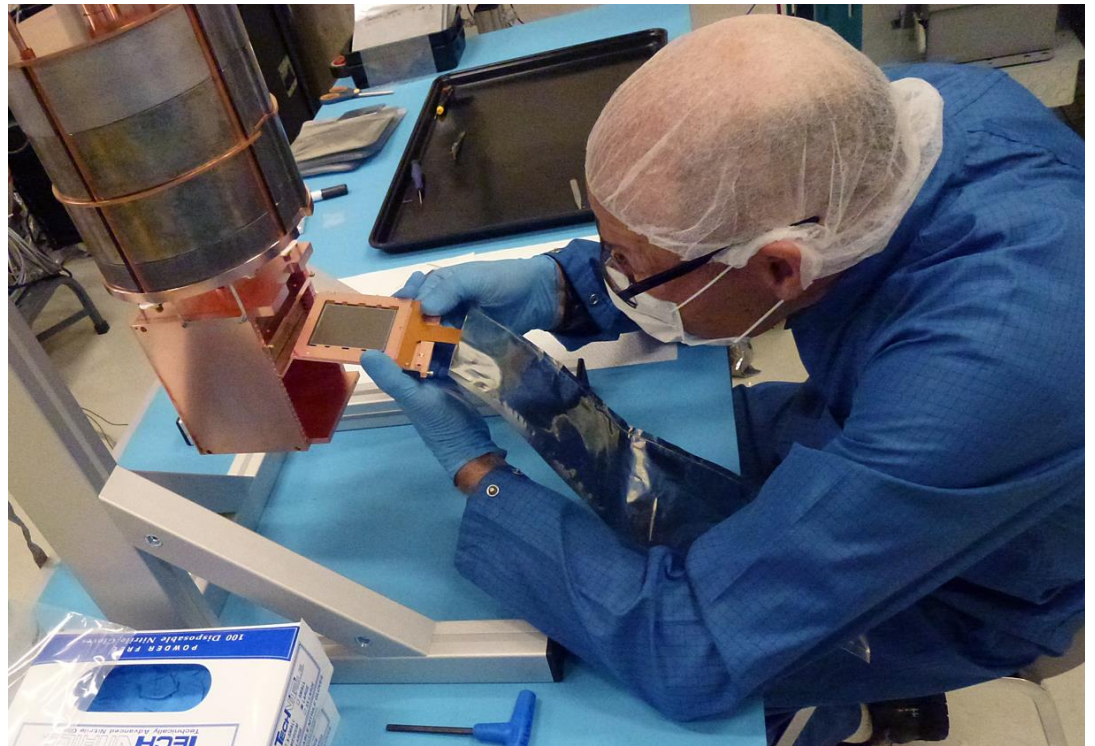
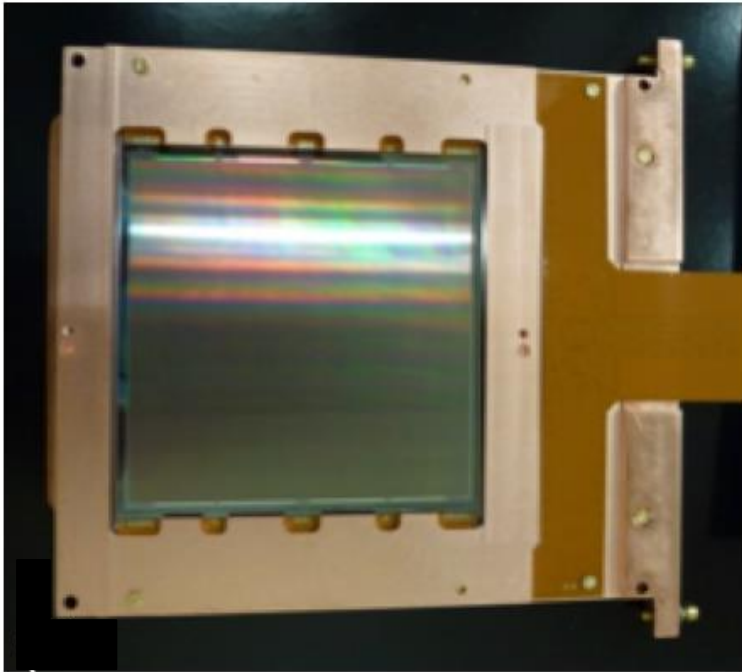
Dark Current

- Dark current measurements on a fully depleted LBNL CCD / line is the Shockley-Read-Hall model



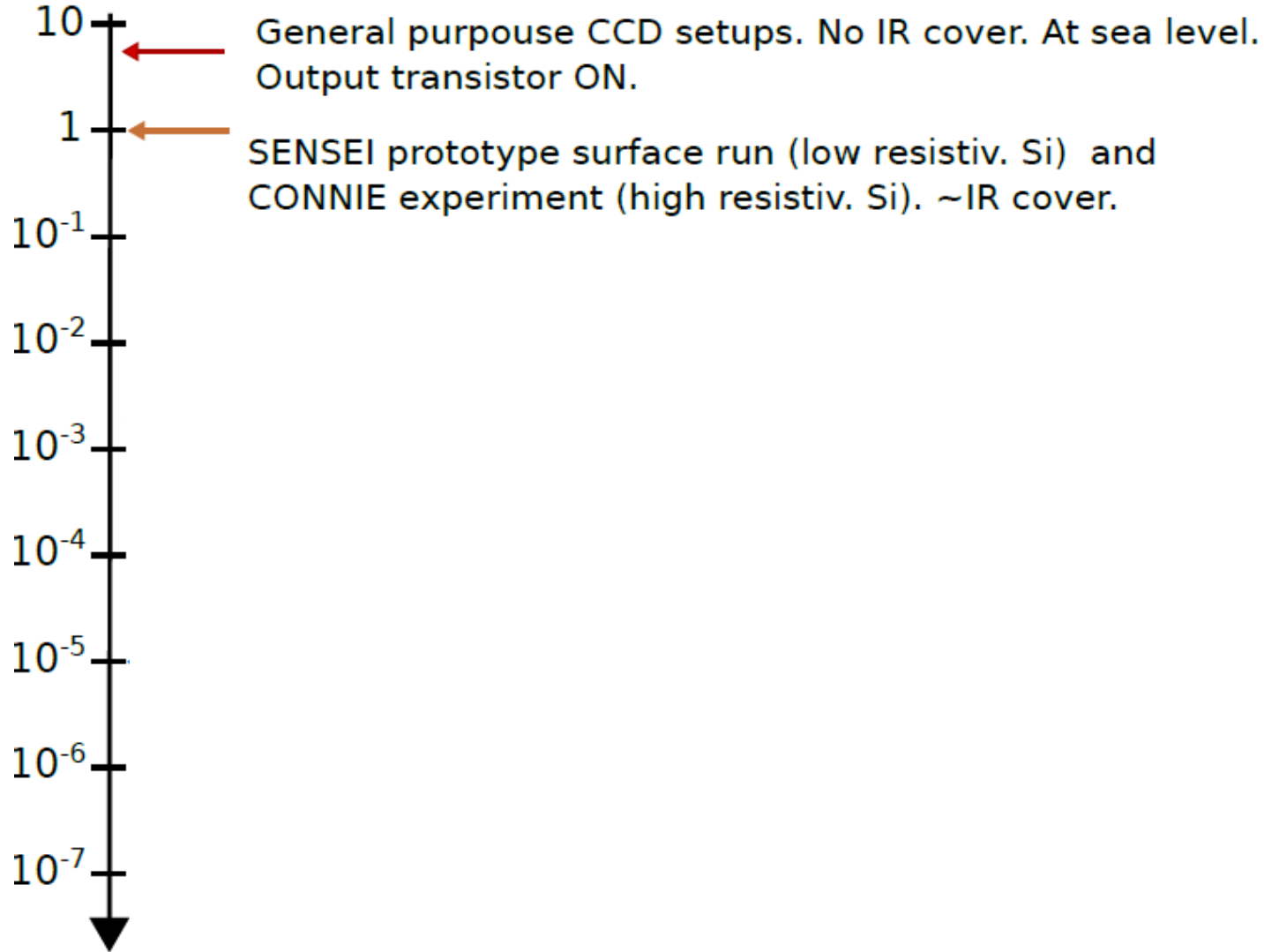
Dark Current

- Dark Matter CCDs surrounded by cold Cu to suppress 300K blackbody radiation
— <https://doi.org/10.1016/j.physletb.2012.04.006>



“Dark Current” / SEE

Single-electron rate (e-/pix/day)



- Deep underground to reduce photon generation from high-energy particles e.g. cosmic-ray muons
 - Photons from e- hole recombination in P-doped layers
 - Low probability but a problem for DM detection
 - High-energy particles produce Cherenkov radiation
 - Photon background
 - [10.1103/PhysRevX.12.011009](https://arxiv.org/abs/10.1103/PhysRevX.12.011009)

PHYSICAL REVIEW X **12**, 011009 (2022)

Sources of Low-Energy Events in Low-Threshold Dark-Matter and Neutrino Detectors

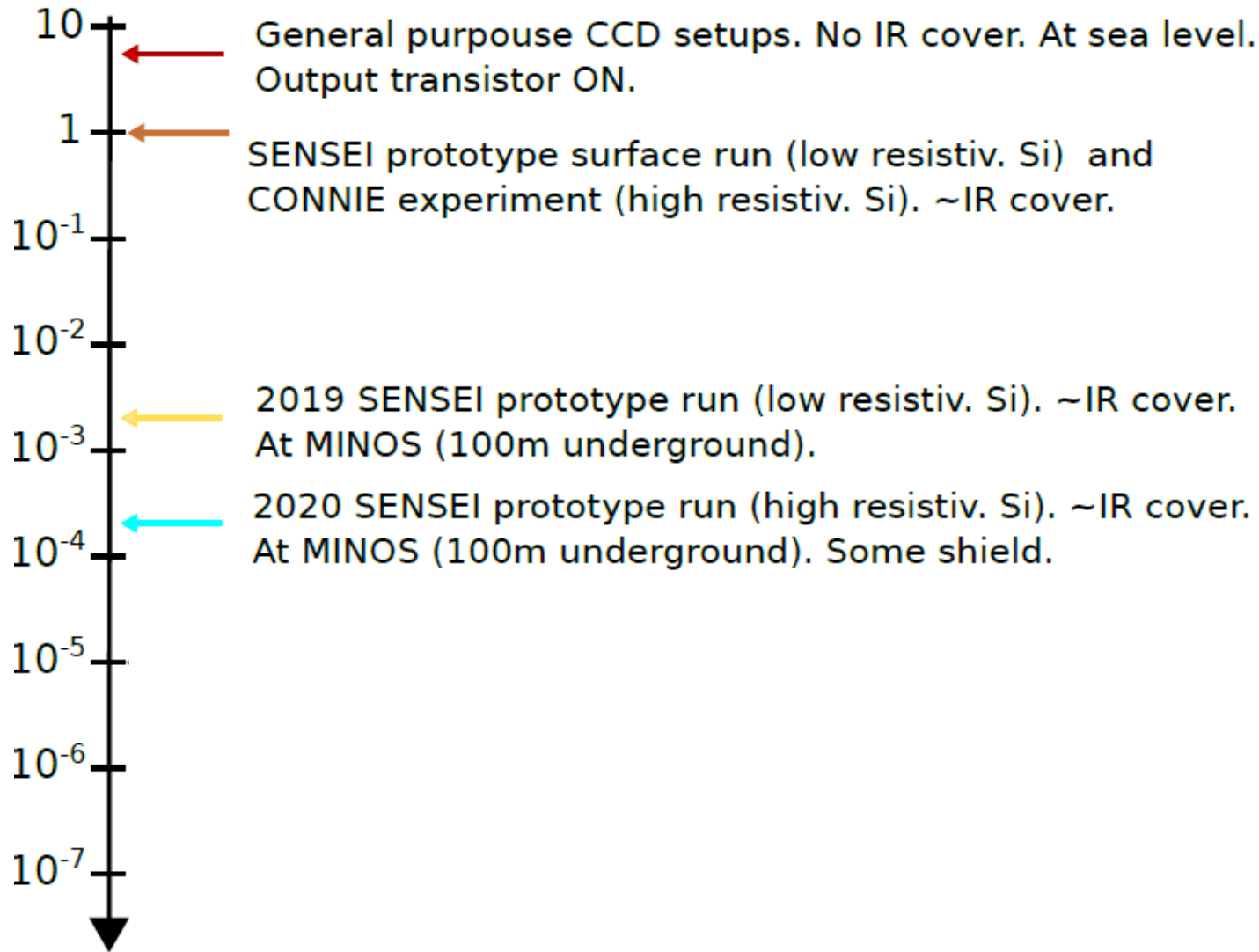
Peizhi Du¹, Daniel Egana-Ugrinovic,² Rouven Essig,¹ and Mukul Sholapurkar¹

¹*C. N. Yang Institute for Theoretical Physics, Stony Brook University, Stony Brook, New York 11794, USA*

²*Perimeter Institute for Theoretical Physics, Waterloo, Ontario N2L 2Y5, Canada*

“Dark Current” / SEE

Single-electron rate (e-/pix/day)



“Dark Current” / SEE

Single-electron rate (e-/pix/day)

PHYSICAL REVIEW LETTERS **125**, 171802 (2020)

Editors' Suggestion

Featured in Physics

SENSEI: Direct-Detection Results on sub-GeV Dark Matter from a New Skipper CCD

Liron Barak,¹ Itay M. Bloch,¹ Mariano Cababie,^{2,3} Gustavo Canelo,³ Luke Chaplinsky,^{4,5} Fernando Chierchie,³ Michael Crisler,⁶ Alex Drlica-Wagner,^{6,7,8} Rouven Essig,⁴ Juan Estrada,³ Erez Etzion,¹ Guillermo Fernandez Moroni,³ Daniel Gift,^{4,5} Sravan Munagavalasa,^{4,5} Aviv Orly,¹ Dario Rodrigues,^{2,3} Aman Singal,⁵ Miguel Sofo Haro,^{3,9} Leandro Stefanazzi,³ Javier Tiffenberg,³ Sho Uemura,¹ Tomer Volansky,¹ and Tien-Tien Yu¹⁰

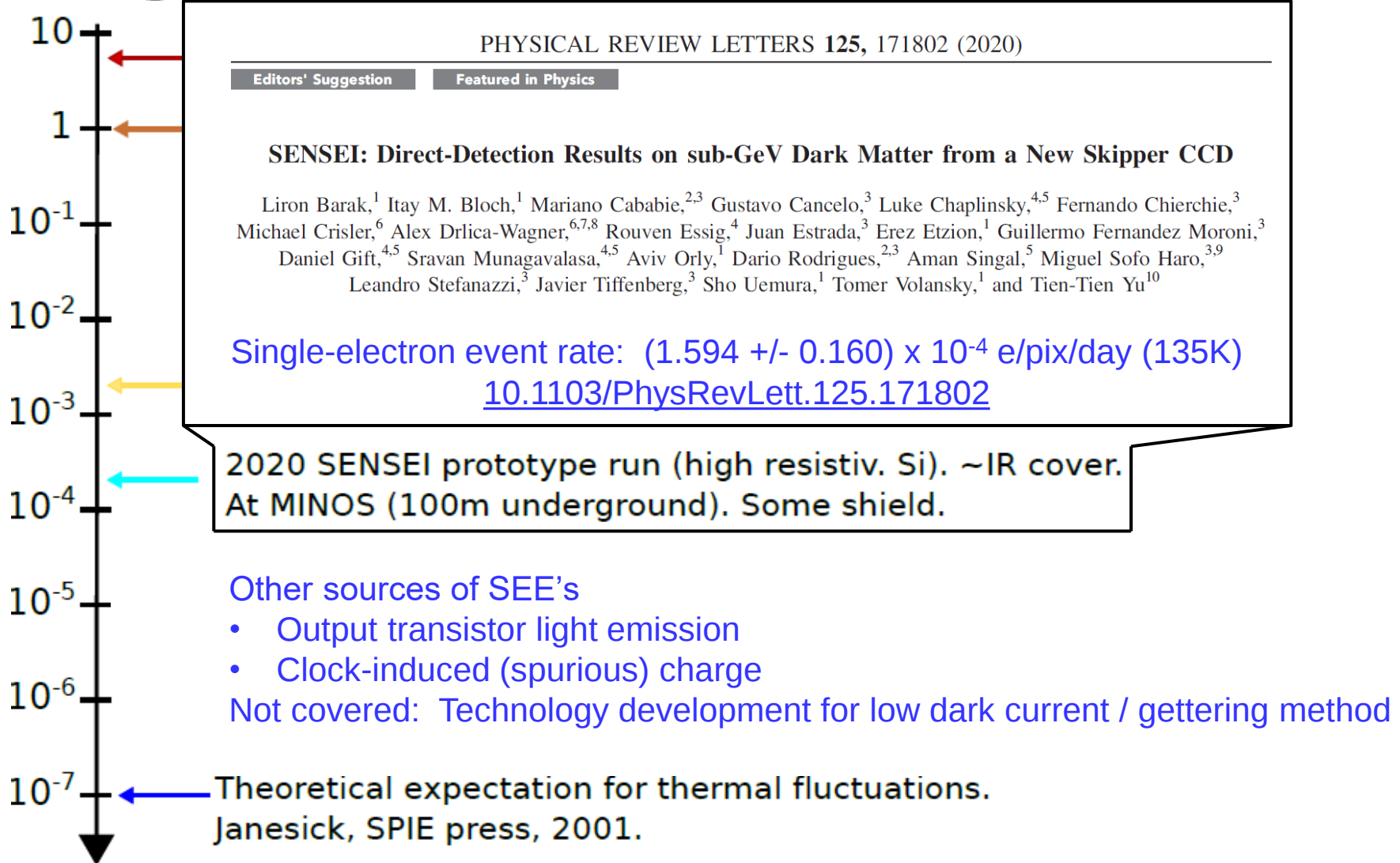
Single-electron event rate: $(1.594 \pm 0.160) \times 10^{-4}$ e/pix/day (135K)
[10.1103/PhysRevLett.125.171802](https://doi.org/10.1103/PhysRevLett.125.171802)

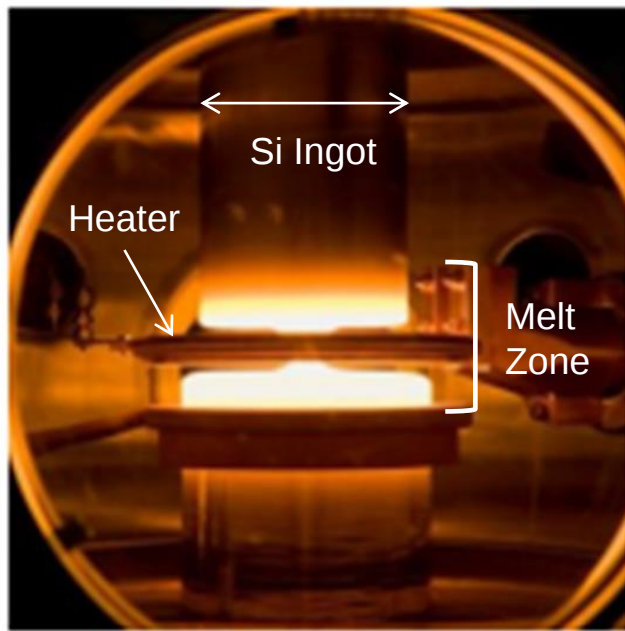
2020 SENSEI prototype run (high resistiv. Si). ~IR cover.
At MINOS (100m underground). Some shield.

Theoretical expectation for thermal fluctuations.
Janesick, SPIE press, 2001.

“Dark Current” / SEE

Single-electron rate (e-/pix/day)





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2020	32-1345-20	18.0 – 20.0	23.5
2020	34-1802-10	17.7 – 22.4	18.4

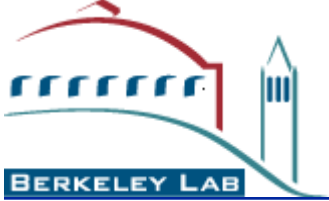
[Link to Topsil Float-Zone silicon](#)

Blue table entries are 150 mm $\varnothing$ diameter

Red are 200 mm $\varnothing$ diameter wafers

Bulk dark current $\sim x_D / \tau$ (x_D = Depletion depth)

Effective “gettering” method used to maintain low dark current
 LBNL/DALSA method is backside in-situ doped polysilicon



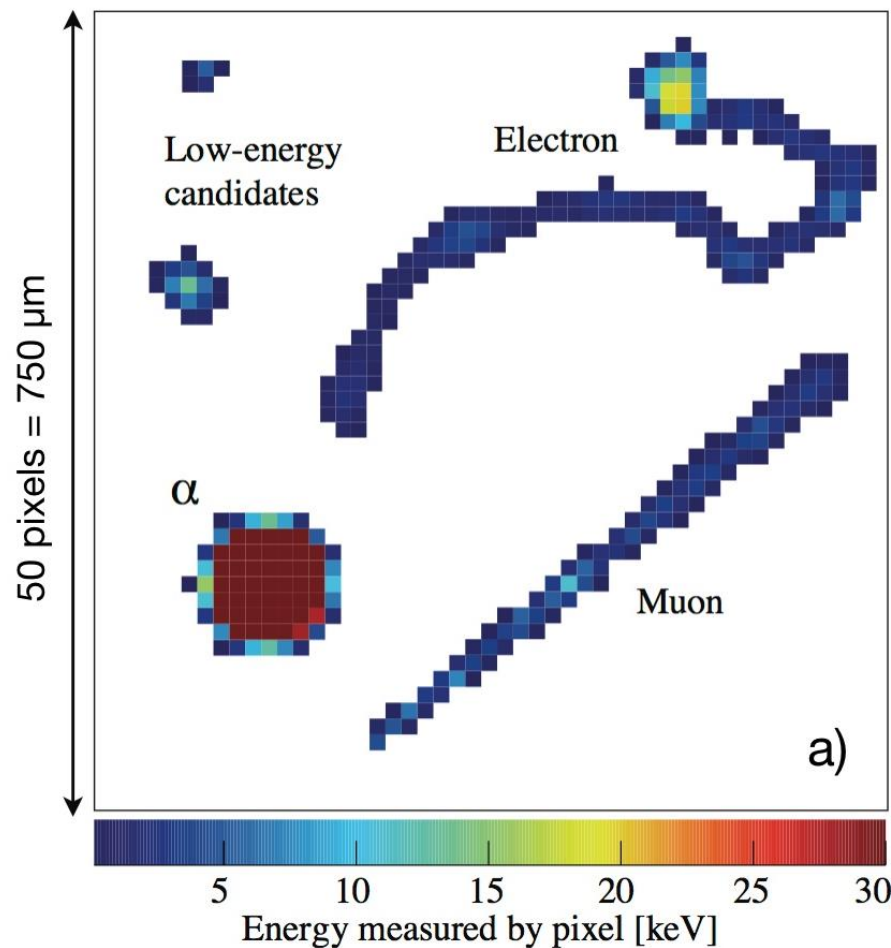
Dark Matter detection with CCDs

Fully depleted CCD advantages for dark matter detection

- Low noise / few e⁻ and deep sub electron (Skipper CCDs)
- Thick depleted regions / larger mass
- Background suppression / spatial and energy resolution
- Extremely low dark current for DM experiments
- Main disadvantage is the lack of timing information

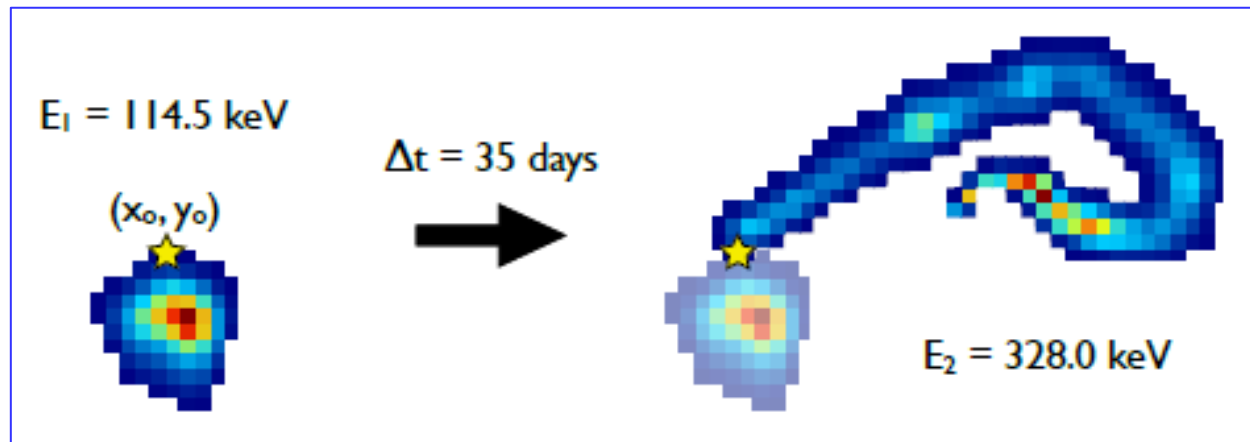
Dark Matter detection with CCDs

- Fully depleted CCDs for dark-matter detection cont'
 - Particle identification for background suppression
 - Spatial correlation and energy measurement



Dark Matter detection with CCDs

- Fully depleted CCDs for dark-matter detection cont'
 - Radioactive contamination in the silicon substrate
 - Decay chain products spatially correlated (double β event below)



*J*inst

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Measurement of radioactive contamination in the high-resistivity silicon CCDs of the DAMIC experiment

The DAMIC collaboration

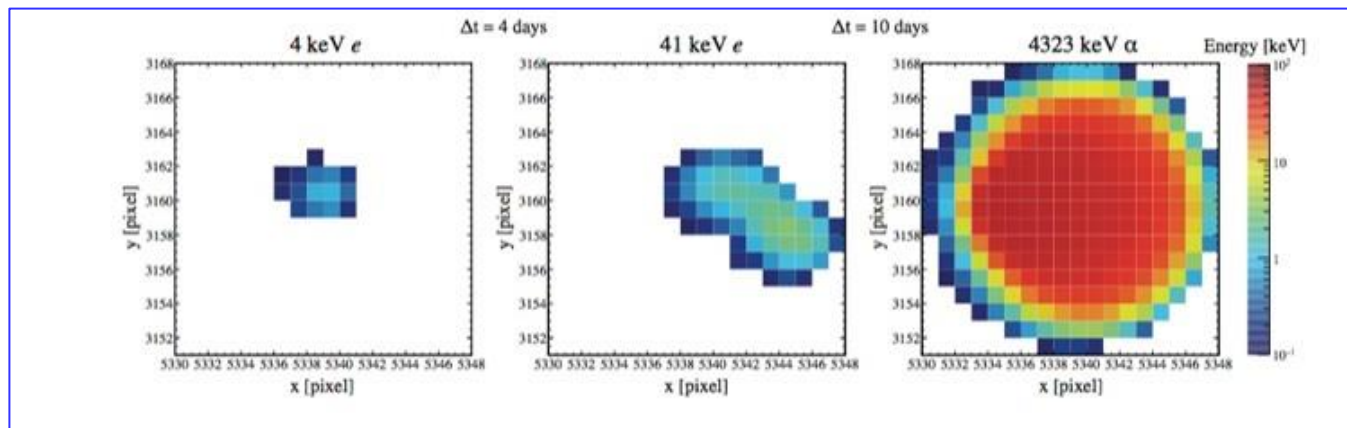
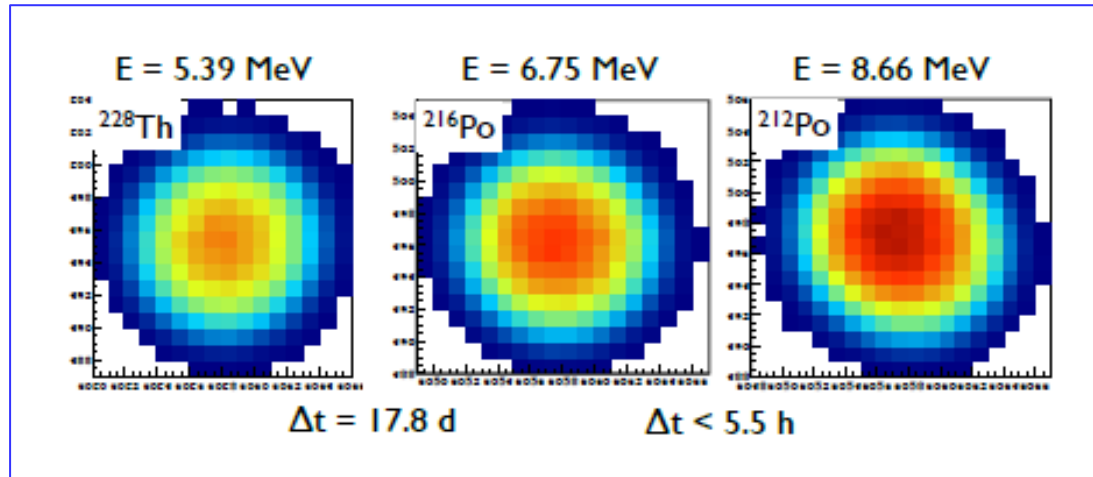
A. Aguilar-Arevalo,^a D. Amidei,^b X. Bertou,^c D. Bole,^b M. Butner,^{d,j} G. Canceled,^d A. Castañeda Vázquez,^a A.E. Chavarria,^{e,1} J.R.T. de Mello Neto,^f S. Dixon,^e J.C. D'Olivo,^a J. Estrada,^d G. Fernandez Moroni,^d K.P. Hernández Torres,^a F. Izraelevitch,^d A. Kavner,^b B. Kilminster,^e I. Lawson,^b J. Liao,^g M. López,ⁱ J. Molina,ⁱ G. Moreno-Granados,^a J. Pena,^e P. Privitera,^e Y. Sarkis,^e V. Scarpine,^d T. Schwarz,^b M. Sofo Haro,^c J. Tiffenberg,^d D. Torres Machado,^f F. Trillaud,^e X. You^f and J. Zhou^c

- Candidate $^{32}\text{Si} - ^{32}\text{P}$ event
- Cosmogenic activation of silicon
- Rejected by spatial / energy / decay time correlation

[10.1088/1748-0221/10/08/P08014](https://doi.org/10.1088/1748-0221/10/08/P08014)

Dark Matter detection with CCDs

- Fully depleted CCDs for dark-matter detection cont'



- Large-format CCD development with 16 x 4 amplifiers
 - U Chicago lead institution
- Challenge: Large format CCDs on 200-mm wafers
 - Stitching with wafer-stepper lithography
 - Requires new backside n+ technology
- Possible new application
 - Imaging of biological tissue

In the brain, hemoglobin absorbs blue and green light strongly, but not red or NIR light (this is why blood appears red to our eye). At the other end, for wavelengths beyond 1 μm , water becomes the dominant absorber. Within this “optical window” (650–1,200 nm), where the light used for two-photon excitation falls, the major source of its attenuation in brain tissue is not absorption, but scattering.

The Practical and Fundamental Limits of Optical Imaging in Mammalian Brains

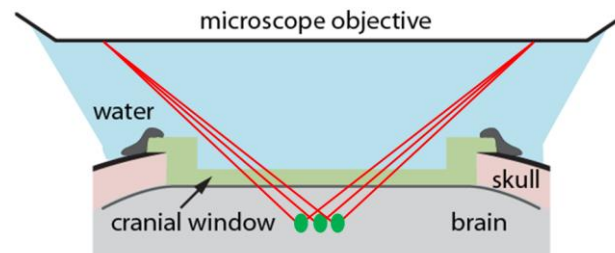
UC-Berkeley Physics

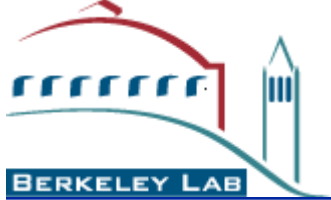
Na Ji^{1,*}

¹Howard Hughes Medical Institute, Janelia Farm Research Campus, Ashburn, Virginia 20148, USA

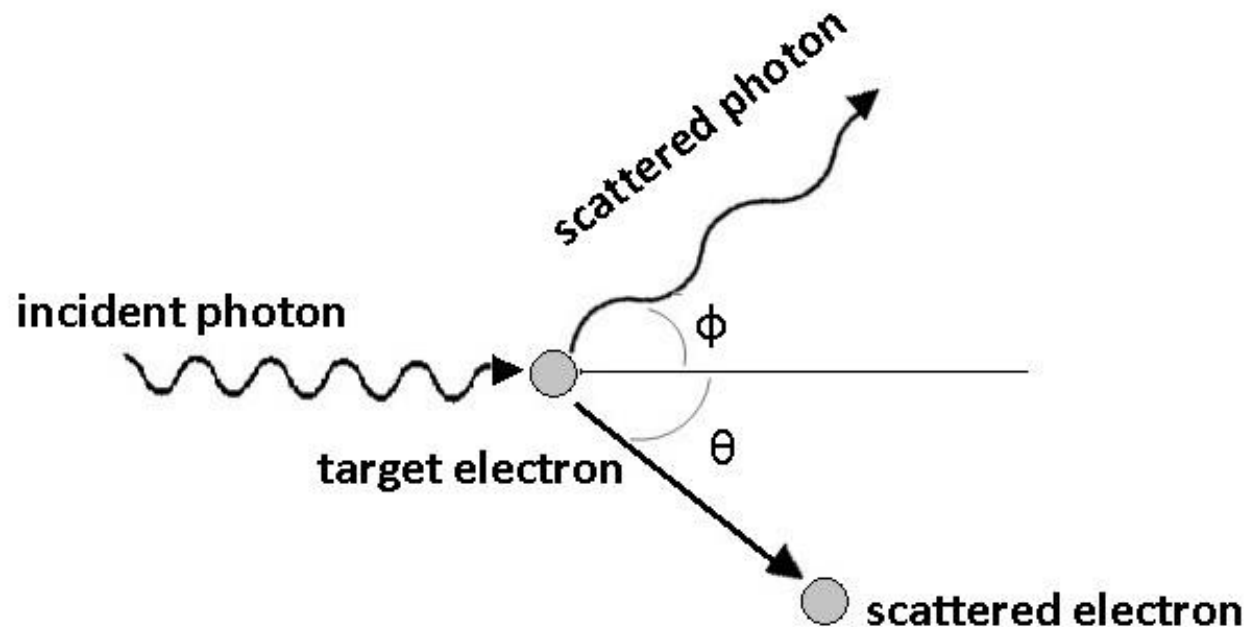
*Correspondence: jn@janelia.hhmi.org

<http://dx.doi.org/10.1016/j.neuron.2014.08.009>

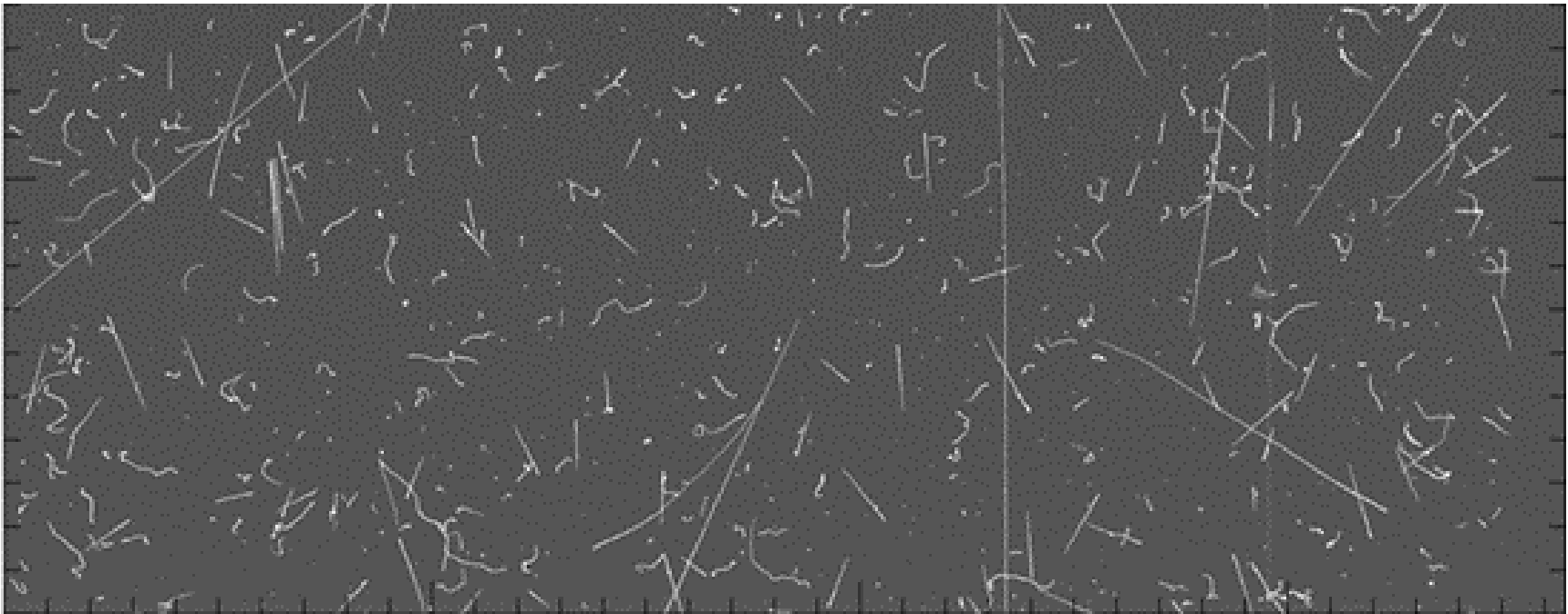




- Fundamental Si studies with Skipper CCDs
 - Silicon response to low-energy particles is needed for DM studies
 - Compton effect / low-energy Compton electrons generated in the bulk of the silicon can mimic dark-matter particles



- Fundamental Si studies with Skipper CCDs
 - 650 um thick LBNL CCD sub-image / 30 minute dark at -150C
 - Sea-level (LBNL CCD lab)
 - Highly curved tracks are (mostly) Compton electrons
 - Low-energy, point-like events are problematic for DM detection



- Don Groom (retired LBNL) terminology: Worms and spots

- Fundamental Si studies with Skipper CCD

PRECISION MEASUREMENT OF COMPTON SCATTERING IN ...

PHYS. REV. D **106**, 092001 (2022)

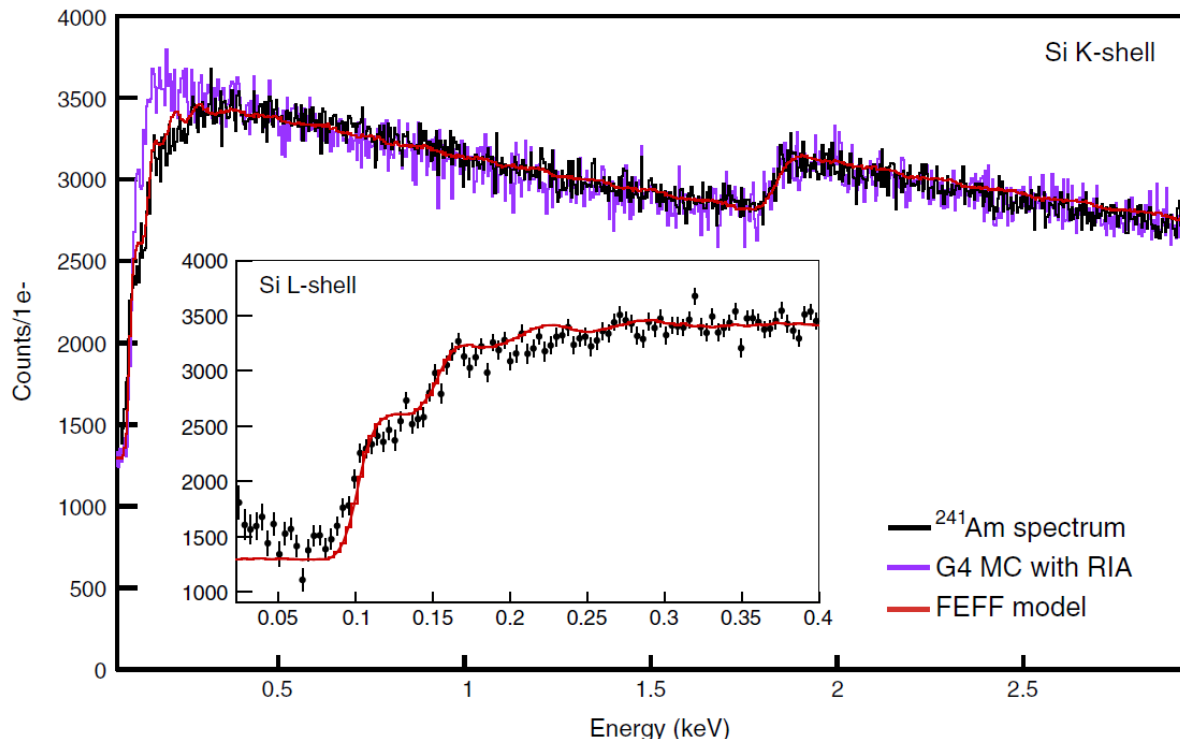


FIG. 10. The measured ^{241}Am Compton spectrum (black) from the 23 eV detection threshold to 2.1 keV. The K-step is observed at 1.8 keV. The GEANT4 simulated spectrum (purple) that is based on the relativistic impulse approximation is also shown. In red is the *ab initio* calculation from the FEFF code, with detector response taken into account. The inset shows the data comparison to the FEFF prediction in the L-shell energy range.

- e- counting to 550 e-
- Exposure in days
 - 106 with ^{241}Am
 - 224k images
 - 48 no source
 - 103k images
- 23 eV lower limit

[10.1103/PhysRevD.106.092001](https://arxiv.org/abs/10.1103/PhysRevD.106.092001)

DAMIC-M

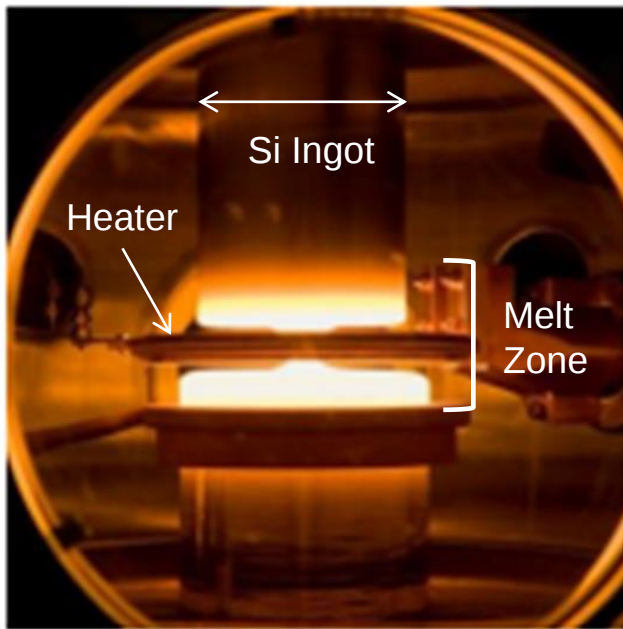
Abstract

The Oscura experiment will lead the search for low-mass dark matter particles using a very large array of novel silicon Charge Coupled Devices (CCDs) with a threshold of two electrons and with a total exposure of 30 kg-yr. The R&D effort, which began in FY20, is currently entering the design phase with the goal of being ready to start construction in late 2024. Oscura will have unprecedented sensitivity to sub-GeV dark matter particles that interact with electrons, probing dark matter-electron scattering for masses down to ~ 500 keV and dark matter being absorbed by electrons for masses down to ~ 1 eV. The Oscura R&D effort has made some significant progress on the main technical challenges of the experiment, of which the most significant are engaging new foundries for the fabrication of the CCD sensors, developing a cold readout solution, and understanding the experimental backgrounds.

- (i) The small silicon band gap allows us to probe DM masses an order of magnitude lower in mass (for both scattering and absorption) than noble-liquid targets, which have an ionization energy of $\mathcal{O}(10$ eV).
- (ii) Due to the small silicon band gap, the electron recoil-energy needed to promote additional electrons from the valence to the conduction band is lower in silicon (~ 3.8 eV) than in many other target materials, so that DM-electron scattering events will often contain two or more electrons.
- (iii) The small mass of the silicon nucleus ensures that solar neutrinos that scatter coherently off nuclei are not a limiting background for the proposed experiment with a 30 kg-year exposure [51].
- (iv) The skipper-CCD technology has already been demonstrated and provides an unprecedented charge resolution, extremely low leakage currents, exquisite spatial resolution and three-dimensional reconstruction, and background identification and rejection capabilities. Indeed, the strongest constraints on low-mass DM scattering off electrons and absorption by electrons (down to ~ 500 keV and ~ 1 eV, respectively) are currently obtained with skipper-CCDs [16].
- (v) Rapid progress is being made in understanding the origin and the mitigation strategies of single- and few-electron backgrounds [52–55].

The Oscura Experiment

Enabling technology: Float-zone silicon



Year Acquired	Topsil Crystal #	Resistivity ρ (k Ω -cm)	Lifetime τ (ms)
2009	2142946	5.5 - 7	4.4
2009	2143310	5.0 - 6.0	16.3
2009	2144322	14.0 - 20.0	3.4
2014	22-0572-10	20.0 - 28.0	7.3
2015	33-0203-20	22.0 - 26.0	21.4
2019	31-1062-10	> 10.0	22.4
2020	33-1751-30	> 10.0	18.9

[Link to Topsil Float-Zone silicon](#)

- Float-zone refining: Favorable impurity segregation into the liquid phase, and localized melting with repeated passes results in extremely pure silicon
- 10 k Ω -cm n-type doping level is $\sim 4 \times 10^{11} \text{ cm}^{-3}$, or a purity level of about 1 part in 10^{11}
- The depletion voltage $\sim x_{\text{Depl}}^2/\rho$, and bulk dark current $\sim x_{\text{Depl}}/\tau$ (x_{Depl} = Depletion depth)
- Standard Czochralski silicon limited to a resistivity ρ of about 50 ohm-cm (O_2 donors)
 - Conventional CCDs and CMOS image sensors limited to depletion depths of a few to $\sim 20 \text{ um}$

- One final topic related to Skipper CCDs
 - Dark current
- We use gettering methods during the CCD fabrication to maintain low dark current
 - Backside in-situ doped (P) polysilicon (ISDP)

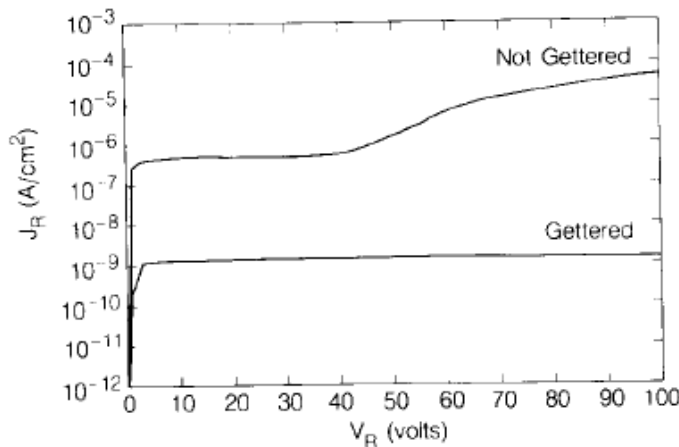


Fig. 2. The detector diode reverse-leakage current for a device with backside gettering compared to one without. The devices were fabricated on $10\text{ k}\Omega\text{ cm}$ $\langle 100 \rangle$ substrates, and both devices are from the same wafer.

Nuclear Instruments and Methods in Physics Research A275 (1989) 537–541
North-Holland, Amsterdam

537

FABRICATION OF DETECTORS AND TRANSISTORS ON HIGH-RESISTIVITY SILICON

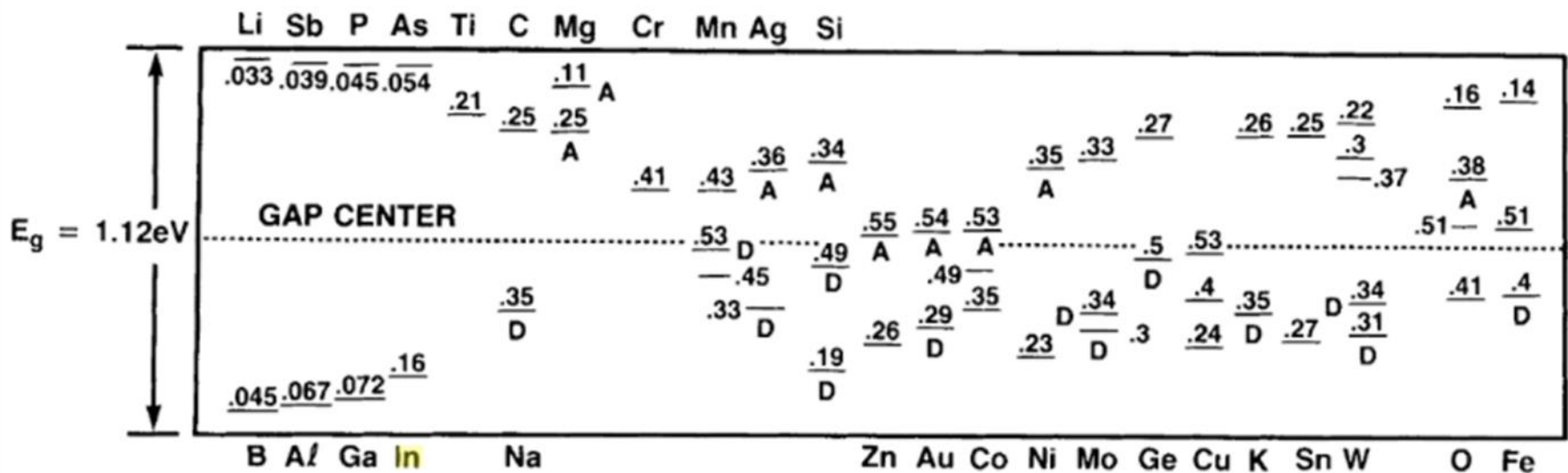
Steve HOLLAND

Lawrence Berkeley Laboratory, University of California, Berkeley, CA 94720, USA

Especially important for
thick, fully depleted devices

Dark Current

- Dark current from the substrate is determined by extremely low levels of unwanted impurities (metals) that have energy states near the bandgap center



The Gettering Process for High- ρ silicon

- A significant and collaborative effort was needed to optimize the “gettering” process to achieve low dark current

- Backside layer traps “lifetime killing” impurities (metals)
- Looks simple, but a high yield, robust process was not trivial to realize
- Close collaboration and willingness on Mitel / DALSA’s part was critical
- <https://www.sciencedirect.com/science/article/pii/S0168900289907419>

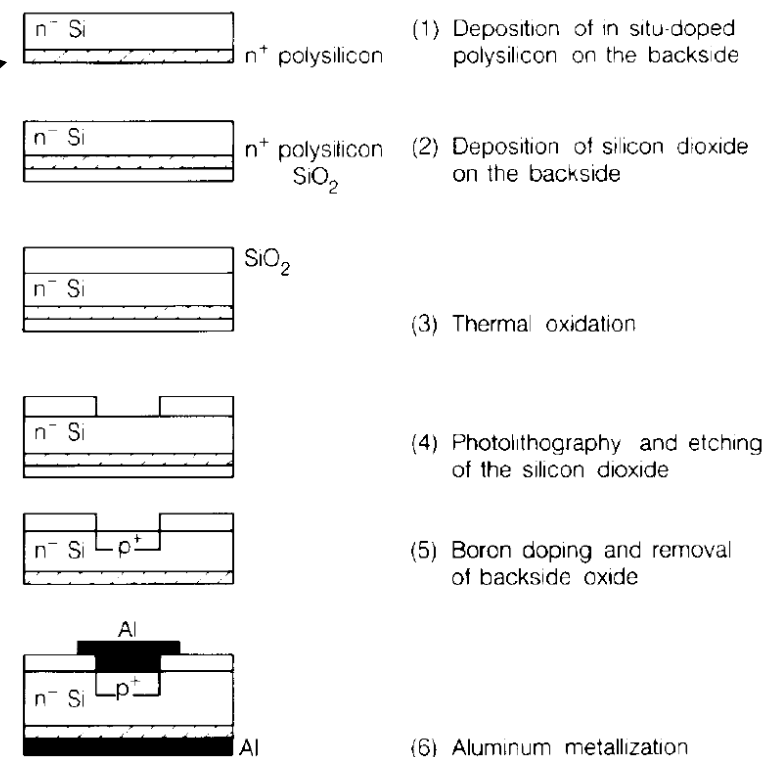


Fig. 1. The fabrication process used in this work.

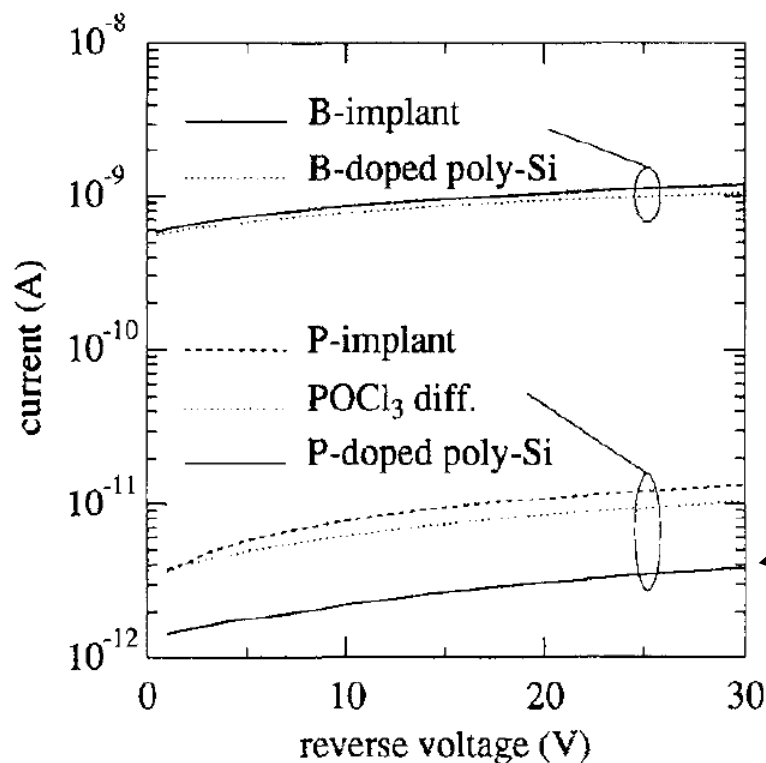
FABRICATION OF DETECTORS AND TRANSISTORS ON HIGH-RESISTIVITY SILICON

Steve HOLLAND

Lawrence Berkeley Laboratory, University of California, Berkeley, CA 94720, USA

The Gettering Process for High- ρ silicon

- Dark current for high- ρ silicon pin diodes



- Comparison study of various gettering methods (1997)

- <https://www.sciencedirect.com/science/article/pii/S0168900297006128>

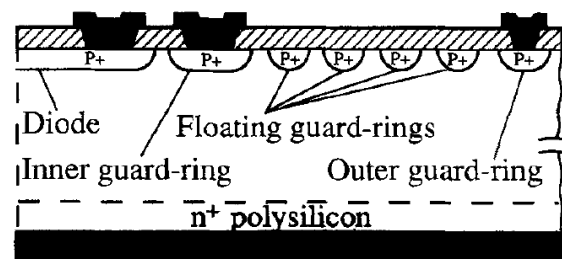


Fig. 2. Schematic cross-section (half device) of a PIN detector on n-type substrate.



Nuclear Instruments and Methods in Physics Research A 395 (1997) 344–348

**NUCLEAR
INSTRUMENTS
& METHODS
IN PHYSICS
RESEARCH**
Section A

Si-PIN X-ray detector technology

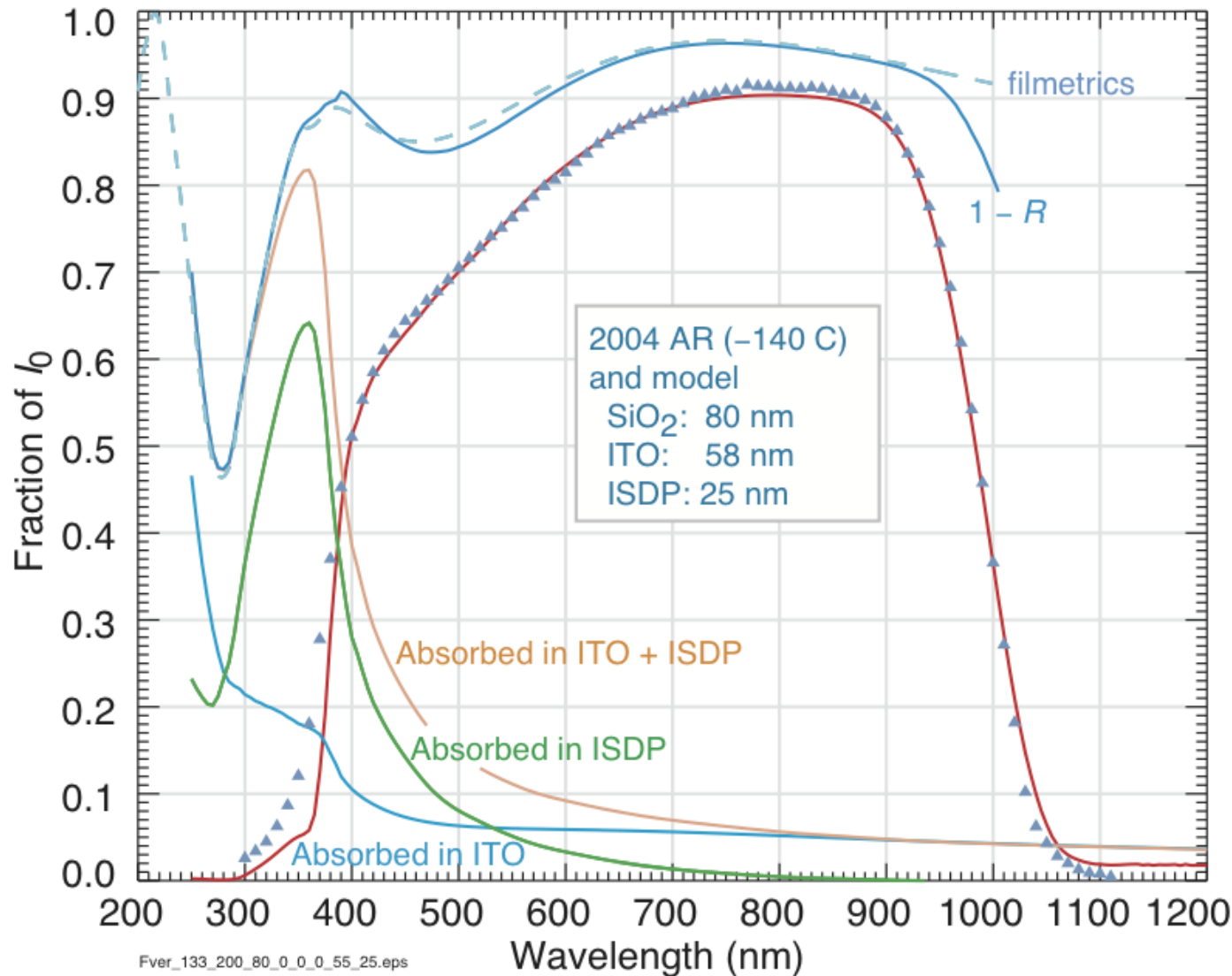
G.F. Dalla Betta^a, G.U. Pignatelli^{a,*}, G. Verzellesi^a, M. Boscardin^b

^aDipartimento di Ingegneria dei Materiali, Università di Trento, I-38050 Mesiano (TN), Italy

^bIRST-Microelectronics, 38050 Povo (TN), Italy

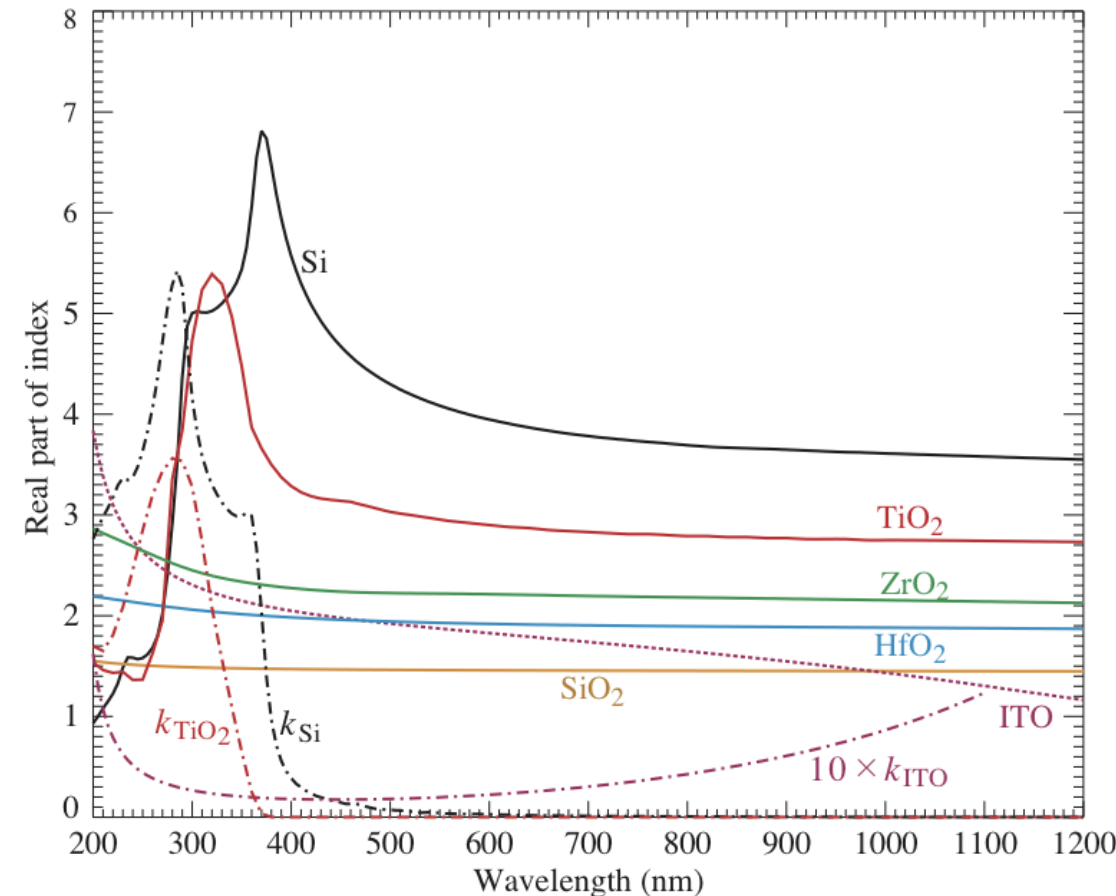
Quantum Efficiency

- QE results DECam ITO SiO₂ AR coating



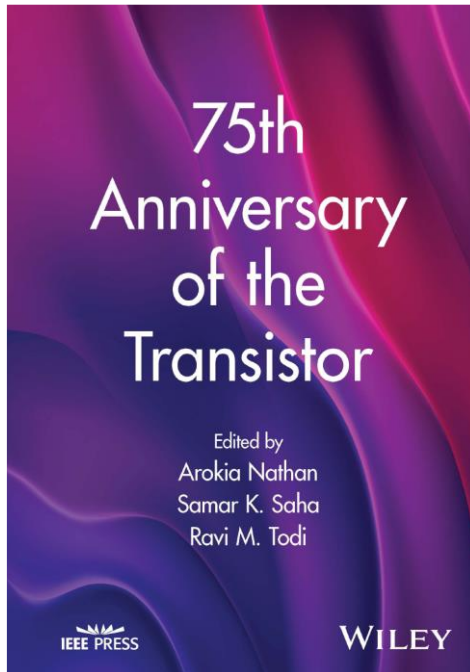
Quantum Efficiency

- New anti-reflection coating material used in the DESI CCDs to address ITO performance



- ITO index decreasing with λ
- Looks like single AR coating at long λ when used with $SiO_2^\dagger$
- Replace most of the ITO with ZrO_2

[†] Pointed out originally by Don Groom



Chapter 22

Imaging Inventions

Charge-Coupled Devices

Michael F. Tompsett



Chapter 23

The Invention and Development of CMOS Image Sensors

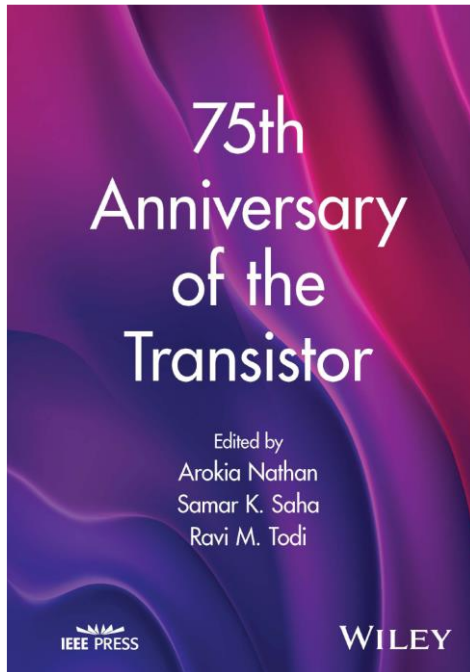
A Camera in Every Pocket

Eric R. Fossum

Thayer School of Engineering, Dartmouth College, Hanover, NH, USA



The invention of CCD imagers was actually preceded by work on a thin-film-transistor array in 1963 by Paul Weimer at RCA Labs, and simultaneous proposals for x - y addressed MOS imagers in 1967 by Peter Noble at Plessey in England and Gene Weckler at Fairchild in California. However MOS technology was too primitive at the time and 25 years of MOS technology development were required before these proposals were picked up again by Eric Fossum and yielded viable devices. Today's CMOS imagers are made with incredible quality and yield and have replaced CCD imagers for other than space and astronomical work.



Chapter 22

Imaging Inventions

Charge-Coupled Devices

Michael F. Tompsett



Chapter 23

The Invention and Development of CMOS Image Sensors

A Camera in Every Pocket

Eric R. Fossum

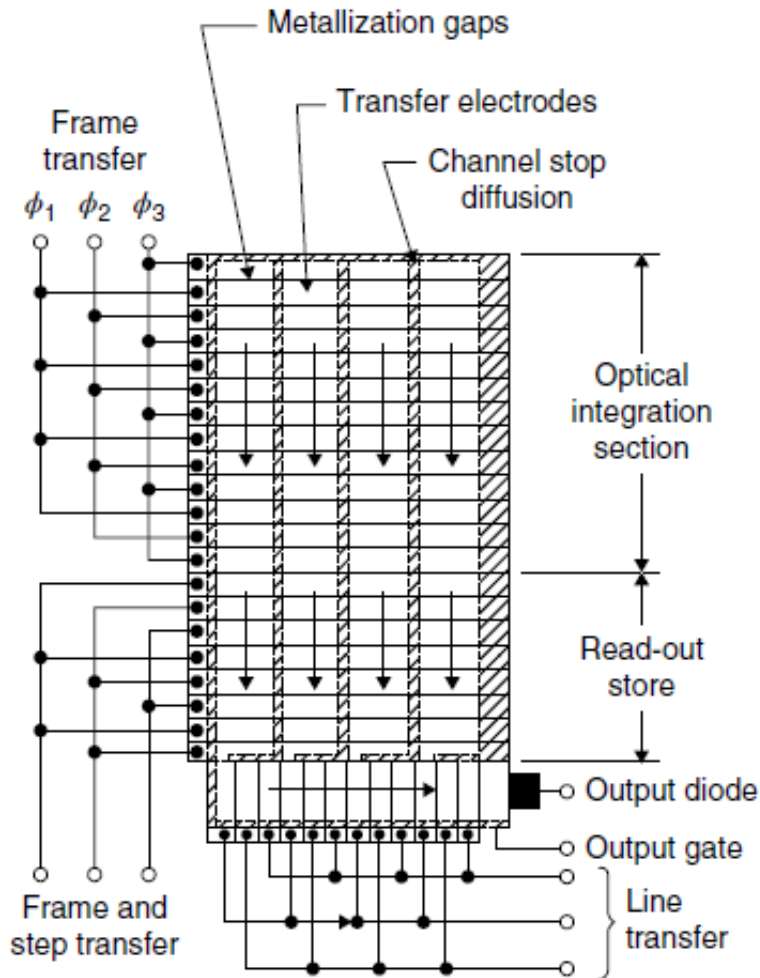
Thayer School of Engineering, Dartmouth College, Hanover, NH, USA



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, dark matter and fundamental radiation detection.

75th Anniversary of the Transistor



Chapter 22

Imaging Inventions Charge-Coupled Devices

Michael F. Tompsett



Figure 22.3 Readout principle of “Frame-Transfer” CCD imaging array.

High-voltage compatible CCDs

- Spatial resolution in fully depleted CCDs goes as $\sim 1/(V_{\text{sub}})^{-1/2}$
 - Carrier transit time (holes)

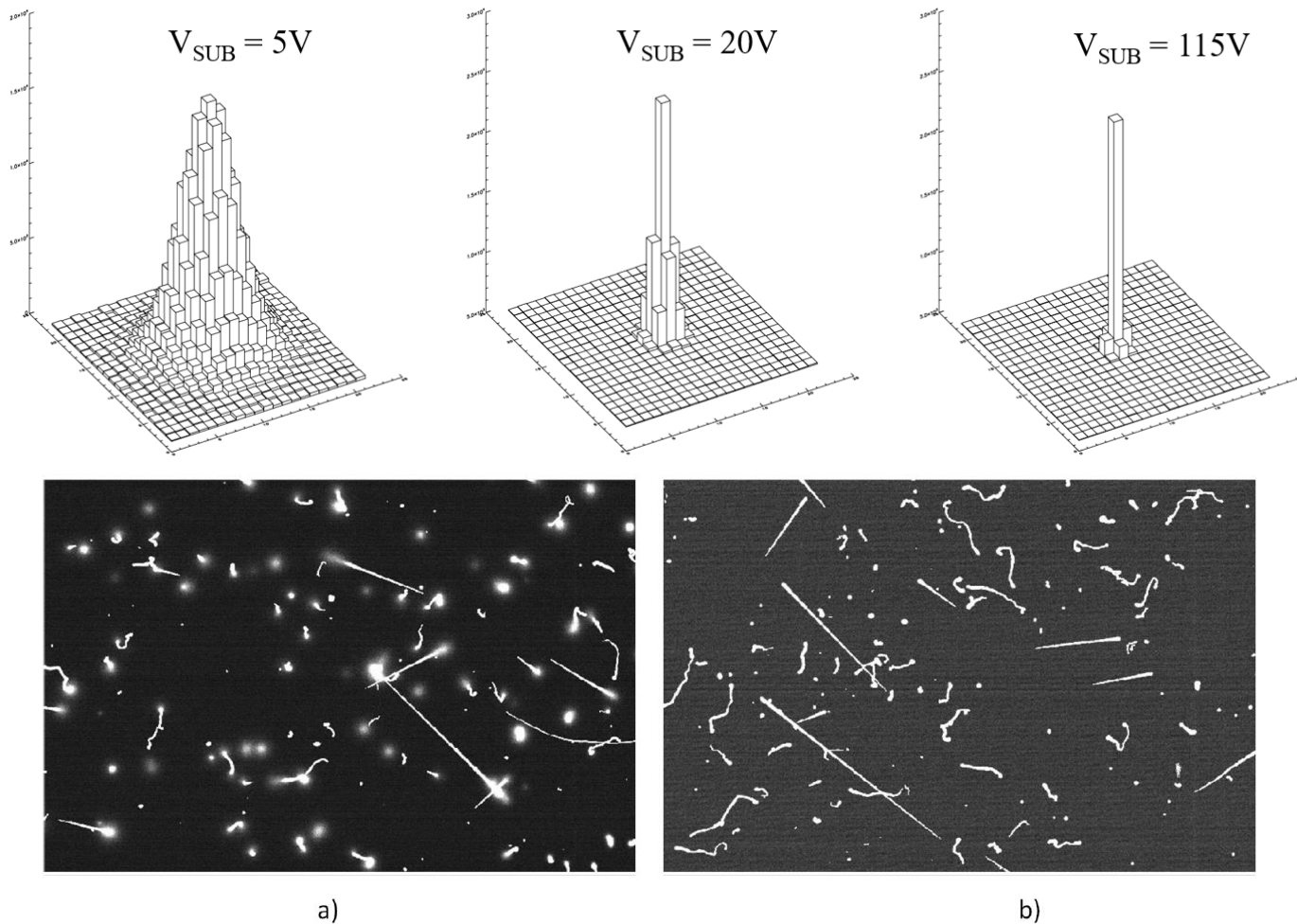


Figure 4. Sub-images of 30 minute dark exposures taken at -140°C on a $500\text{ }\mu\text{m}$ -thick, $4\text{k} \times 2\text{k}$, $(15\text{ }\mu\text{m})^2$ -pixel CCD fabricated on $\sim 20,000\text{ }\Omega\text{-cm}$ silicon. The size of the sub-image is approximately 650 rows by 770 columns. a) $V_{\text{sub}} = 30\text{V}$ b) $V_{\text{sub}} = 60\text{V}$.